



Service Manual

G5400



Model : G5400



Table Of Contents

1. INTRODUCTION	5	3.16 Headset Jack Interface	30
1.1 Purpose	5	3.17 Key Back-light Illumination	31
1.2 Regulatory Information	5	3.18 LCD Back-light Illumination	31
A. Security	5	3.19 Speaker & MIDI IC	32
B. Incidence of Harm	5		
C. Changes in Service	5	4. TROUBLE SHOOTING	33
D. Maintenance Limitations	5	4.1 RF Components	33
E. Notice of Radiated Emissions	6	4.2 RX Trouble	34
F. Pictures	6	4.2.1 Checking Regulator Circuit	35
G. Interference and Attenuation	6	4.2.2 Checking VCTCXO Circuit	36
H. Electrostatic Sensitive Devices	6	4.2.3 Checking PLL Control Signal	37
1.3 Abbreviations	7	4.2.4 Checking Ant SW & Mobile SW..	38
		4.2.5 Checking SAW Filter Circuit	39
2. PERFORMANCE	8	4.2.6 Checking RX IQ	40
2.1 H/W Feature	8	4.3 Tx Trouble	41
2.2 Technical Specification	9	4.3.1 Checking Regulator Circuit	42
		4.3.2 Checking VCTCXO Circuit	43
3. TECHNICAL BRIEF	13	4.3.3 Checking PLL Control Signal	44
3.1 General Description	13	4.3.4 Checking Ant SW & Mobile SW..	45
3.2 Receiver Part	13	4.3.5 Checking SAW Filter Circuit	46
A. RF front end	13	4.3.6 Checking TX IQ	47
B. IF	13	4.3.7 Receiver and Transmitter	
C. Demodulator and base processing ..	14	RF Level	48
3.3 Synthesizer Part	14	4.4 Power On Trouble	49
3.4 Transmitter Part	15	4.5 Charging Trouble	51
A. IF Modulator	16	4.6 LCD Trouble	53
B. OPLL	16	4.7 Receiver Trouble	55
C. Power Amplifier	16	4.8 Speaker Trouble	57
3.5 13MHz Clock	17	4.9 MIC Trouble	59
3.6 Power Supplies and Control Signals ...	17	4.10 Vibrator Trouble	61
3.7 Digital Main Processor	18	4.11 Key Backlight LED Trouble	63
3.8 Analog Main Processor	21	4.12 Folder on/off Trouble	65
3.9 Power management IC	27	4.13 SIM Detect Trouble	67
3.10 Memories	27	4.14 Earphone Trouble	69
3.11 Display and Interface	27	4.15 HFK Trouble	73
3.12 Keypad Switches and Scanning	27		
3.13 Microphone	29	5. DISASSEMBLY	
3.14 Earpiece	30	INSTRUCTION	77
3.15 Hands-free Interface	30	5.1 Disassembly	77

6. DOWNLOAD AND CALIBRATION	84	D. Buzzer [3-4]	105
6.1 Download	84	E. Vibrator [3-5]	105
A. Download Setup	84	F. LCD [3-6]	105
B. Download Procedure	85	G. Keypad	105
6.2 Calibration	91	H. Sub LCD	105
A. Equipment List	91	10.4 Trace option [MENU 4]	106
B. Equipment Setup	91	10.5 Call Timer [MENU 5]	106
C. Test Jig Operation	92	A. All calls [5-1]	106
7. BLOCK DIAGRAM	94	B. Reset settings [5-2]	106
8. CIRCUIT DIAGRAM	95	10.6 Fact. Reset [MENU 6]	106
8.1 MAIN	95	10.7 S/W version [MENU 7]	106
8.2 AUDIO	96	11. STAND ALONE TEST	107
8.3 MIDI	97	11.1 Introduction	107
8.4 RF CIRCUIT	98	A. Tx Test	107
8.5 Keypad	99	B. Rx Test	107
8.6 SIM, IrDA, Battery	100	11.2 Setting Method	107
9. PCB LAYOUT	100	A. COM port	107
10. ENGINEERING MODE	103	B. Tx	107
A. About Engineering Mode	103	C. Rx	107
B. Access Codes	103	11.3 Means of Test	108
C. Key Operation	103	12. AUTO CALIBRATION	110
10.1 BB Test [MENU 1]	103	12.1 Overview	110
A. LCD [1-1]	103	12.2 Requirements	110
B. LCD [1-2]	103	12.3 Menu and settings	110
C. Backlight [1-3]	103	12.4 AGC	112
D. Buzzer [1-4]	103	12.5 APC	112
E. Vibrator [1-45]	103	12.6 ADC	112
F. ADC (Analog to Digital Converter) [1-6]	103	12.7 Setting	112
G. BATTERY [1-7]	103	12.8 How to do calibration	112
H. Audio [1-8]	103	13. EXPLODED VIEW & REPLACEMENT PART LIST	113
I. DAI (Digital Audio Interface) [1-9] ...	103	13.1 Exploded View	113
10.2 RF Test [MENU 2]	105	13.2 Accessories	117
A. SAR Test [2-1]	105	13.3 Replacement Part List	118
10.3 MF Mode [MENU 3]	105		
A. All auto test [3-1]	105		
B. LED [3-2]	105		
C. Backlight [3-3]	105		

1. INTRODUCTION

1.1 Purpose

This manual provides the information necessary to repair, calibration, description and download the features of this model.

1.2 Regulatory Information

A. Security

Toll fraud, the unauthorized use of telecommunications system by an unauthorized part (for example, persons other than your company's employees, agents, subcontractors, or person working on your company's behalf) can result in substantial additional charges for your telecommunications services. System users are responsible for the security of own system. There are may be risks of toll fraud associated with your telecommunications system. System users are responsible for programming and configuring the equipment to prevent unauthorized use. The manufacturer does not warrant that this product is immune from the above case but will prevent unauthorized use of common-carrier telecommunication service of facilities accessed through or connected to it. The manufacturer will not be responsible for any charges that result from such unauthorized use.

B. Incidence of Harm

If a telephone company determines that the equipment provided to customer is faulty and possibly causing harm or interruption in service to the telephone network, it should disconnect telephone service until repair can be done. A telephone company may temporarily disconnect service as long as repair is not done.

C. Changes in Service

A local telephone company may make changes in its communications facilities or procedure. If these changes could reasonably be expected to affect the use of the this phone or compatibility with the network, the telephone company is required to give advanced written notice to the user, allowing the user to take appropriate steps to maintain telephone service.

D. Maintenance Limitations

Maintenance limitations on this model must be performed only by the manufacturer or its authorized agent. The user may not make any changes and/or repairs except as specifically noted in this manual. Therefore, note that unauthorized alternations or repair may affect the regulatory status of the system and may void any remaining warranty.

E. Notice of Radiated Emissions

This model complies with rules regarding radiation and radio frequency emission as defined by local regulatory agencies. In accordance with these agencies, you may be required to provide information such as the following to the end user.

F. Pictures

The pictures in this manual are for illustrative purposes only; your actual hardware may look slightly different.

G. Interference and Attenuation

Phone may interfere with sensitive laboratory equipment, medical equipment, etc. Interference from unsuppressed engines or electric motors may cause problems.

H. Electrostatic Sensitive Devices

ATTENTION

Boards, which contain Electrostatic Sensitive Device (ESD), are indicated by the  sign. Following information is ESD handling:

- Service personnel should ground themselves by using a wrist strap when exchange system boards.
- When repairs are made to a system board, they should spread the floor with anti-static mat which is also grounded.
- Use a suitable, grounded soldering iron.
- Keep sensitive parts in these protective packages until these are used.
- When returning system boards or parts like EEPROM to the factory, use the protective package as described.

1.3 Abbreviations

For the purposes of this manual, following abbreviations apply:

APC	Automatic Power Control
BB	Baseband
BER	Bit Error Ratio
CC-CV	Constant Current – Constant Voltage
DAC	Digital to Analog Converter
DCS	Digital Communication System
dBm	dB relative to 1 milliwatt
DSP	Digital Signal Processing
EEPROM	Electrical Erasable Programmable Read-Only Memory
ESD	Electrostatic Discharge
FPCB	Flexible Printed Circuit Board
GMSK	Gaussian Minimum Shift Keying
GPB	General Purpose Interface Bus
GSM	Global System for Mobile Communications
IPUI	International Portable User Identity
IF	Intermediate Frequency
LCD	Liquid Crystal Display
LDO	Low Drop Output
LED	Light Emitting Diode
OPLL	Offset Phase Locked Loop
PAM	Power Amplifier Module
PCB	Printed Circuit Board
PGA	Programmable Gain Amplifier
PLL	Phase Locked Loop
PSTN	Public Switched Telephone Network
RF	Radio Frequency
RLR	Receiving Loudness Rating
RMS	Root Mean Square
RTC	Real Time Clock
SAW	Surface Acoustic Wave
SIM	Subscriber Identity Module
SLR	Sending Loudness Rating
SRAM	Static Random Access Memory
PSRAM	Pseudo SRAM
STMR	Side Tone Masking Rating
TA	Travel Adapter
TDD	Time Division Duplex
TDMA	Time Division Multiple Access
UART	Universal Asynchronous Receiver/Transmitter
VCO	Voltage Controlled Oscillator
VCTCXO	Voltage Control Temperature Compensated Crystal Oscillator
WAP	Wireless Application Protocol

2. PERFORMANCE

2.1 H/W Features

Item	Feature	Comment
Standard Battery	Li-ion, 740 mAh Size: 34 × 50 × 4.5mm Weight: 17.2g	
Stand by Current	Under the minimum current consumption environment (such as paging period 9), the level of standby current is below 4mA.	
Talk time	Up to 3 hours (GSM TX Level 7)	
Stand by time	Up to 200 hours (Paging Period: 9, RSSI: -85 dBm)	
Charging time	2.3 hours	
RX Sensitivity	GSM, EGSM: -105dBm, DCS: -105dBm	
TX output power	GSM, EGSM: 32 dBm (Level 5) DCS: 29dBm (Level 0)	
GPRS compatibility	Class 10	
SIM card type	3V Small	
Display	128 × 128 pixel 65K Color LCD	
Status Indicator & keypad	Hard icons Key Pad: 0 ~ 9, #, *, Up/Down Navigation Key Confirm Key, Clear Key Send Key, END/PWR Key	
ANT	external	
EAR Phone Jack	Yes	
PC Synchronization	Yes	
Speech coding	EFR/FR/HR	
Data and Fax	Yes	
Vibrator	Yes	
Loud Speaker	Yes	
Voice Recording	Yes	
C-Mike	Yes	
Receiver	Yes	
Travel Adapter	Yes	
Options	Hands-free kit, CLA, Data Kit	

2.2 Technical Specification

Item	Description	Specification					
1	Frequency Band	GSM <ul style="list-style-type: none">• TX: $890 + n \times 0.2$ MHz• RX: $935 + n \times 0.2$ MHz ($n = 1 \sim 124$) EGSM <ul style="list-style-type: none">• TX: $890 + (n - 1024) \times 0.2$ MHz• RX: $935 + (n - 1024) \times 0.2$ MHz ($n = 975 \sim 1024$) DCS <ul style="list-style-type: none">• TX: $1710 + (n - 512) \times 0.2$ MHz• Rx: $1805 + (n - 512) \times 0.2$ MHz ($n = 512 \sim 885$)					
2	Phase Error	RMS < 5 degrees Peak < 20 degrees					
3	Frequency Error	< 0.1 ppm					
4	Power Level	GSM, EGSM					
		Level	Power	Toler.	Level	Power	Toler.
		5	33 dBm	± 2dB	13	17 dBm	± 3dB
		6	31 dBm	± 3dB	14	15 dBm	± 3dB
		7	29 dBm	± 3dB	15	13 dBm	± 3dB
		8	27 dBm	± 3dB	16	11 dBm	± 5dB
		9	25 dBm	± 3dB	17	9 dBm	± 5dB
		10	23 dBm	± 3dB	18	7 dBm	± 5dB
		11	21 dBm	± 3dB	19	5 dBm	± 5dB
		12	19 dBm	± 3dB			
		DCS					
		Level	Power	Toler.	Level	Power	Toler.
		0	30 dBm	± 2dB	8	14 dBm	± 3dB
		1	28 dBm	± 3dB	9	12 dBm	± 4dB
		2	26 dBm	± 3dB	10	10 dBm	± 4dB
		3	24 dBm	± 3dB	11	8 dBm	± 4dB
		4	22 dBm	± 3dB	12	6 dBm	± 4dB
		5	20 dBm	± 3dB	13	4 dBm	± 4dB
		6	18 dBm	± 3dB	14	2 dBm	± 5dB
7	16 dBm	± 3dB	15	0 dBm	± 5dB		

2. PERFORMANCE

Item	Description	Specification	
5	Output RF Spectrum (due to modulation)	GSM, EGSM	
		Offset from Carrier (kHz).	Max. dBc
		100	+0.5
		200	-30
		250	-33
		400	-60
		600 ~ < 1,200	-60
		1,200 ~ < 1,800	-60
		1,800 ~ < 3,000	-63
		3,000 ~ < 6,000	-65
		6,000	-71
		DCS	
		Offset from Carrier (kHz).	Max. dBc
		100	+0.5
		200	-30
		250	-33
		400	-60
		600 ~ < 1,200	-60
		1,200 ~ < 1,800	-60
		1,800 ~ < 3,000	-65
		3,000 ~ < 6,000	-65
		6,000	-73
6	Output RF Spectrum (due to switching transient)	GSM, EGSM	
		Offset from Carrier (kHz)	Max. (dBm)
		400	-19
		600	-21
		1,200	-21
		1,800	-24
		GSM	
		Offset from Carrier (kHz)	Max. (dBm)
		400	-22
		600	-24
		1,200	-24
		1,800	-27
7	Spurious Emissions	Conduction, Emission Status	

Item	Description	Specification		
8	Bit Error Ratio	GSM, EGSM BER (Class II) < 2.439% @-102 dBm DCS BER (Class II) < 2.439% @-100 dBm		
9	RX Level Report Accuracy	± 3 dB		
10	SLR	8 ± 3 dB		
11	Sending Response	Frequency (Hz)	Max.(dB)	Min.(dB)
		100	-12	-
		200	0	-
		300	0	-12
		1,000	0	-6
		2,000	4	-6
		3,000	4	-6
		3,400	4	-9
		4,000	0	-
12	RLR	2 ± 3 dB		
13	Receiving Response	Frequency (Hz)	Max.(dB)	Min.(dB)
		100	-12	-
		200	0	-
		300	2	-7
		500	*	-5
		1,000	0	-5
		3,000	2	-5
		3,400	2	-10
		4,000	2	
		* Mean that Adopt a straight line in between 300 Hz and 1,000 Hz to be Max. level in the range.		
14	STMR	13 ± 5 dB		
15	Stability Margin	> 6 dB		
16	Distortion	dB to ARL (dB)		Level Ratio (dB)
		-35		17.5
		-30		22.5
		-20		30.7
		-10		33.3
		0		33.7
		7		31.7
		10		25.5
17	Side Tone Distortion	Three stage distortion < 10%		
18	System frequency (13 MHz) tolerance	≤ 2.5 ppm		

2. PERFORMANCE

Item	Description	Specification	
19	32.768KHz tolerance	≤ 30 ppm	
20	Ringer Volume	At least 80 dB under below conditions: 1. Ringer set as ringer. 2. Test distance set as 50 cm	
21	Charge Voltage	Fast Charge : < 500 mA Slow Charge: < 60 mA	
22	Antenna Display	Antenna Bar Number	Power
		5	-85 dBm ~
		4	-90 dBm ~ -86 dBm
		3	-95 dBm ~ -91 dBm
		2	-100 dBm ~ -96 dBm
		1	-105 dBm ~ -101 dBm
		0	~ -105 dBm
23	Battery Indicator	Battery Bar Number	Voltage
		0	~ 3.62 V
		1	3.62 ~ 3.73 V
		2	3.73 ~ 3.82 V
		3	3.82 V ~
24	Low Voltage Warning	3.5 \pm 0.03 V (Call)	
		3.62 \pm 0.03 V (Standby)	
25	Forced shut down Voltage	3.35 \pm 0.03 V	
26	Battery Type	1 Li-ion Battery Standard Voltage = 3.7 V Battery full charge voltage = 4.2 V Capacity: 740mAh-	
27	Travel Charger	Switching-mode charger Input: 100 ~ 240 V, 50/60 Hz Output: 5.2 V, 600 mA	

3. TECHNICAL BRIEF

3.1 General Description

The RF parts consist of a transmitter part, a receiver part, a frequency synthesizer part, a voltage supply part, and a VCTCXO part.

The Aero transceiver is composed of three RF chipsets, Si4200-BM[U401], Si4133T-BM[U403] and Si4201-BM[U402] which is dual and triple-band GSM/GPRS wireless communications.

This device integrated a receiver based on a low IF(100KHz) architecture and a transmitter based on a modulation loop architecture. And the synthesizer[U403] part employed the Silicon Labs Si4133T-BM, a complete dual band synthesizer with built in VCOs.

The transceiver employed a 3 wire serial interface to allow an external system controller to write the control registers for dividers, receive path gain, power down setting, and other controls.

3.2 Receiver Part

A. RF front end

RF front end consists of Antenna Switch(FL401), two SAW Filters(FL402, FL403) dual band LNAs integrated in transceiver(U401).

The Received RF signals(GSM 925MHz ~ 960MHz, DCS 1805MHz ~ 1880MHz) are fed into the antenna or Mobile switch. An antenna matching circuit is between the antenna and the mobile switch.

The Antenna Switch(FL401) is used to control the Rx and Tx paths. And, the input signals VC1 and VC2 of a FL401 are directly connected to baseband controller to switch either Tx or Rx path on.

Ant S/W module(FL401) is an antenna switch module for dual band phone.

The logic and current is given below table 3-1.

Table 3-1. The logic and current

	VC1	VC2	Current
GSM TX	0V	2.5 ~ 3.0V	10.0 mA max
DCS TX	2.5 ~ 3.0V	0V	10.0 mA max
GSM/DCS RX	0V	0V	< 0.1 mA

The receiver part uses a low-IF receiver architecture that allows for the on-chip integration of the channel selection filters, eliminating the external RF image reject filters and the IF SAW filter required in conventional super-heterodyne architecture. The Si4200-BM[U401] integrates three differential input LNAs that are matched to the 200 Ohm balanced-output SAW filters through external LC matching networks.

B. IF

A quadrature image-rejection mixer downconverts the RF signal to a 100kHz intermediate frequency(IF) with the RFLO from the Si4133T-BM[U403]. The RFLO frequency is between 1737.8 and 1989.8 MHz, and is divided by two in the Si4200 for GSM850 and E-GSM 900 modes. The mixer output is amplified with an analog programmable gain amplifier(PGA), which is controlled with the AGAIN[2:0] bits in register 05h.

The quadrature IF signal is digitized with high resolution A/D converters(ADCs).

The Si4201-BM[U402] downconverts the ADC output to baseband with a digital 100kHz quadrature LO signal. Digital decimation and IIR filters perform channel selection to remove blocking and

3. TECHNICAL BRIEF

reference interference signals.

The response of the IIR filter is programmable to a high selectivity setting(CSEL=0) or a low selectivity setting(CSEL=1). After channel selection, the digital output is scaled with digital PGA, which is controlled with the DGAIN[5:0] bits in register 05h.

C. Demodulator and base band processing

The amplified digital output signal go through with DACs that drive a differential analog signal onto the RXIP,RXIN,RXQP and RXQN pins to interface to standard analog ADC input baseband ICs. No special processing is required in the baseband for offset compensation or extended dynamic range.

Compared to a direct-conversion architecture, the low-IF architecture has a much greater degree of immunity to dc offsets that can arise from RF local oscillator(RFLO) self-mixing, 2nd order distortion of blockers, and device 1/f noise.

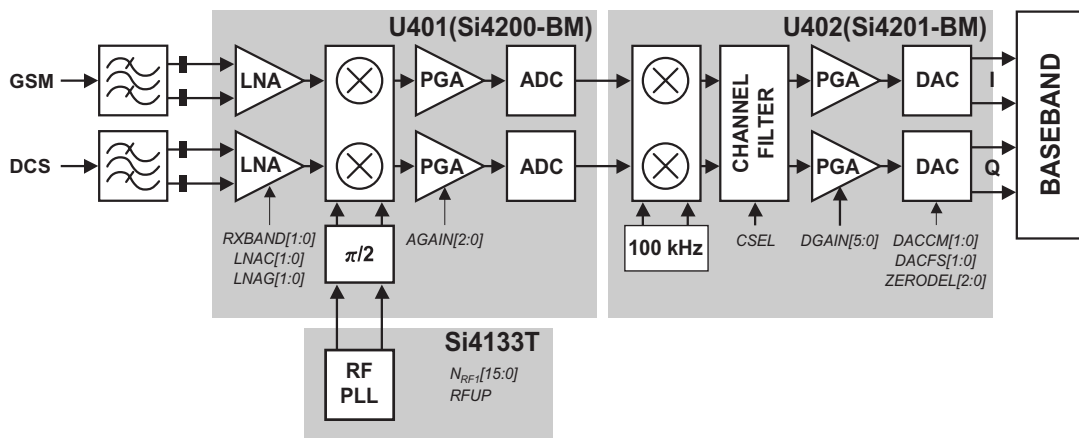


Figure 3-1. RF Receiver path Block diagram

3.3 Synthesizer Part

The synthesizer IC, the Si4133T-BM[U403] is a monolithic CMOS integrated circuit that performs IF and RF synthesis. Two complete PLLs are integrated including VCOs, varactors, resonators, loop filters, reference and VCO dividers, and phase detectors. Differential outputs for the IF and RF PLLs are provided for direct connection to the Si4200-BM[U401] transceiver IC. The RF PLL uses two multiplexed VCOs.

The RF1 VCO is used for Receive mode, and the RF2 VCO is used for Transmit mode.

The IF PLL is used only during Transmit mode and uses a single VCO.

The center frequency of each of the three VCOs on the Si4133T is set by connection of an external inductance(Lext). The IF and RF output frequencies are set by programming the N-Divider registers,N[RF1],N[RF2], and N[IF]. Programming the N-Divider register for either RF1 or RF2 automatically selects the proper VCO. The output frequency of each PLL is as follows:

$$f_{out} = N * f_{\phi}$$

A programmable divider at the XIN pin allows either a 13 or 26MHz from the external applied crystal oscillator.

The RF PLL phase detector update rate(f_{ϕ}) can be programmed with the RFUP bit in register 31h to either f_{ϕ} = 100kHz or f_{ϕ} = 200kHz. The IF PLL always uses f_{ϕ} = 200kHz.

Receive mode should use f_{ϕ} = 100kHz in DCS1800 and PCS1900 bands, and f_{ϕ} = 200kHz in the GSM850 and E-GSM 900 bands.

Transmit modes should always use f_{ϕ} = 200kHz. The IF and RF output frequencies are set by

A. IF Modulator

The baseband converter(BBC) within the GSM chipset generates I and Q baseband signals for the Transmit vector modulator. The modulator provides more than 40dBc of carrier and unwanted side-band Rejection and produces a GMSK modulated signal. The baseband software is able to cancel out differential DC offsets in the I/Q baseband signals caused by imperfections in the D/A converters.

The TX-Modulator implements a quadrature modulator. A quadrature mixer upconverts the differential I/Q signals with the IFLO to generate a SSB IF signal which is filtered and used as the reference input to the OPLL. The Si4133T [U403] generates the IFLO frequency. The IFLO is divided by two to generate The quadrature LO signals for the quadrature modulator.

B. OPLL

The OPLL consists of a feedback mixer, a phase detector, a loop filter, and a fully integrated TXVCO.

The TXVCO is centered between the DCS 1800 and PCS 1900 bands, and its output is divided by two for the GSM 850 and E-GSM 900 bands. The Si4133T generates the RFLO frequency between 1272 and 1483 MHz. To allow a single VCO to be used for the RFLO, high-side injection is used for the GSM 850 and E-GSM 900 bands, and low-side injection is used for the DCS 1800 and PCS 1900 bands.

Low-pass filters before the OPLL phase detector reduce the harmonic content of the quadrature modulator and feedback mixer outputs. The cutoff frequency of the filters is programmable with the FIF[3:0] bits in register 04h.

The OPLL requires no external duplexer to attenuate transmitter noise and spurious signals in the receive band. Additionally, the output of the transmit VCO (TXVCO) is a constant-envelope signal which reduces the problem of spectral spreading caused by non-linearity in the PA.

C. Power Amplifier

The RF3133 [U404] is a triple-band GSM/DCS/PCS power amplifier module that incorporates an indirect closed loop method of power control. The indirect closed loop is fully self contained and does not require loop optimization. It can be driven directly from the DAC output in the baseband circuit.

On-board power control provides over 37 dB of control range with an analog voltage input(Vramp). Its efficiency is 55% at GSM and 52% at DCS.

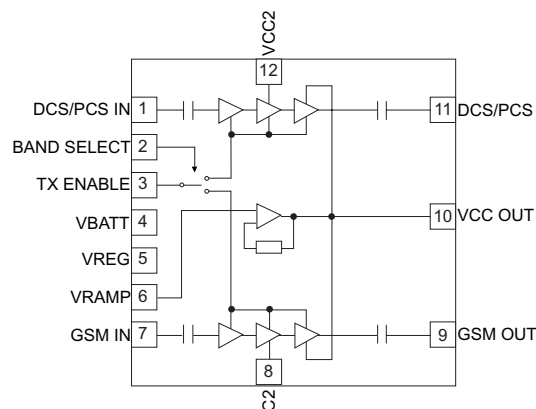


Figure 3-4. Power Amplifier Block Diagram

3.5 13 MHz Clock

The 13 MHz clock(X401) consists of a TCXO(Temperature Compensated Crystal Oscillator) which oscillates at a frequency of 13 MHz. It is used within the Si4133T/Si4201 RF Main Chip,BB Analog chip-set(U102 AD6521), Digital(U101 AD6525), and MIDI(U201) Chipset.

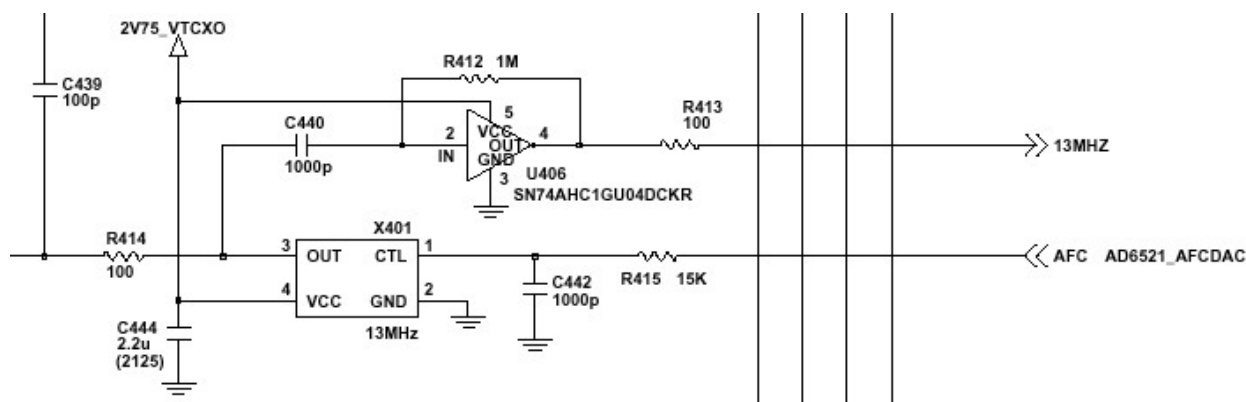


Figure 3-5. VCTCXO Circuit

3.6 Power Supplies and Control Signals

There are two regulators used in the phone to provide RF power. One is contained inside of ADP3522(U302), Power management IC to provide the power for the VCTCXO(X401). The other is used to provide the power for remaining RF circuits.

Table 3-2. Power supplies and control signals.

Regulator	Voltage	Powers	Enable Signal
Regulator 1 (U302, 2V75_VTCXO)	12.75V +/- 0.5V	VTCXO	10.0 mA max
Regulator 2 (U405, RF2.85V)	2.85V +/- 0.5V	RF circuitry	RF_EN

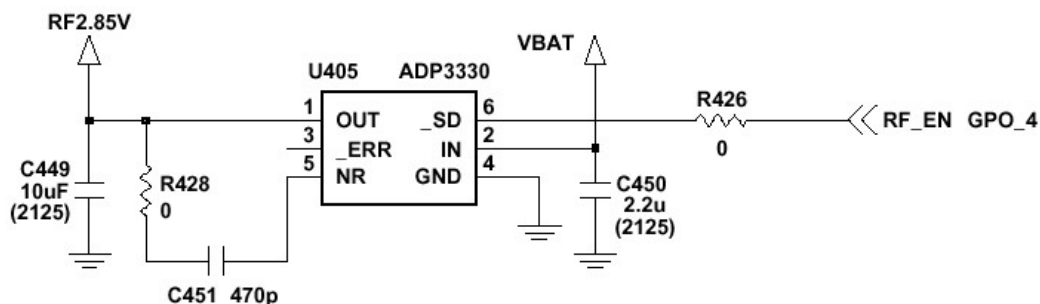


Figure 3-6. Regulator

3.7 Digital Main Processor

AD6525

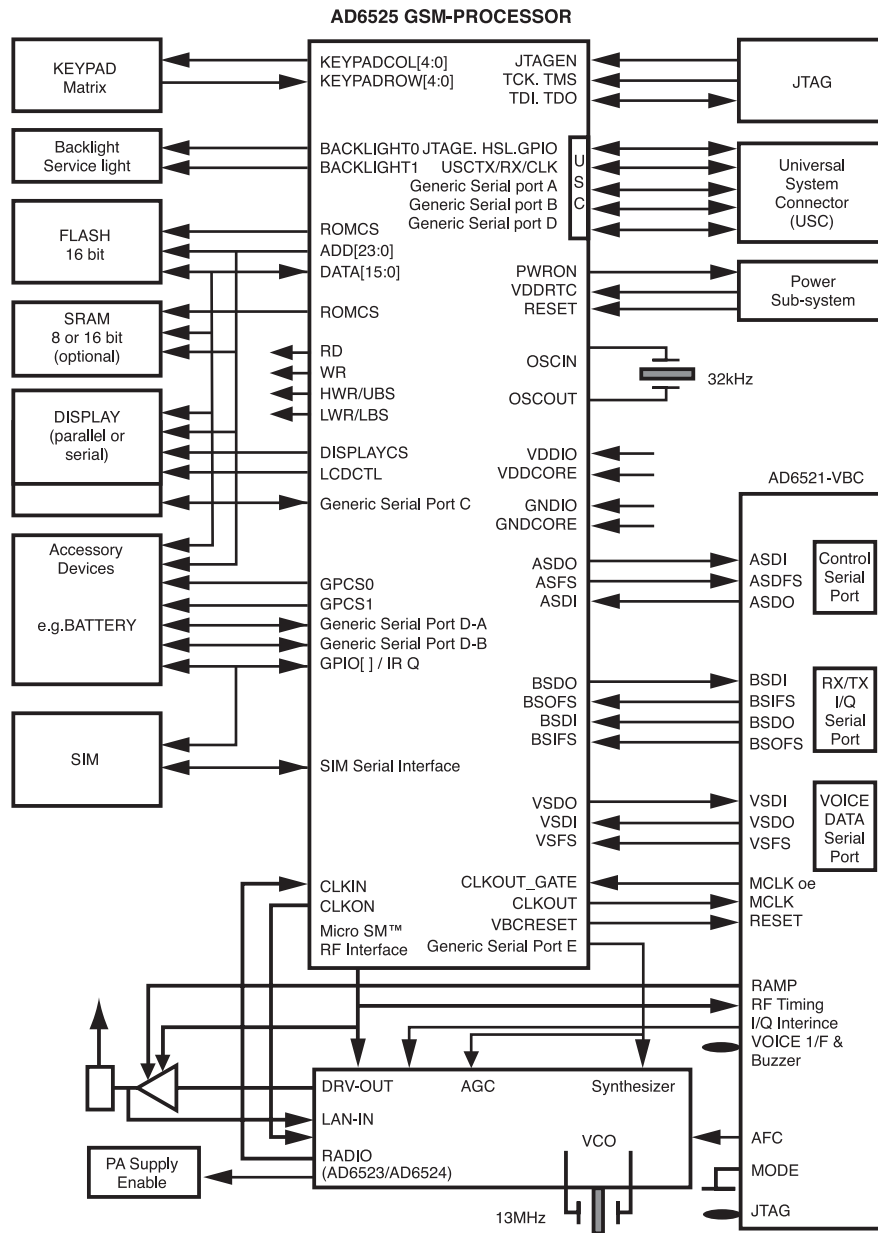


Figure 3-7. Example of System interconnection of AD6525 External Interface

Interconnection with external devices

RTC block interface

Countered by external X-TAL
The X-TAL oscillates 32.768KHz

LCD module interface

Main controlled by _MAIN_LCD_CS, _SUBLCD_CS, LCD_RES,
LCD_RS(ADD1),_WR,DATA[00...15] signals.

Table 3-3.

	Description
_MAIN_LCD_CS	MAIN LCD driver chip enable. MAIN LCD driver IC has own CS pin
LCD_RES	This pin resets LCD module.
LCD_RS (ADD1)	This pin determines whether the data to LCD module are display data or control data. ADD1 can select 16 bit parallel bus. ADD1 is also used to address flash memory.
_WR	Write control. The phone do not read data from LCD chip.
DATA [00...15]	Parallel data lines. Color LCD driver chip uses the 16-bit data interface.
2V8_VMEM	3V voltage is supplied to white colored LED driver for backlighting.
LCD_BACKLIGHT	Control signal of white LED driver IC.
_SUBLCD_CS	SUB LCD driver chip enable, Sub LCD driver IC has own CS pin.
DATA[08...15]	Parallel data lines, Sub LCD driver chip uses the 8-bit data in reface.

RF interface

The AD6522 control RF parts through TXEN, RXON1, RXON2, AGCEN, PLL_DATA, PLL_CLK, PLL_LE etc.

Table 3-4.

GPO	Signal Name	Description	Reset
0	RXON	RX Enable/Disable	L
1	TXON	TX Enable/Disable	L
4	RF_EN	RF LDO Enable/Disable	L
8	VREG	Regulating Voltage input for Power Control function (2.8V nominal)	L
9	ANT_SW1	Antenna Switch Band Select (DCS Band)	L
10	ANT_SW1	Antenna Switch Band Select (GSM Band)	L
16	PA_EN	PAM Enable/Disable	L
17	PA_BAND	PAM Band Selectl	
18	PDNB	Powerdown Input	L
19	S_EN	Serial Enable Input	L
20	S_DATA	Serial Data Input	L
21	S_CLK	Serial Clock Input	L

3. TECHNICAL BRIEF

SIM interface

The AD6525 check status periodically in call mode if SIM card is inserted or not, but the AD6525 don't check in deep sleep mode.

Interface by SIMDATAOP, SIMCLK, SIM_RST(GPIO_23)

Table 3-5.

	Description
SIMDATAOP	This pin receives and sends data to SIM card. This model support 1.8volt or 3.0 volt interface SIM card.
SIMCLK	Clock 3.25MHz frequency.
SIM_RST(GPIO_23)	Reset SIM block.

SIM CONNECTOR

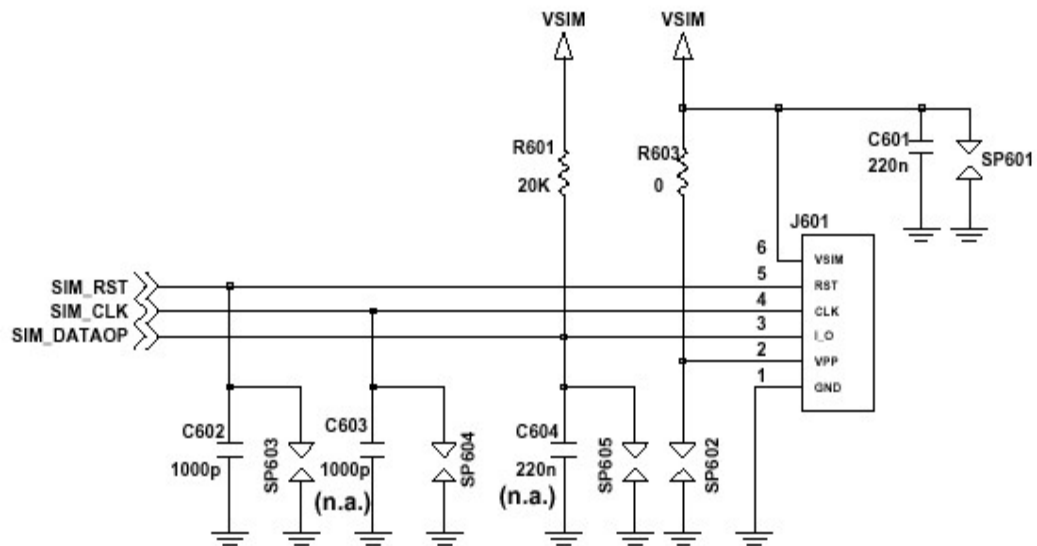


Figure 3-8. SIM Interface of AD6525

Key interface

Include 5 column and 5 row. The AD6522 detect key press by interrupt.

ADP3522 interrupt

There are two interrupts EOC and CHARGEDET

EOC: End of Charge. AD6525 makes charging operation stop when high signal is inputted.

CHARGEDET: This pin is activated when the charger is inserted.

Description

SIMDATAOP This pin receives and sends data to SIM card. This model support 1.8volt or 3.0 volt interface SIM card.

SIMCLK Clock 3.25MHz frequency.

SIM_RST(GPIO_23) Reset SIM block.

3.8 Analog Main Processor

AD6521

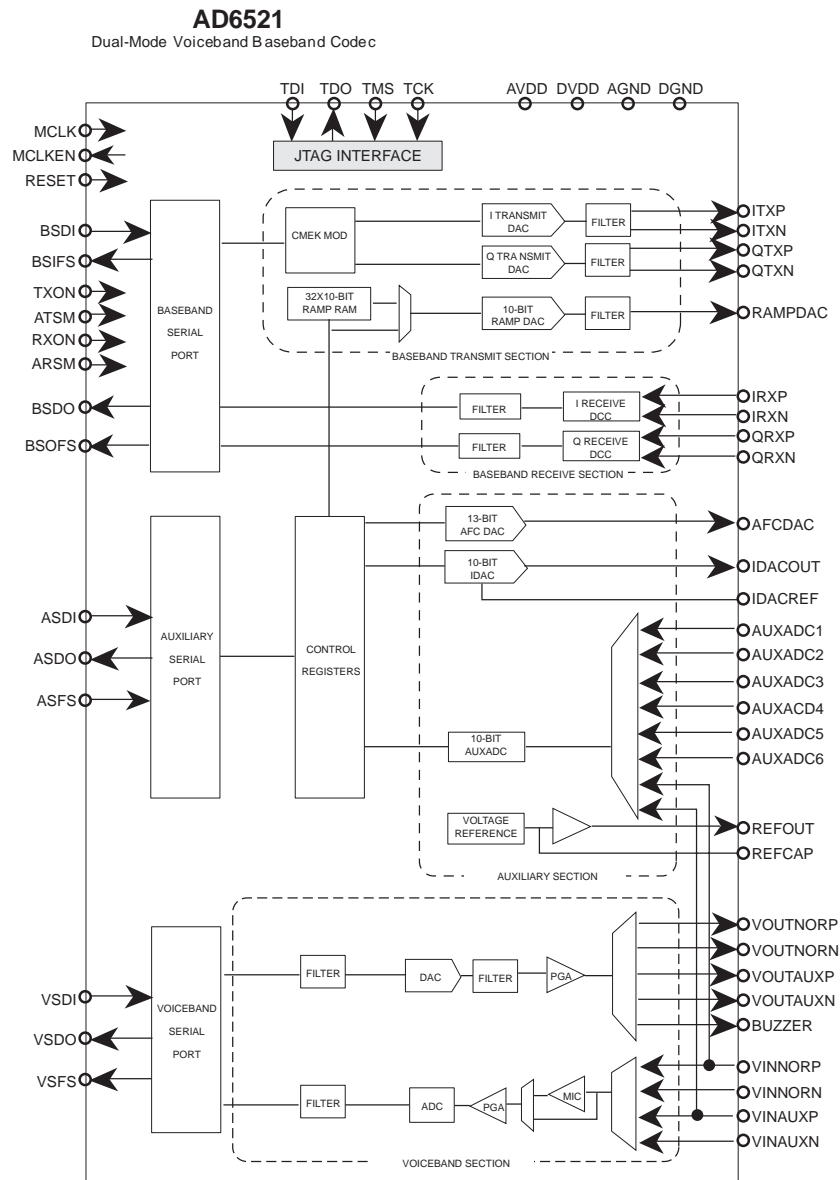


Figure 3-9. AD6521 function block diagram

3. TECHNICAL BRIEF

BB Transmit section

This section generates in-phase and quadrature BB modulated GMSK signals ($BT = 0.3$) in accordance with GSM 05.05 Phase 2 specifications.

- The transmit channel consists of a digital GMSK modulator, a matched pair of 10-bit DACs and a matched pair of reconstruction filter.

BB Receive section

This section consists of two identical ADC channels that process baseband in-phase(I) and quadrature(Q) input signals.

Each channel consists of a coarse switched capacitor input filter, followed by a high-order sigma-delta modulator and a lowpass digital filter.

Auxiliary section

This section contains two auxiliary DACs(AFC DAC, IDAC) for system control.

This section also contains AUX ADC and Voltage Reference

AUX ADC : 6 channel 10 bits

AFC DAC : 13 bits

IDAC : 10 bits

Voiceband section

Receive audio signal from MIC. The phones use differential configuration.

Send audio signal to Receiver. The phones use differential configuration.

It interconnects external devices such as main microphone, main receiver, ear-phone and Hands free kit through the VINNORP, VINNORN, VOUTNORP, VOUTNORN, VINAUXP, VINAUXN, VOUTAUXP, VOUTAUXN

VINNORP, VINNORN: Main MIC positive/negative terminal.

VOUTNORP, VOUTNORN: Main Receiver positive/negative terminal.

VINAUXP, VINAUXN: Hands free kit microphone positive/negative terminal.

VOUTAUXP, VOUTAUXON: Hands free kit speaker positive/negative terminal.

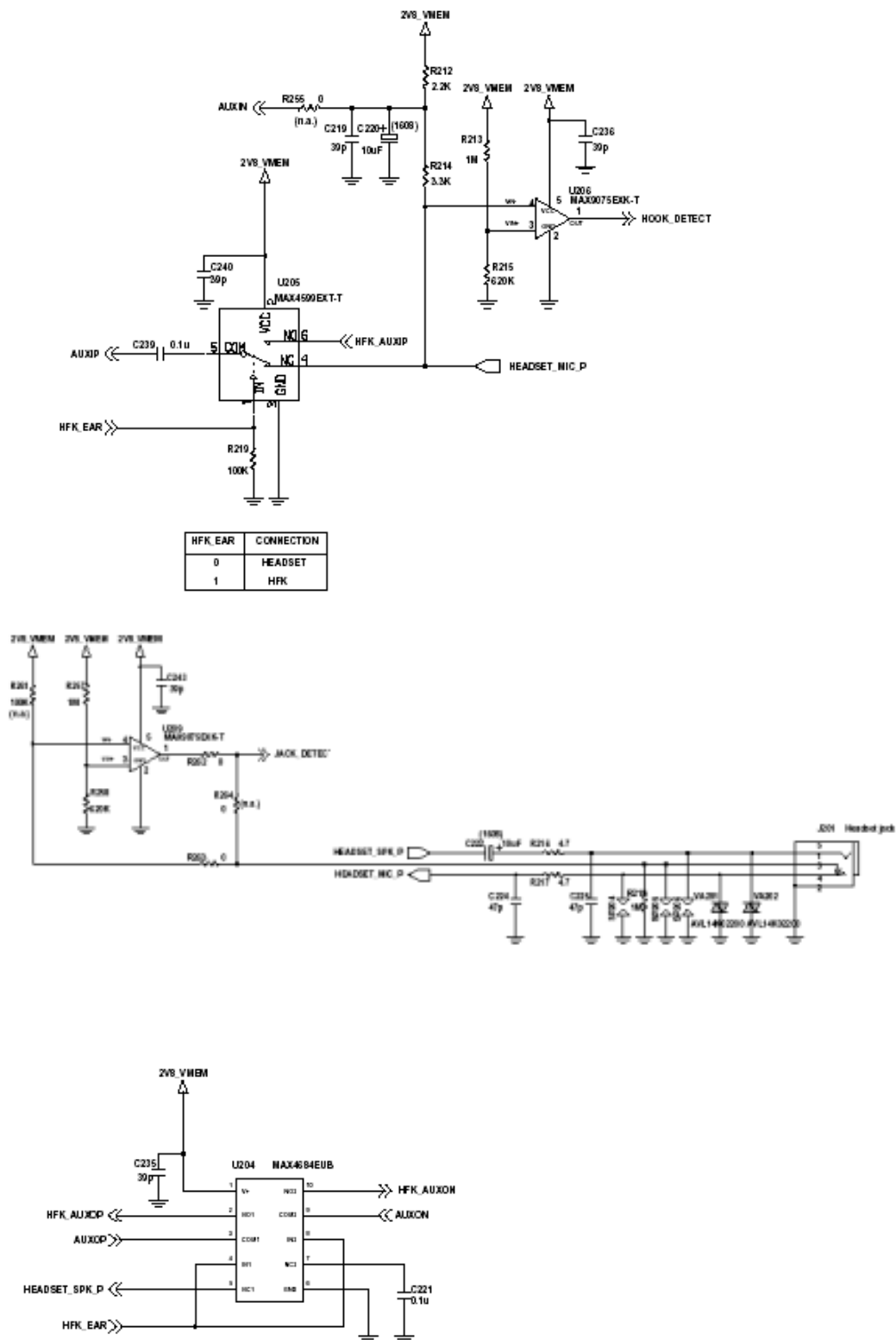


Figure 3-10. Voice band circuit diagram

3. TECHNICAL BRIEF

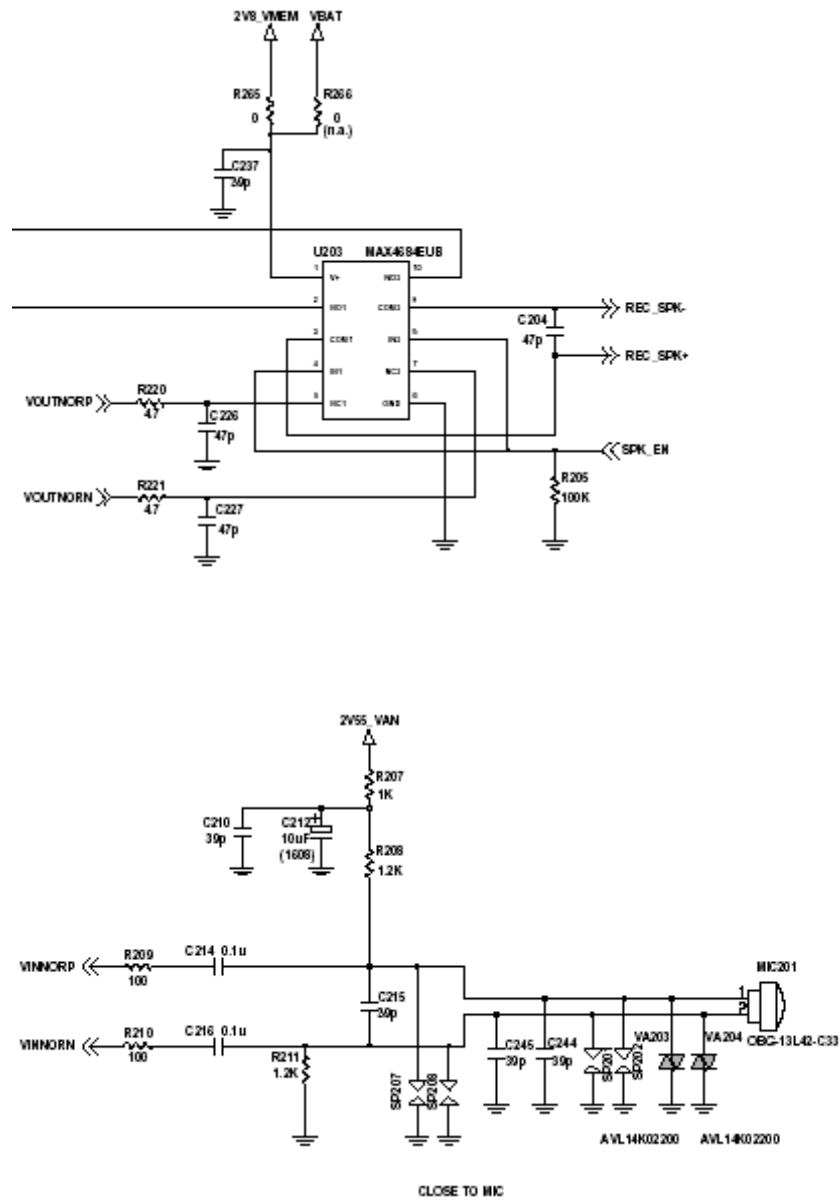


Figure 3-11. Voice band circuit diagram

3.9 Power Management IC

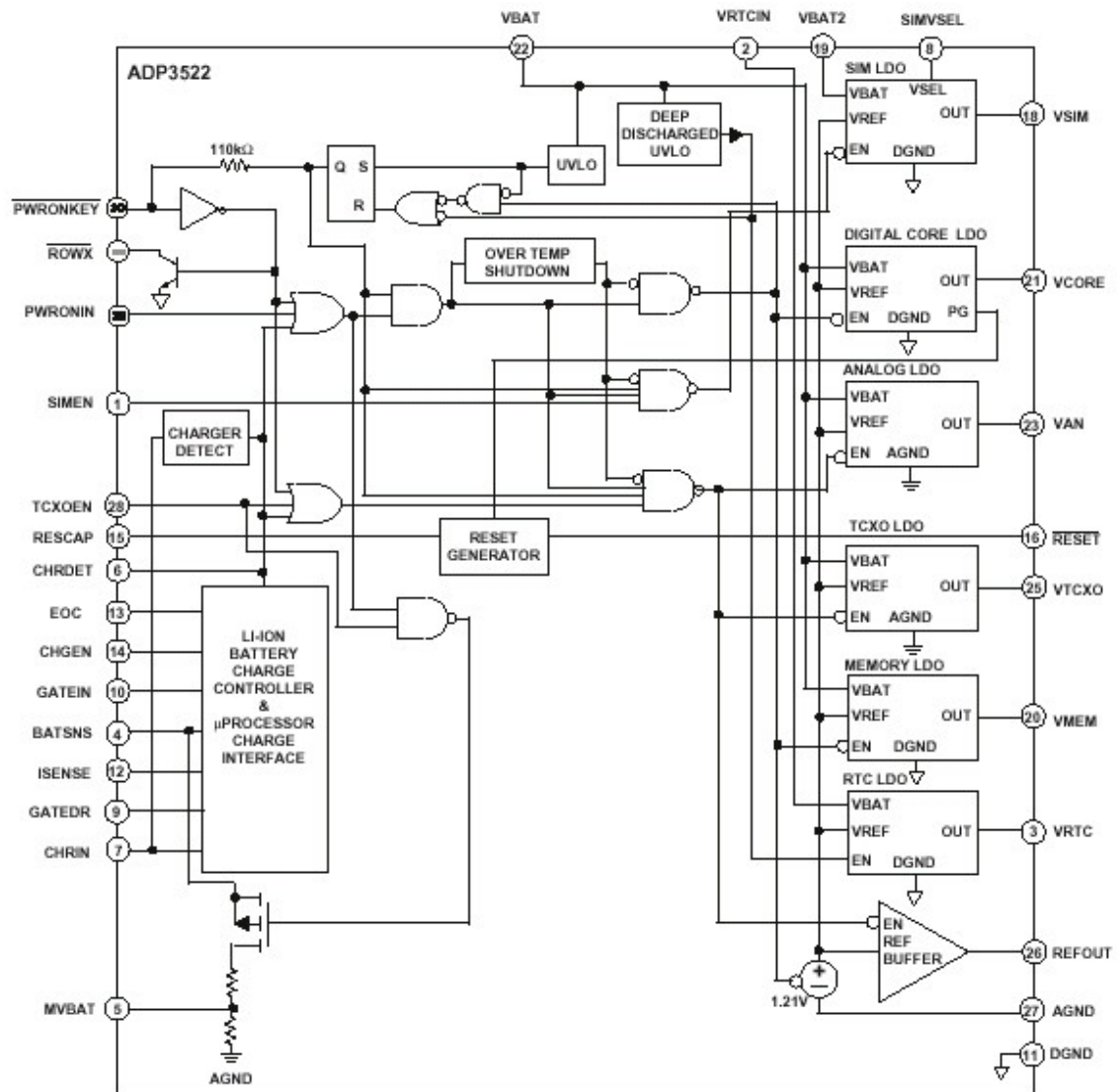


Figure 3-12. ADP3522 inner block diagram

Table 3-6.

	Description
VSIM	2.85V(is provided to SIM card)
VCORE	1.8V(is provided to the AD6525 & AD6521's digital core)
VRTC	2.0V(is provided to the RTC and Backup Battery)
VAN	2.55V(is provided to the AD6521 I/O and used as microphone bias)
VTCXO	2.75V(is provided to VCTCXO)
VMEM	2.8V(is provided to Flash)

Power up sequence logic

The ADP3522 controls power on sequence.

Power on sequence

If a battery is inserted, the battery powers the 6 LDOs.
Then if PWRONKEY is detected, the LDOs output turn on.
REFOUT is also enabled, Reset is generated and send to the AD6525.

LDO block

There are 6 LDOs in the ADP3522.

Battery charging block

It can be used to charge Lithium Ion and/or Nickel Metal Hydride batteries. The phones use Li-Ion battery only. Charger initialization, trickle charging, and Li-Ion charging control are implemented in hardware.

Charging Process

1. Check charger is inserted or not.
2. If ADP3522 detects that Charger is inserted, the CC-CV charging starts.
3. Exception: When battery voltage is lower than 3.2V, the precharge (low current charge mode) starts firstly.
4. And the battery voltage reach to 3.2V the CC-CV charging starts.

Pins used for charging

CHGDET : Interrupt to AD6525 when charger is plugged.
CHGEN : Control signal from AD6525 to charge Li+ battery.
EOC : Interrupt to AD6525 when battery is fully charged.
GATEIN : Control signal from AD6525 to charge NiMH battery. But, not used.
MVBAT : Battery voltage divider. Divide ratio is 1:2.3 and it is sensed in AD6521 AUX_ADC4.

TA (Travel Adaptor)

Input voltage : AC 85V ~ 264V, 47~63Hz
Output voltage : DC 5.2V(± 0.2 V)
Output current : Max 750mA(± 50 mA)

Battery

Li-ion battery : Max 4.2V, Nom 4.0V
Standard battery : Capacity - 740mAh, Li-ion

3.10 Memories

128Mbit flash memory + 32Mbit PSRAM

16 bit parallel data bus

ADD01 ~ ADD22.

2 Chip enables for Flash memory select.

RF Calibration data, Audio parameters and battery calibration data etc are stored in Flash memory area.

3.11 Display and Interface

Table 3-7.

	LCD
Main LCD Display Format	128 × RGB × 160dots
Main LCD Backlight	White LED Backlight
Sub LCD Display Format	96 × 16dots
Sub LCD Backlight	7Color LED Backlight

G5400 Main LCD supports one 65000 color resolution LCD module.

There are the control signals : _MAIN_LCD_CS (which is derived from AD6525, this acts as the chip select enable for the LCD), _WR, LCD_RS and LCD_RES. AD6525 uses DATA[00:15] pins to send data for displaying graphical text onto the LCD.

G5400 Sub LCD supports one 65000 mono resolution LCD module.

There are the control signals : _SUBLCD_CS (which is derived from AD6525, this acts as the chip select enable for the LCD), _WR, LCD_RS and LCD_RES. AD6525 uses DATA[08:15] pins to send data for displaying graphical text onto the LCD.

3.12 Keypad Switches and Scanning

The key switches are metal domes, which make contact between two concentric pads on the keypad layer of the PCB when pressed. There are 25 switches (KB1-KB22), connected in a matrix of 5 rows by 5 columns, as shown in Figure, except for the power switch (KD110), which is connected independently. Functions, the row and column lines of the keypad are connected to ports of AD6525. The columns are outputs, while the rows are inputs and have pull-up resistors built in. When a key is pressed, the corresponding row and column are connected together, causing the row input to go low and generate an interrupt. The columns/rows are then scanned by AD6525 to identify the pressed key.

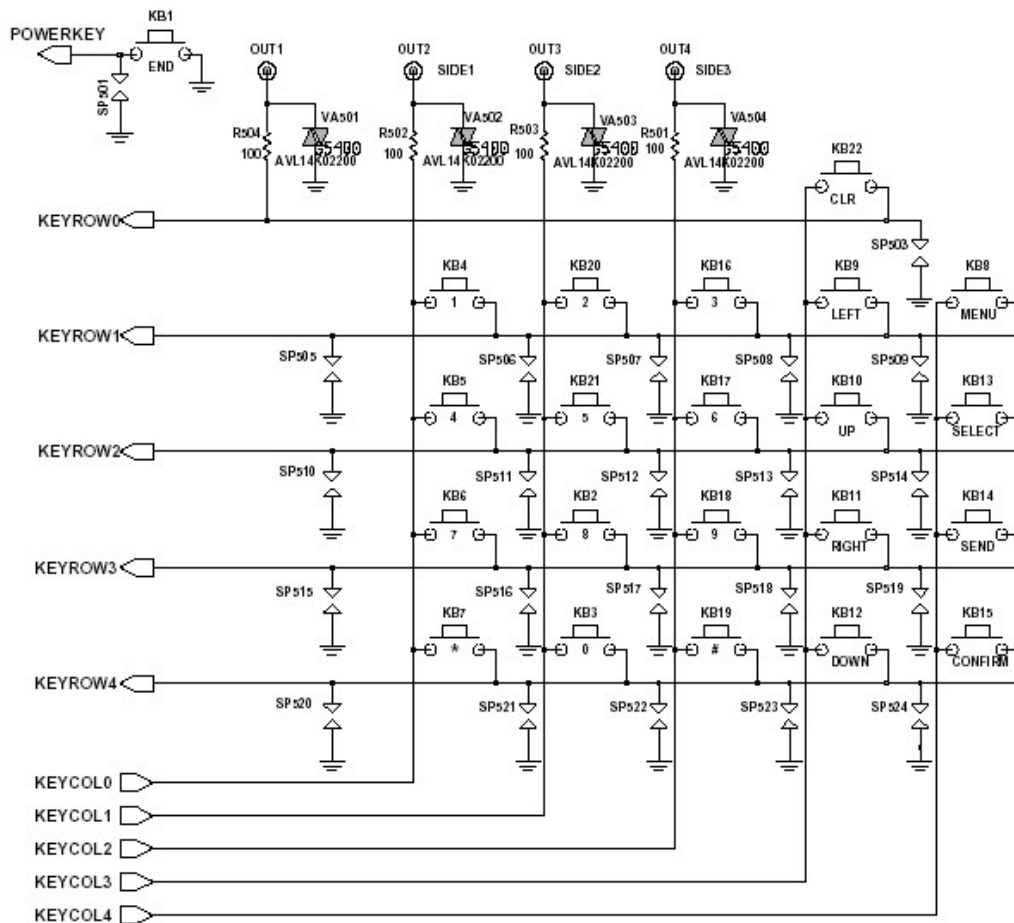


Figure 3-13. Keypad Switches and Scanning

3.13 Microphone

The microphone is placed to the front cover and contacted to main PCB. The audio signal is passed to VINNORP (#J10) and VINNORN (#K10) pins of AD6525. The voltage supply 2V55_VAN is output from ADP3522, and is a bias voltage for the VINNORP. The VINNOR or VINAUX signal is then A/D converted by the Voiceband ADC part of AD6521. The digitized speech is then passed to the DSP section of AD6525 for processing (coding, interleaving etc.).

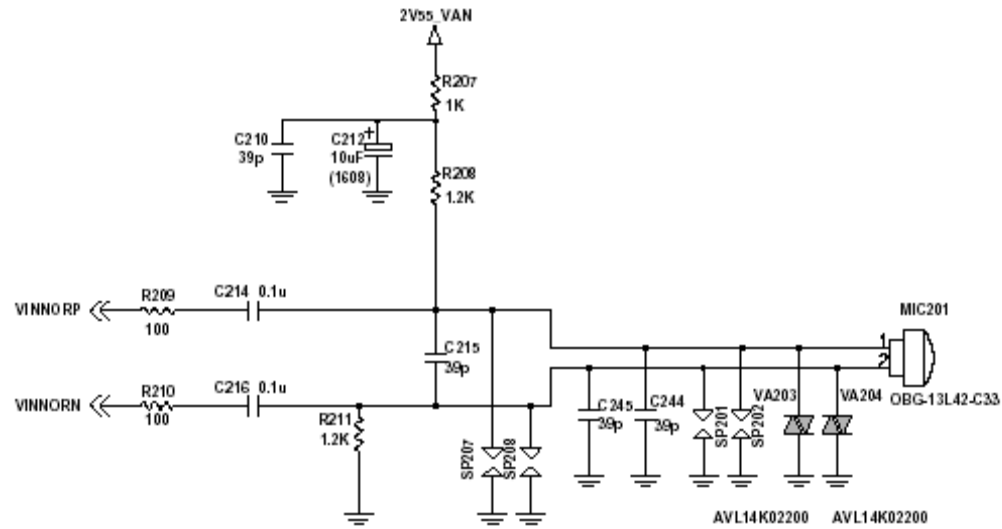


Figure 3-14. Microphone

3.14 Earpiece

The earpiece is driven directly from AD6521 VOUTNORP (#K8) and VOUTNORN (#K7) pins and the gain is controlled by the PGA in an AD6521.

The earpiece is placed in the folder cover and contacted to LCD PCB.

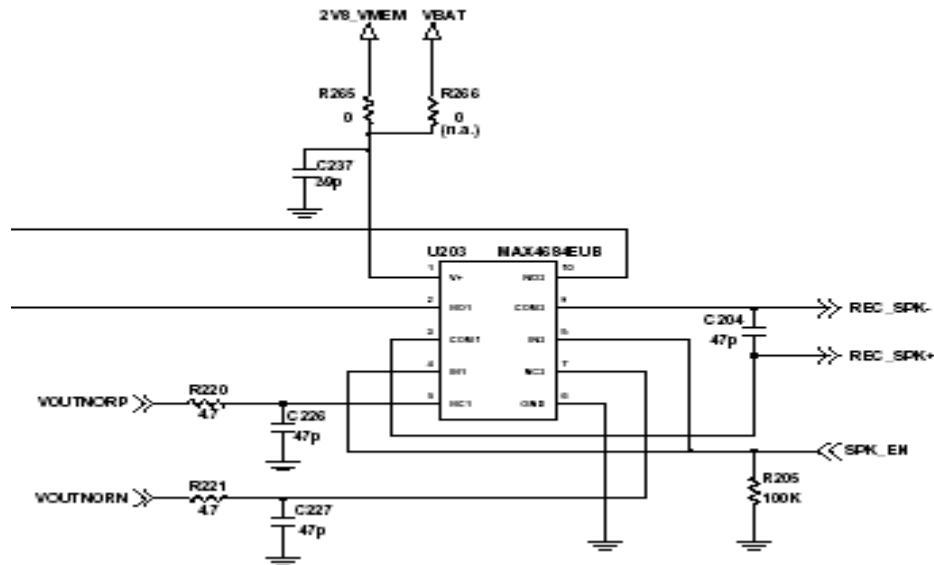


Figure 3-15. Earpiece

3.15 Hands-free Interface

The audio out (VOUTAUXP & VOUTAUXN) to the hands-free kit consists of a pair of differential signal from AD6521 auxiliary outputs (#K9, #K6), which are tracked down the board to carkit connector (CN602) at the base of the handset. The DC level of the signal is supplied to the VOUTAUX pin.

3.16 Headset Jack Interface

This phone chooses a 3-pole type ear-mic jack which has three electrodes such as Receiver +, Mic+, and GND. This type usually supports only single-ended configuration in the audio path. But most of phones use the common interface.

3.17 Key Back-light Illumination

In key back-light illumination, there are 12 Blue LEDs in Main Board, which are driven by KEY_BACKLIGHT line from AD6525.

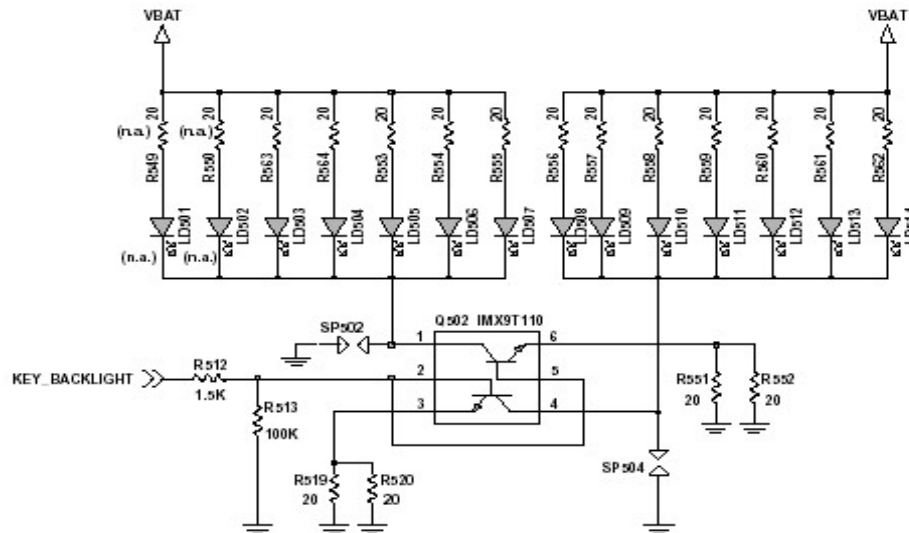


Figure 3-16. Key Back-light Illumination

3.18 LCD Back-light Illumination

In LCD Back-light illumination, there is an driver in LCD Board, which is driven by BACKLIGHT line from AD6525.

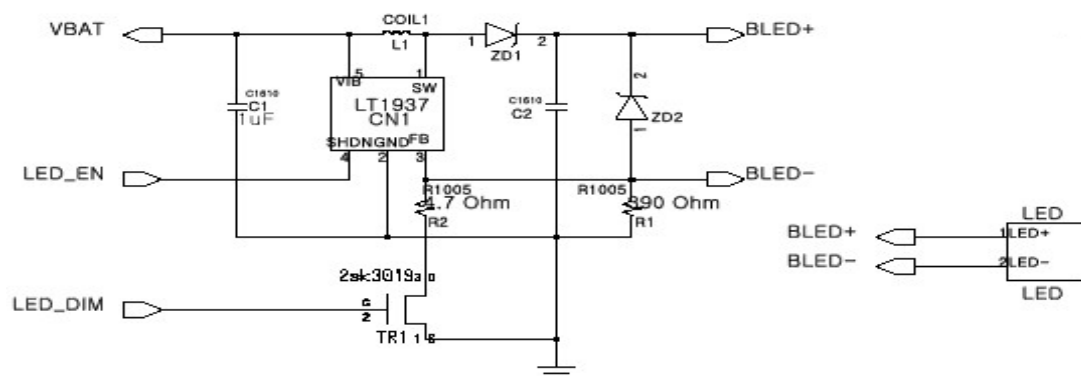


Figure 3-17. Main LCD Back light Illumination

3. TECHNICAL BRIEF

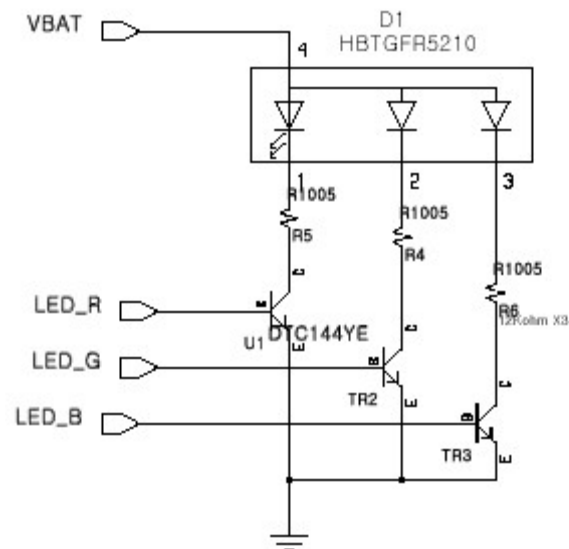


Figure 3-18. Sub LCD Back-light Illumination

3.19 Speaker & MIDI IC

LG-G5400 don't use buzzer. but uses the loud speaker and Melody IC which makes the robust joyful melody sounds.

- Melody IC control

2GPIO are assigned to control melody IC. Melody data is transferred to melody IC.

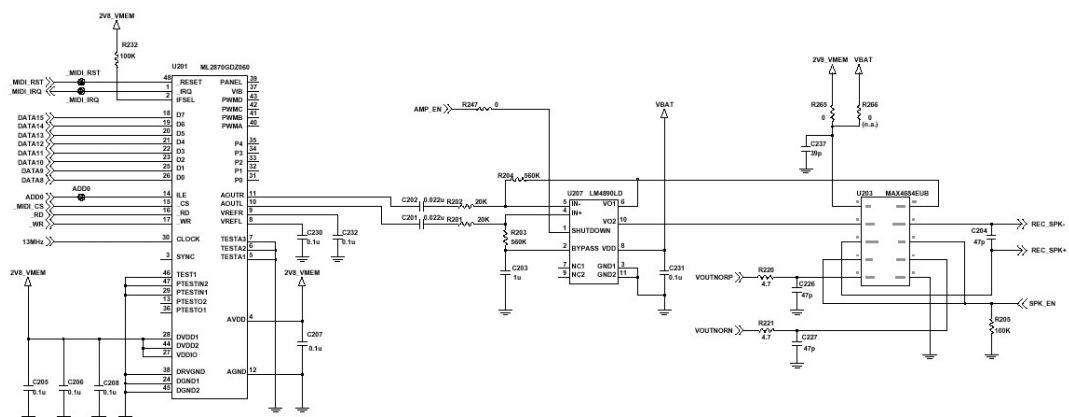


Figure 3-19. Speaker & MIDI IC

Basically, this phone have a melody IC of Oki ltd. ML2870(melody IC maker partnumber) is a PCM-based hi-grade sound generator LSI for mobile phones that realize advanced game sounds. This LSI stands in need of external amplifier. External amplifier used by mobile phones in addition to game sounds and ringing melodies that are replayed by a sound generator. This melody IC has hi-grade 175 polyphonies based on General MIDI system level1, the standard spec for PCM sound generator.

4. TROUBLE SHOOTING

4.1 RF COMPONENTS

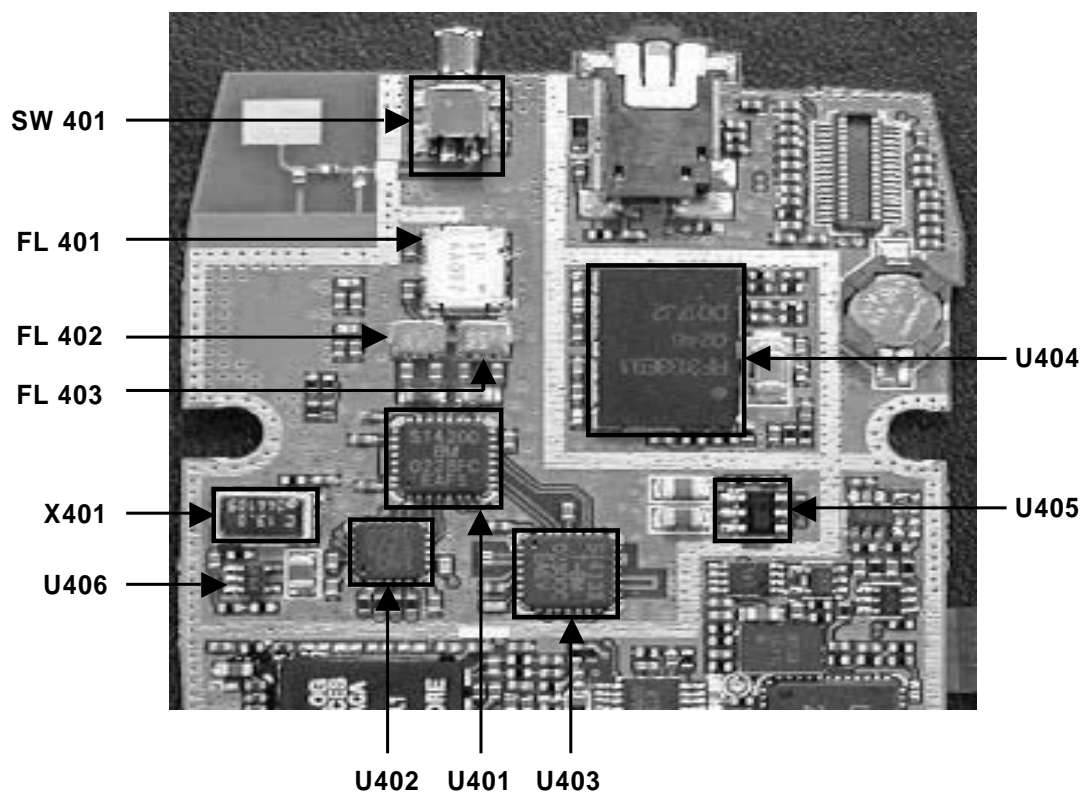


Figure 4-1.

Table 4-1.

Reference	VC1	VC2	Current
U401, U402, U403	RF Main Chip	SW401	Mobile Switch
U404	PAM	FL401	Antenna Switch
U405	RF LDO	FL402	GSM SAW Filter
U406	Inverter	FL403	DCS SAW Filter
X401	VCTCXO		

4.2 Rx Trouble

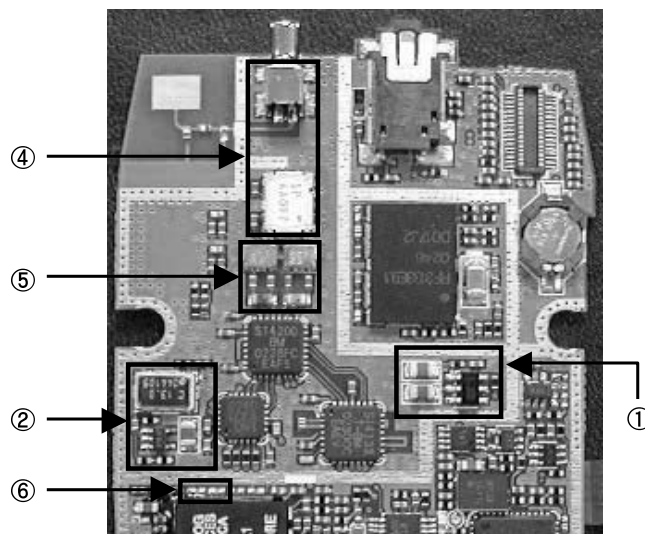
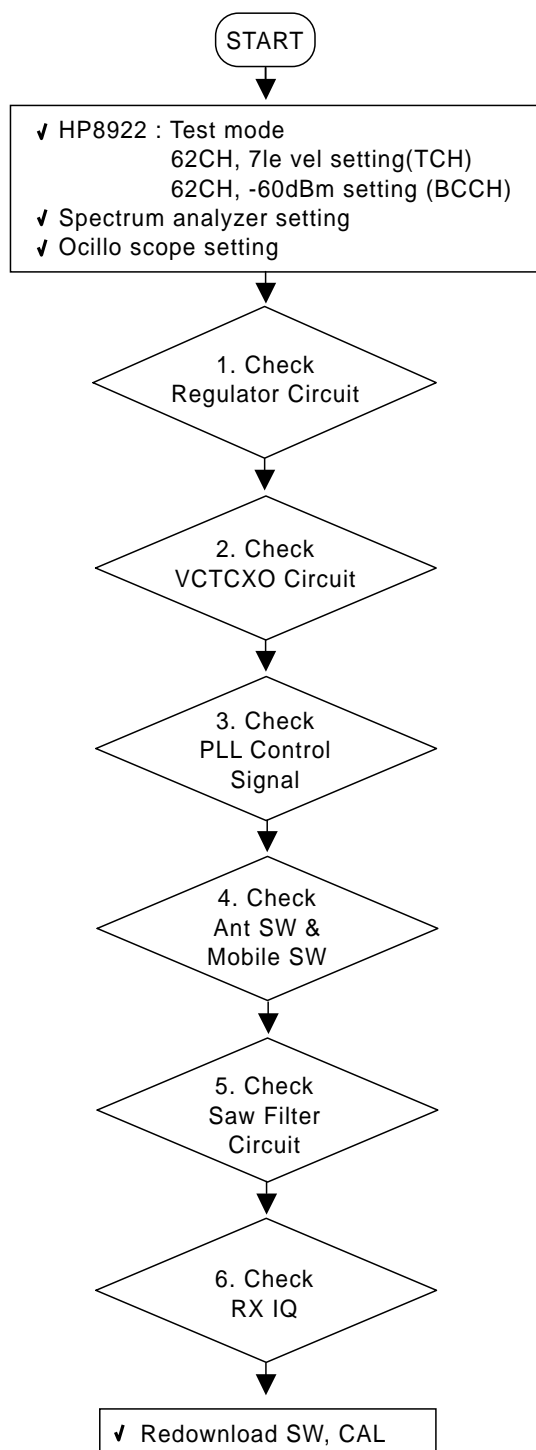


Figure 4-2a.

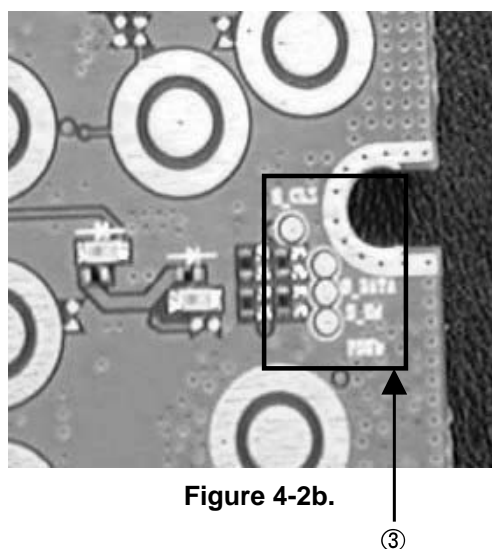
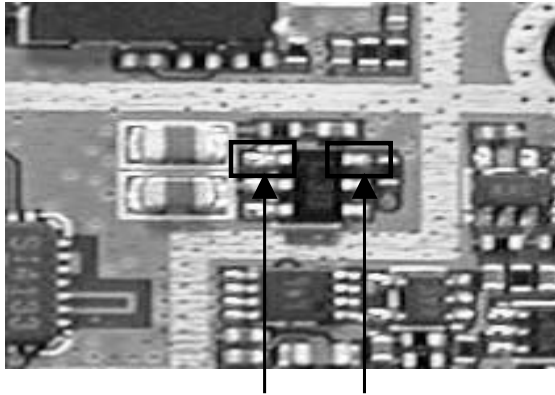


Figure 4-2b.

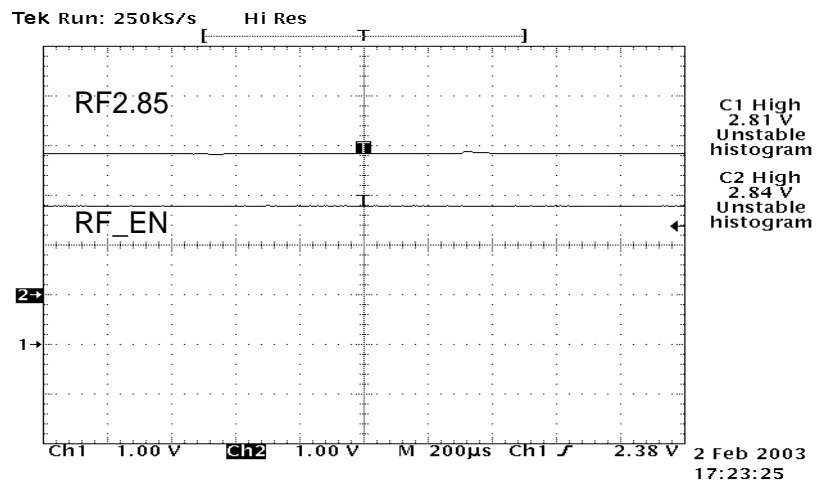
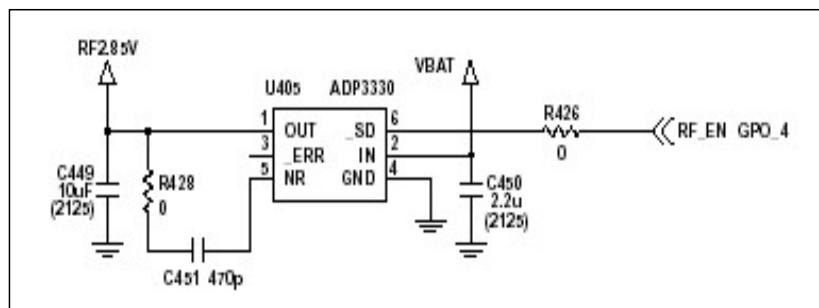
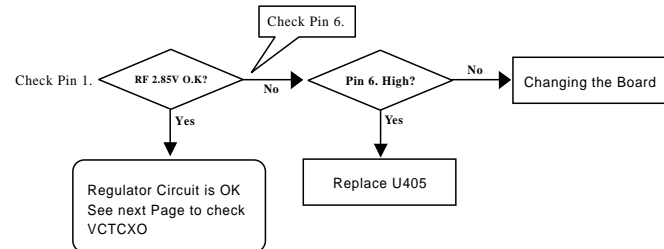
Now See next Page to see
How to check each parts

4.2.1 Checking Regulator Circuit



U405.1 U405.6

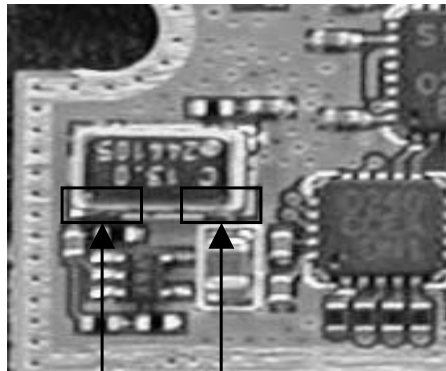
Figure 4-3.



Graphic 4-1.

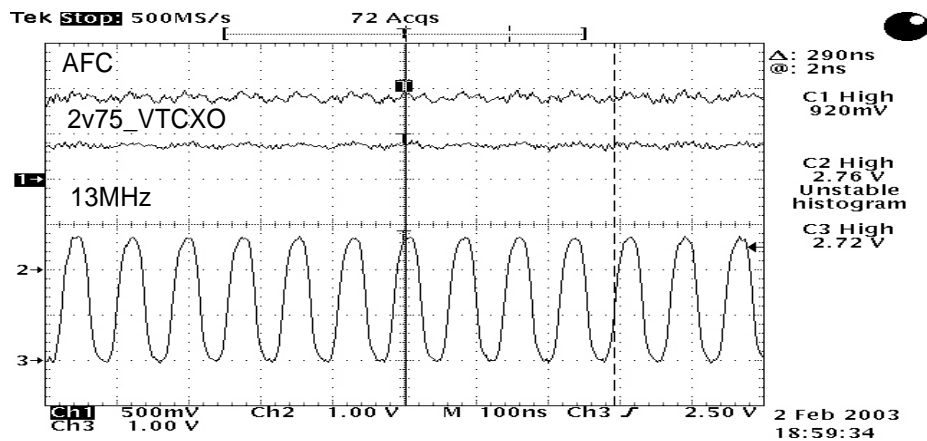
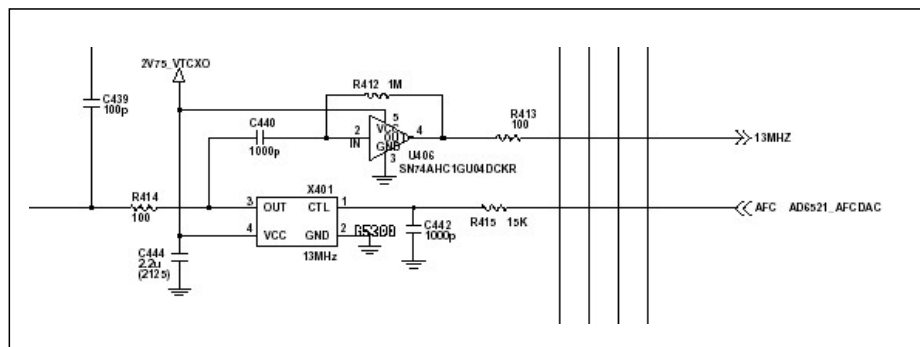
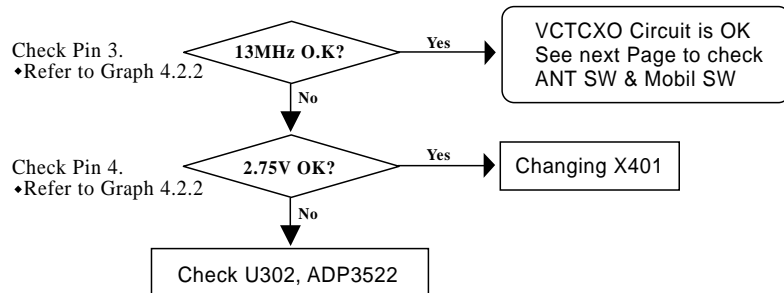
4. TROUBLE SHOOTING

4.2.2 Checking VCTCXO Circuit



X401.3 X401.4

Figure 4-4.



Graphic 4-2.

4.2.3 Checking PLL Control Signal

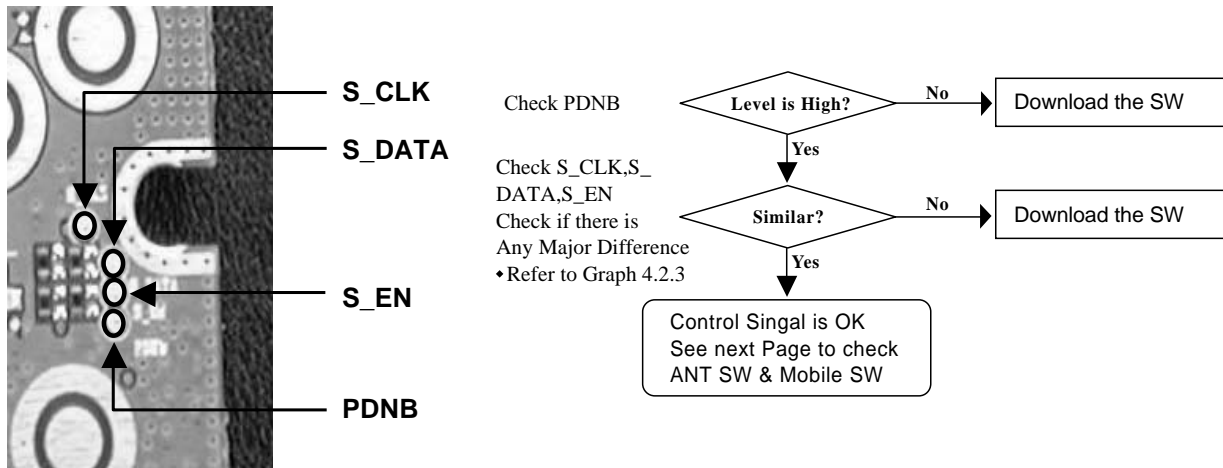
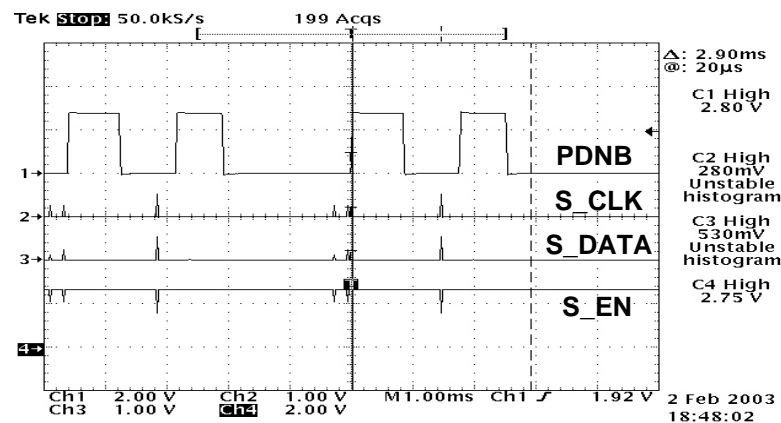
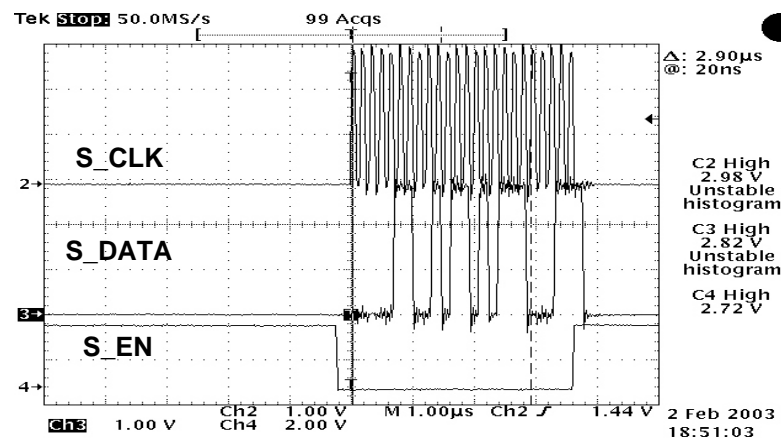


Figure 4-5.



Graphic 4-3a.



Graphic 4-3b.

4.2.4 Checking Ant SW & Mobile SW

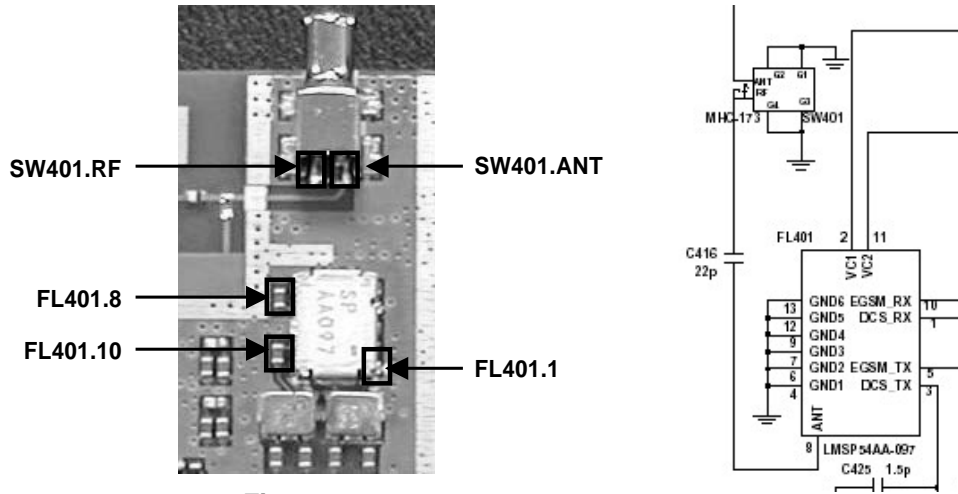


Figure 4-6.

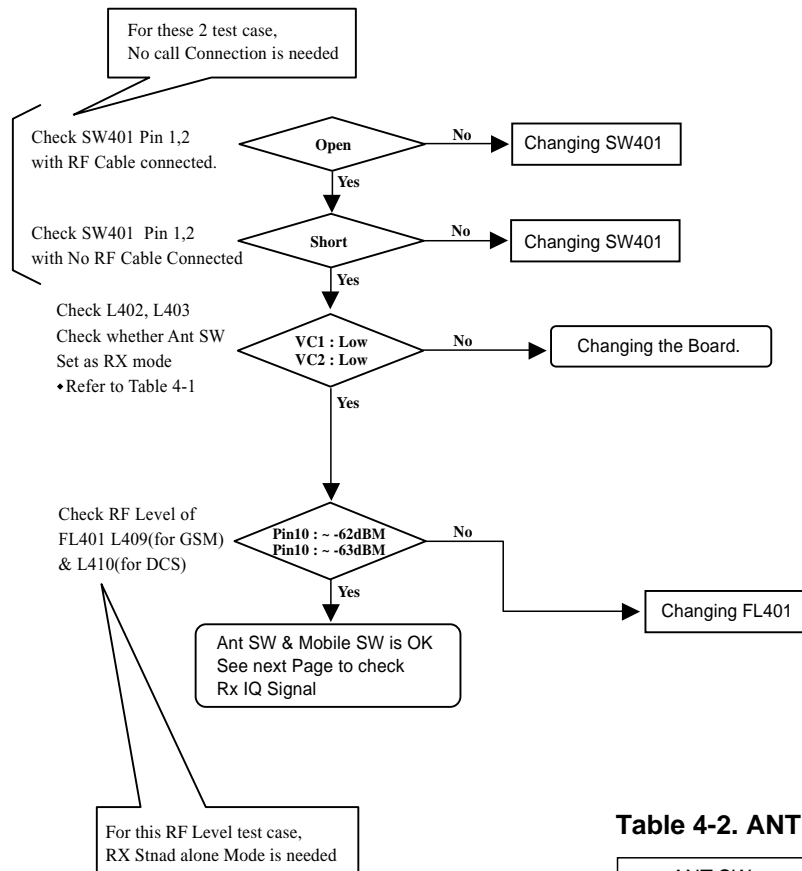


Table 4-2. ANT SW Control Logic

ANT SW	VC1	VC2
EGSM TX	0	1
DCS TX	1	0
EGSM, DCS RX	0	0

4.2.5 Checking SAW Filter Circuit

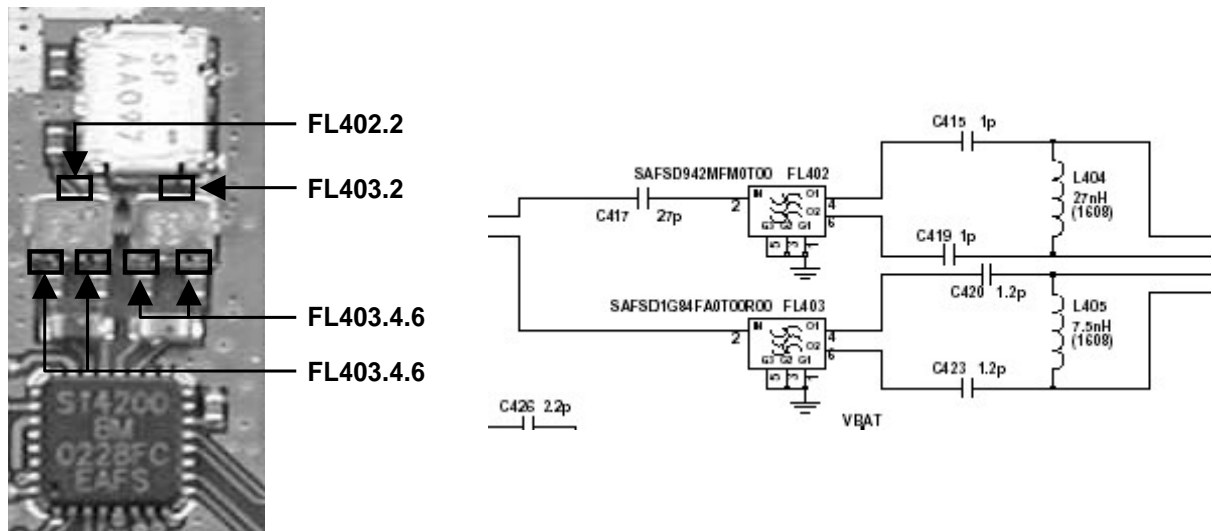
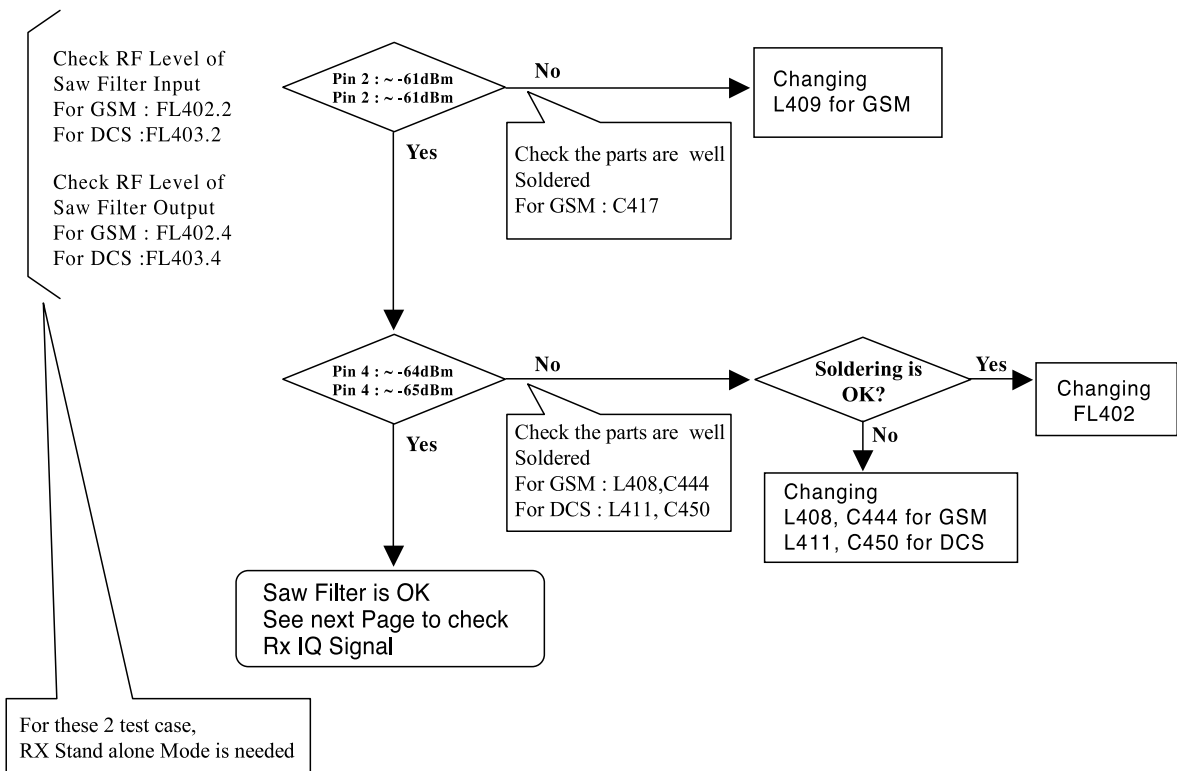
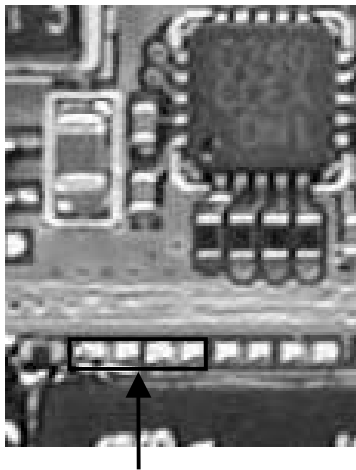


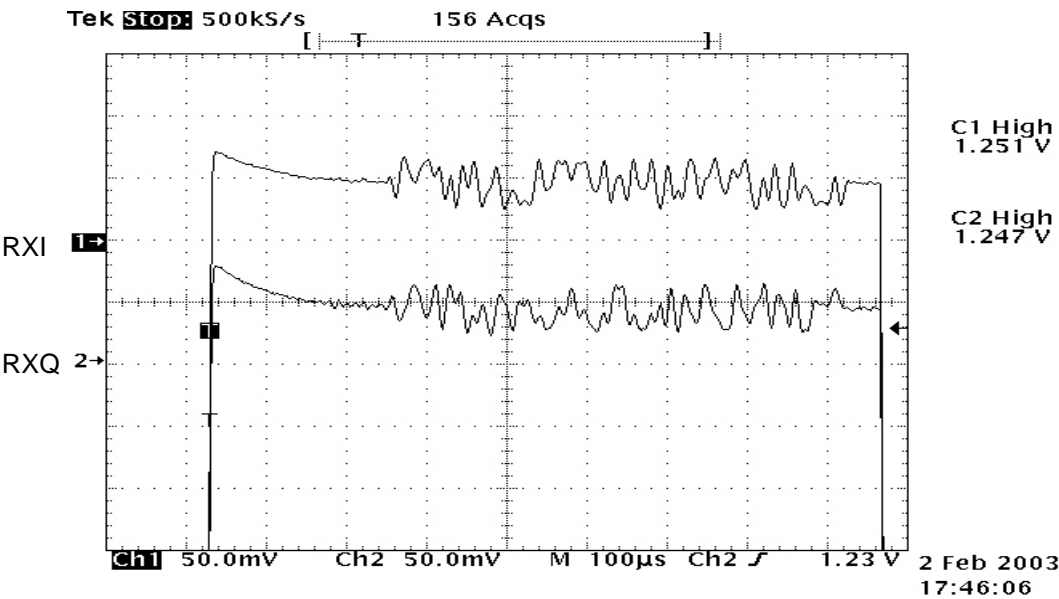
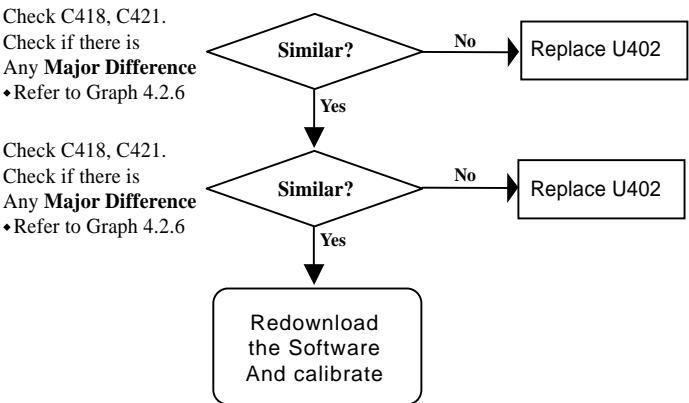
Figure 4-7.



4.2.6 Checking RX IQ



C418, C421
Figure 4-8.



Graphic 4-4.

4.3 TX Trouble

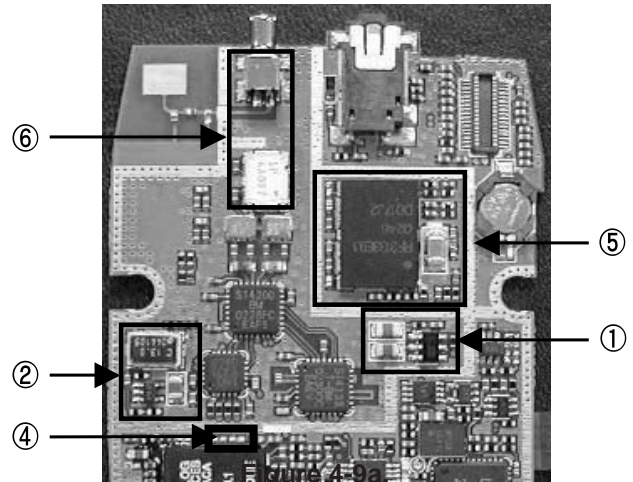
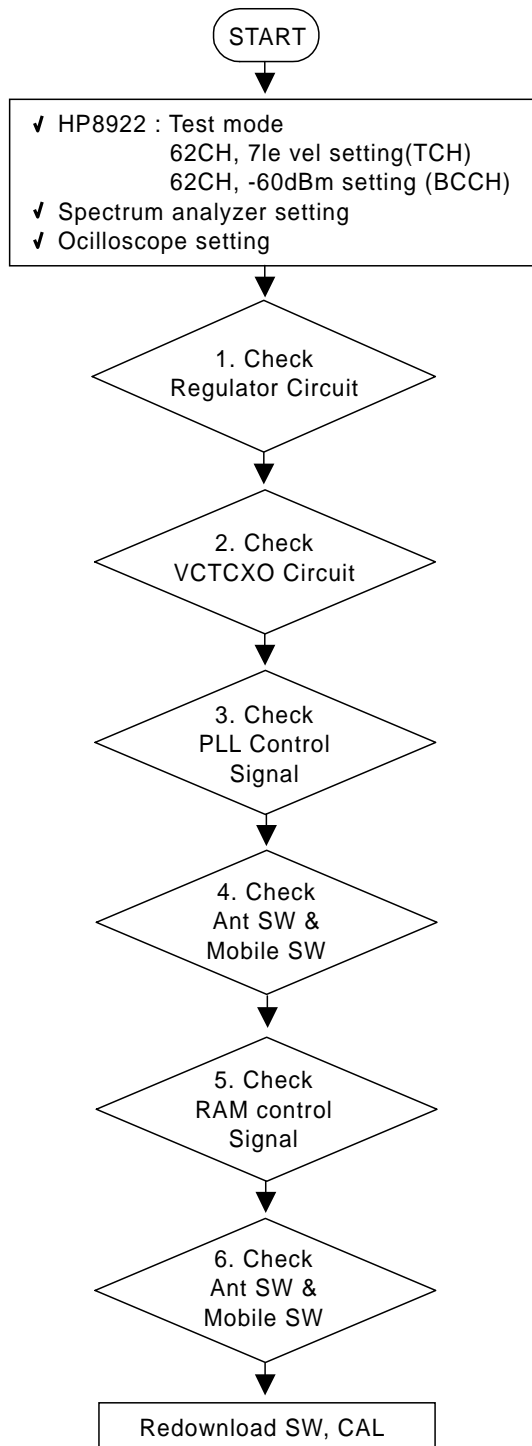


Figure 4-9a.

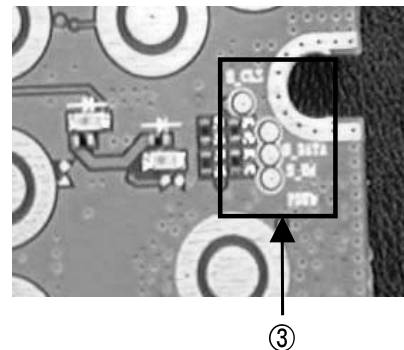
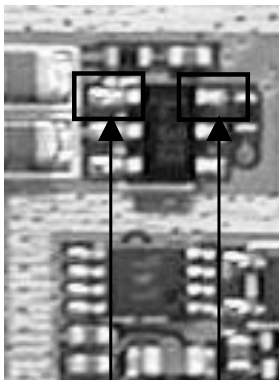


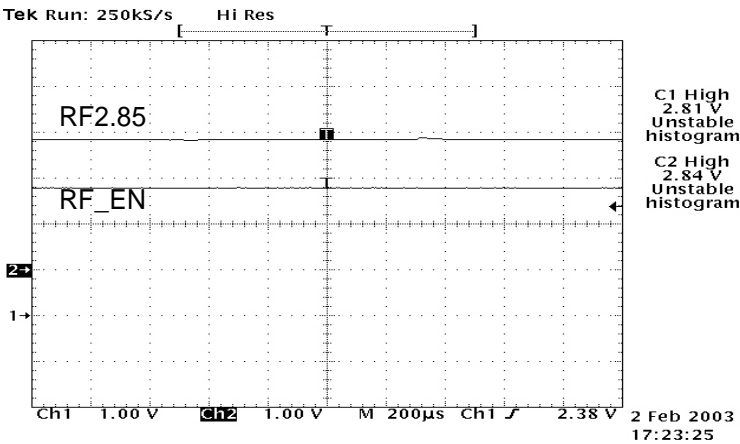
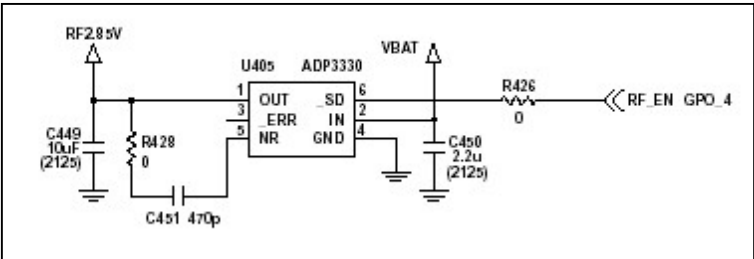
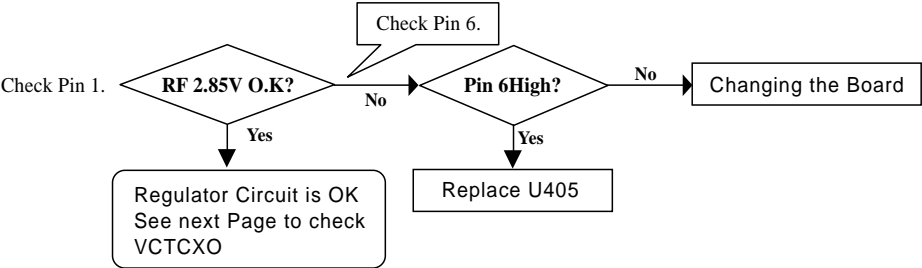
Figure 4-9b.

Now next Page to see
How to check each parts

4.3.1 Checking Regulator Circuit

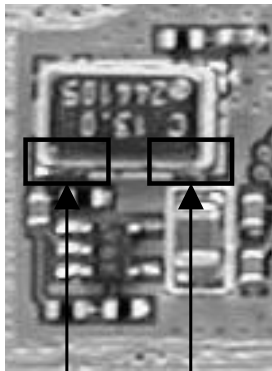


U405.1 U405.6
Figure 4-10.



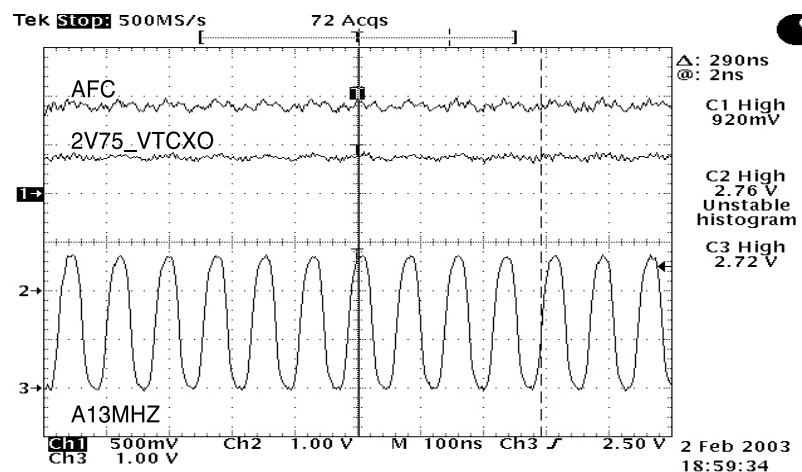
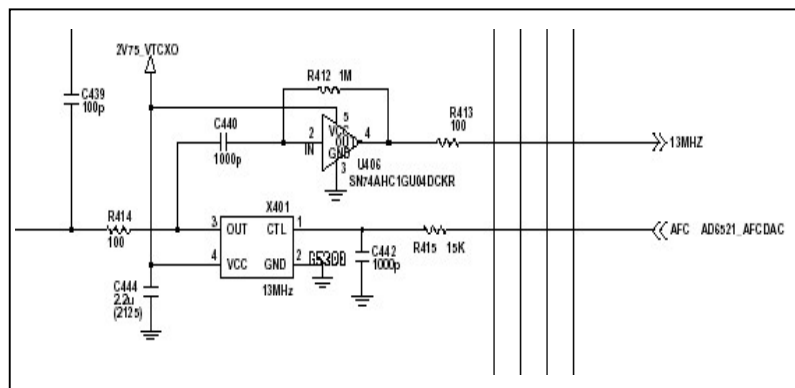
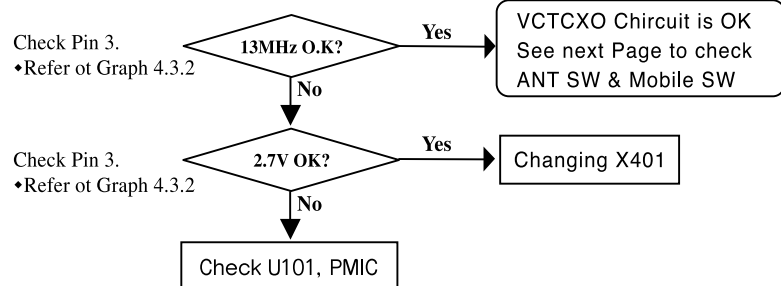
Graphic 4-5.

4.3.2 Checking VCTCXO Circuit



X401.3 X401.4

Figure 4-11.



Graphic 4-6.

4.3.3 Checking PLL Control Signal

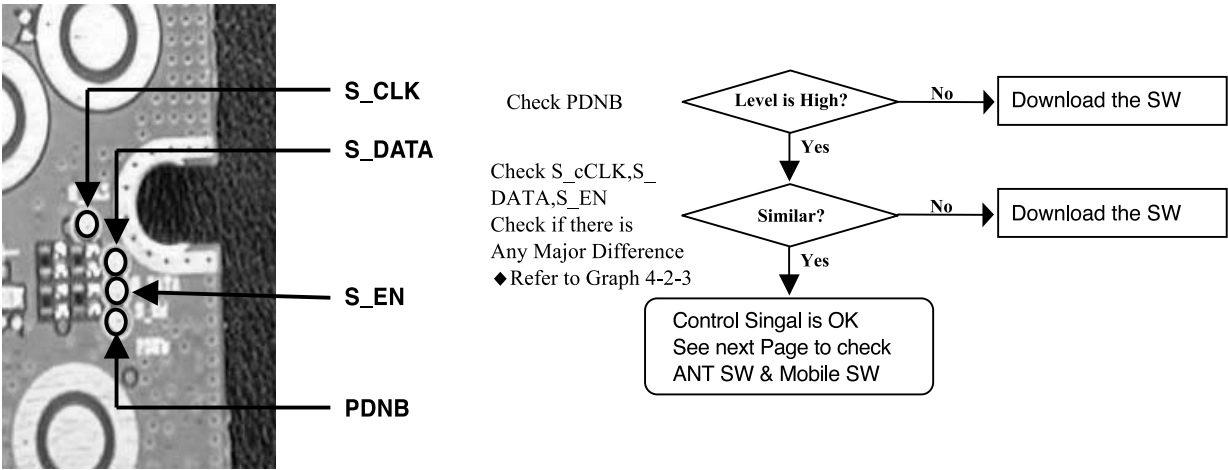
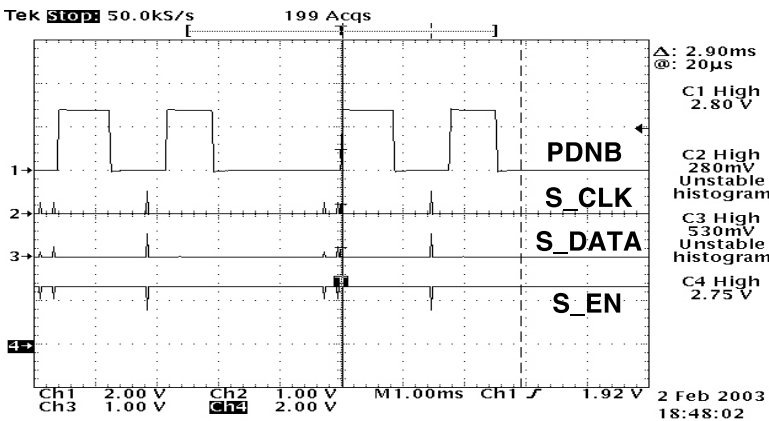
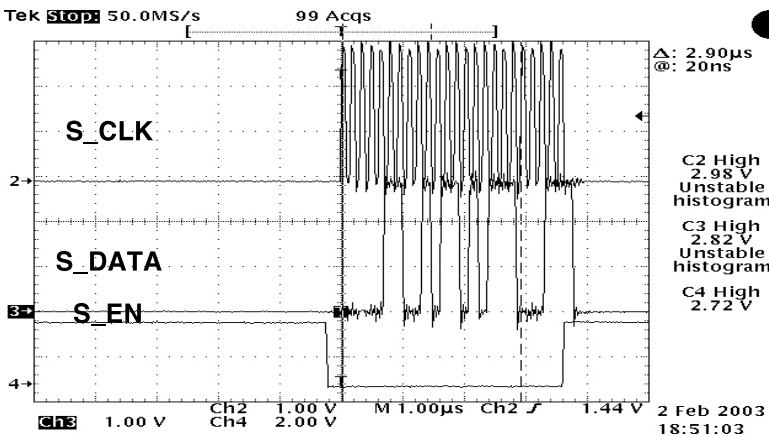


Figure 4-12.



Graphic 4-7a.



Graphic 4-7b.

4.3.4 Checking Ant SW & Mobile SW

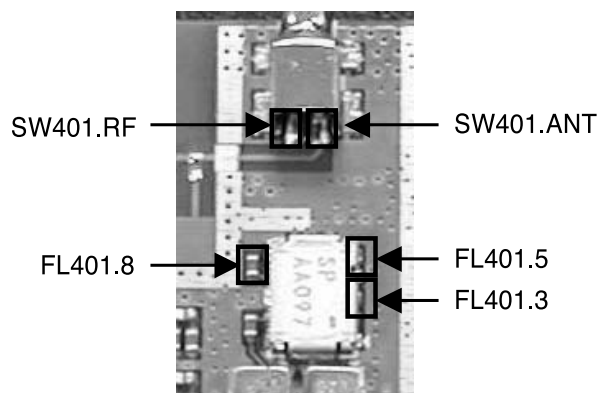
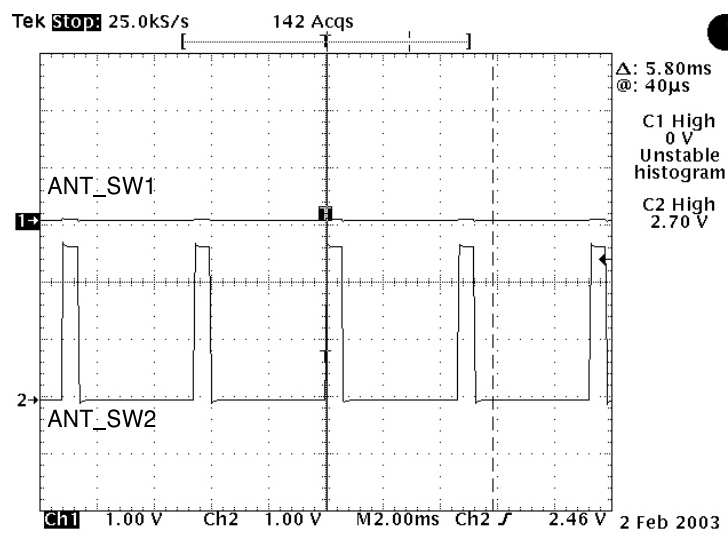
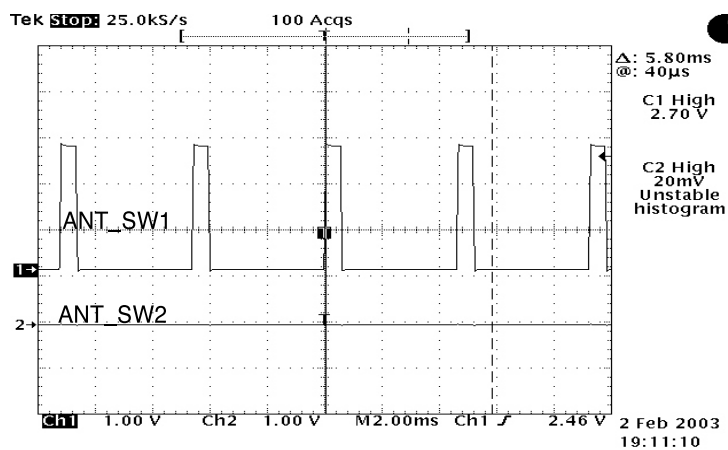


Figure 4-13.



Graphic 4-8a. GSM Tx mode



Graphic 4-8b. DCS Tx mode

4.3.5 Checking PAM Control Signal

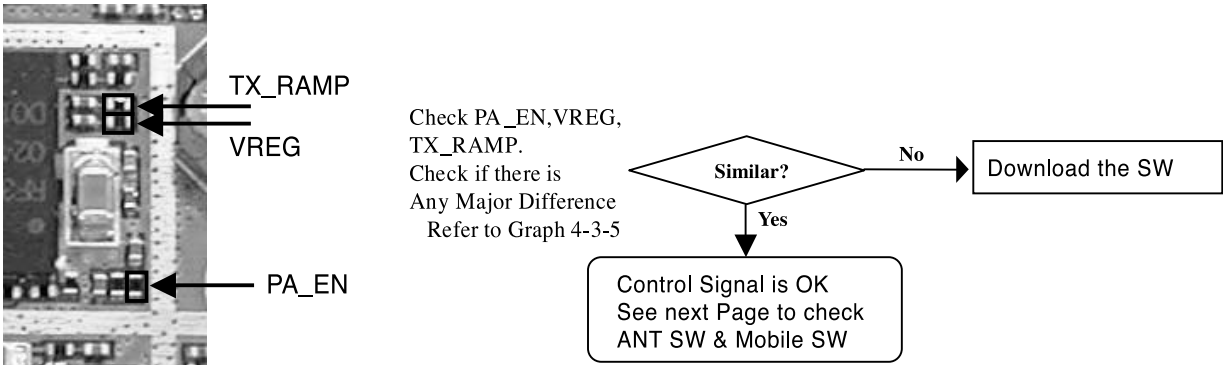
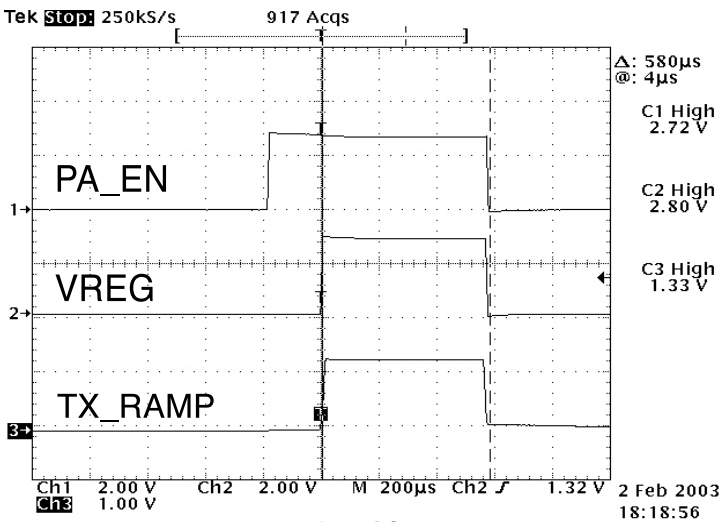
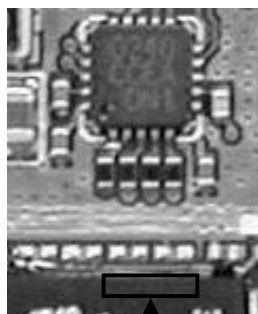


Figure 4-14.



Graphic 4-9.

4.3.6 Checking TX IQ



C427, C436

Figure 4-15.

Check C427, C436.
Check if there is
Any Major Difference
Refer to Graph 4-10

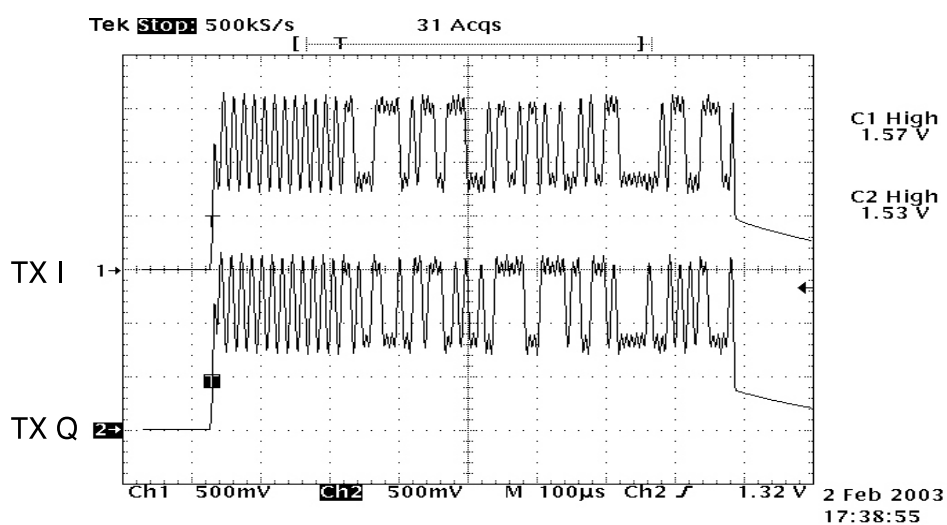
Similar?

No

Download the SW

Yes

TX IQ Signal is OK
See next Page to check
RF TX Level



Graphic 4-10.

4.3.7 Receiver and Transmitter RF Level

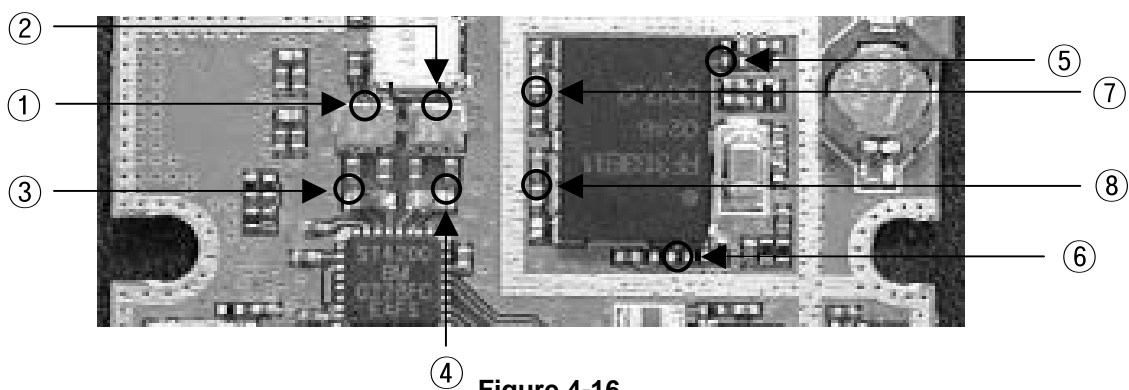
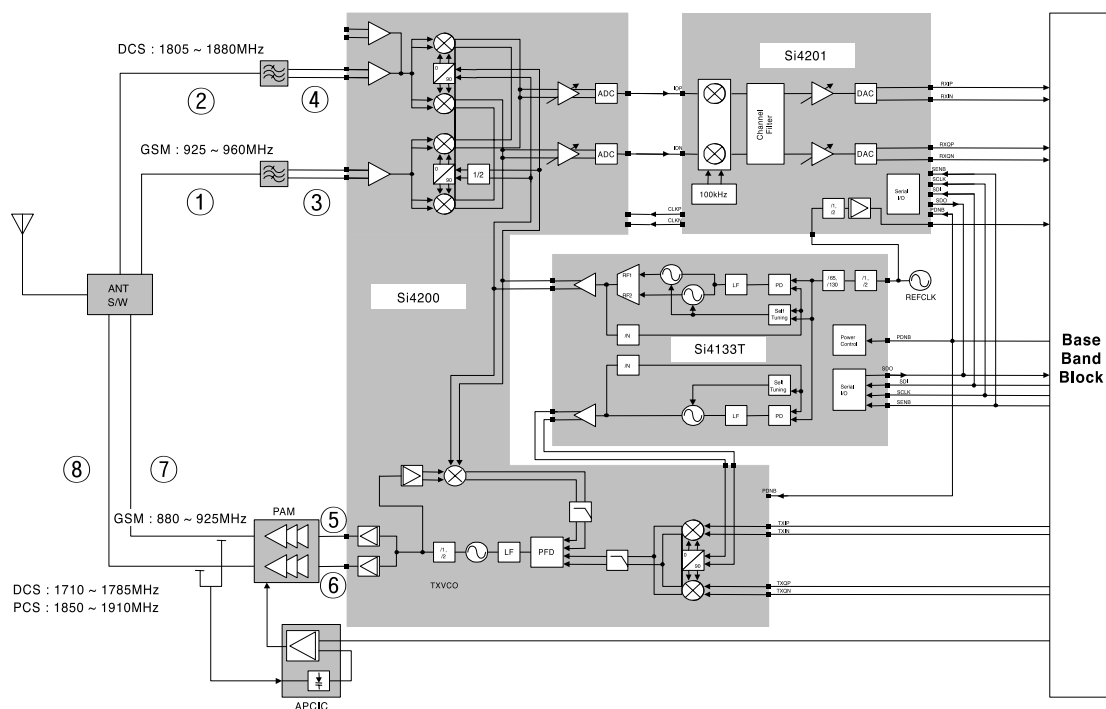
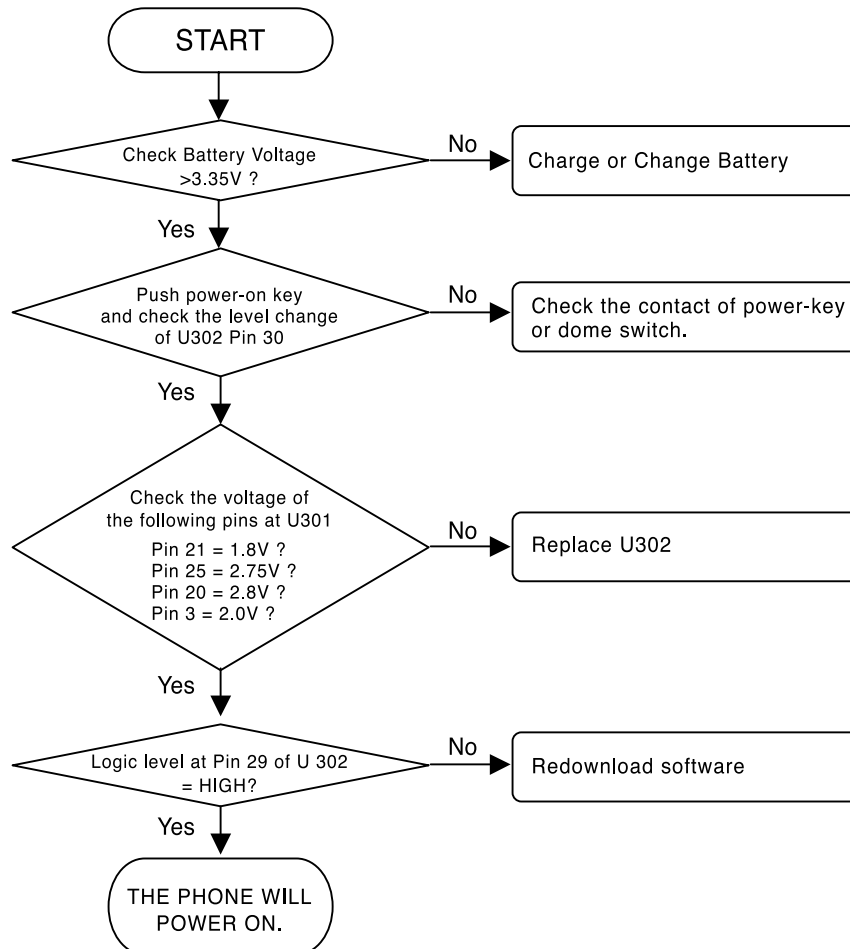


Figure 4-16

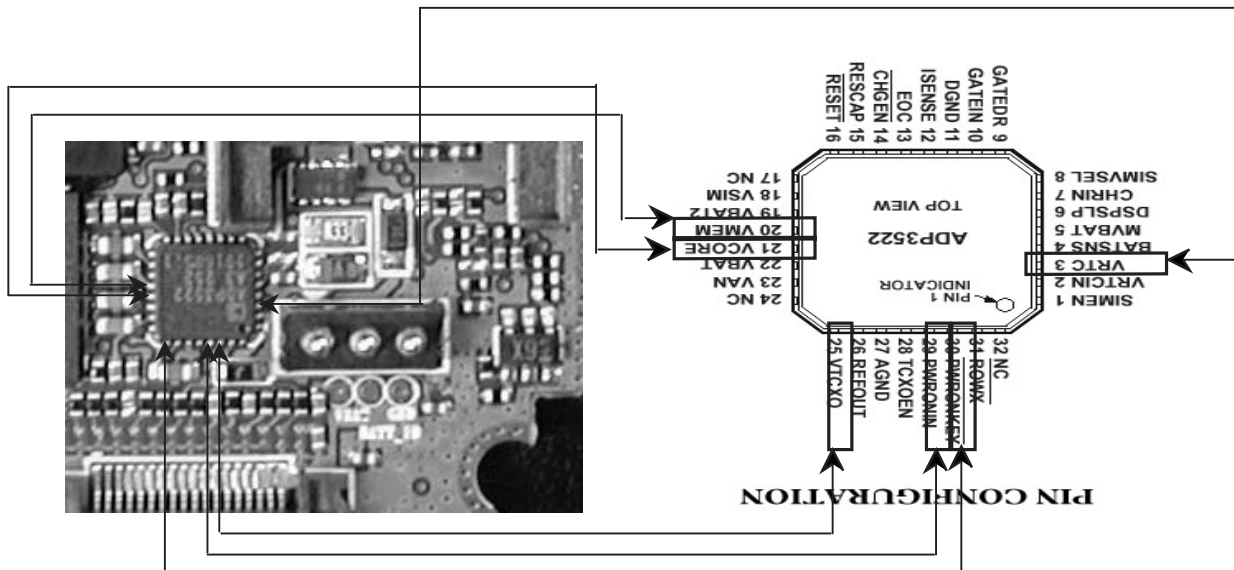
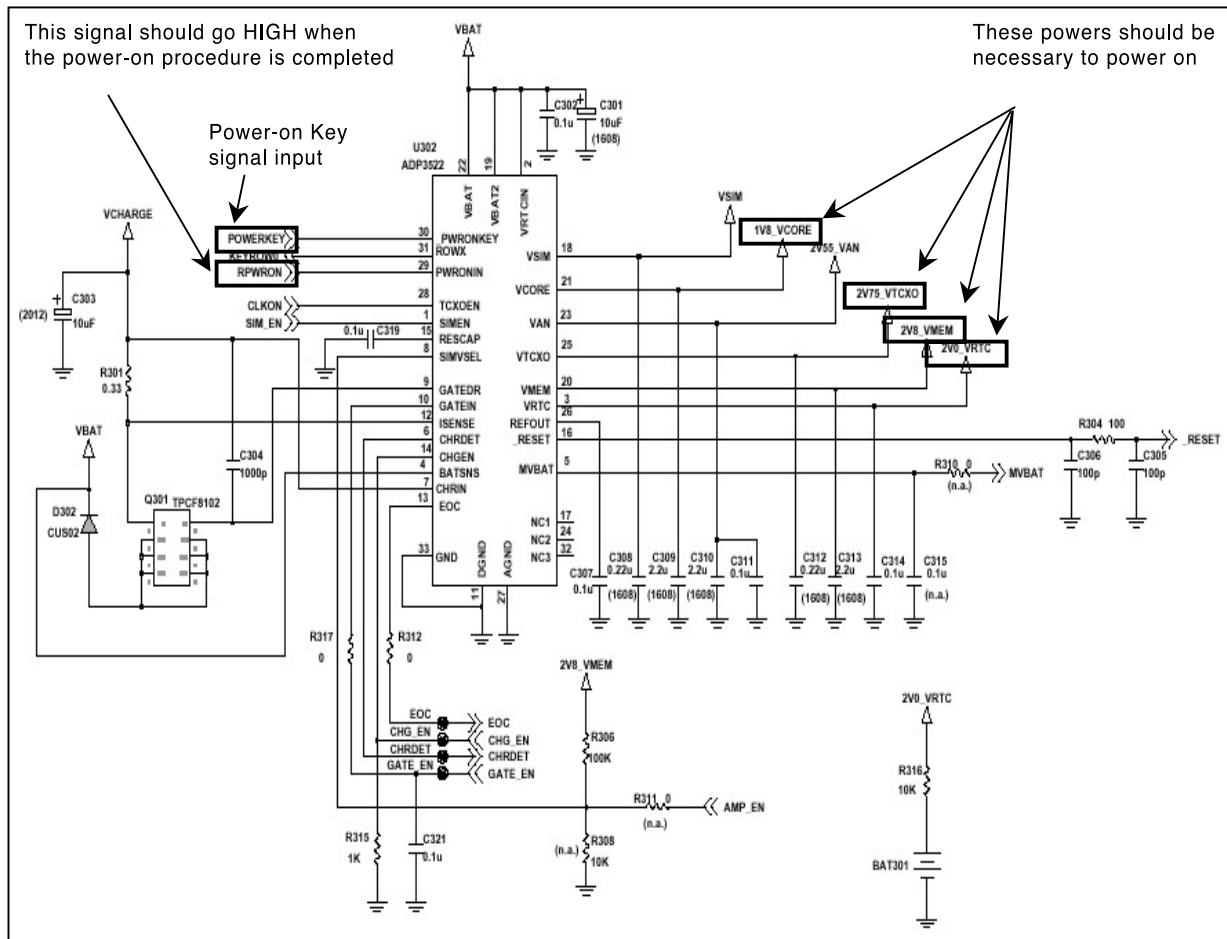
4.4 Power On Trouble

SETTING : Connect PIF, and set remote switch off at PIF.



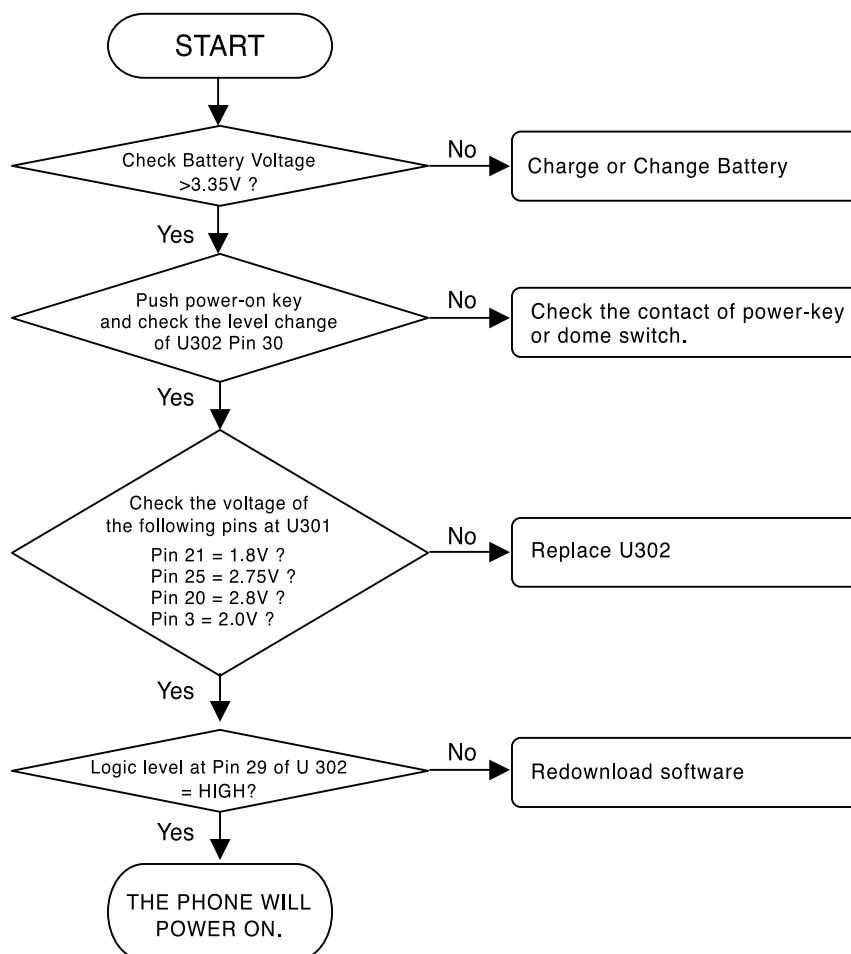
4. TROUBLE SHOOTING

◆ Test) Check U302(ADP3522)



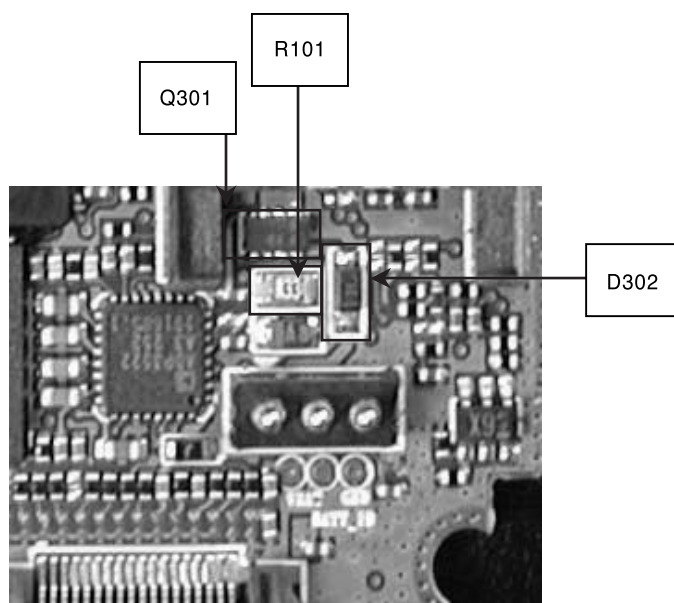
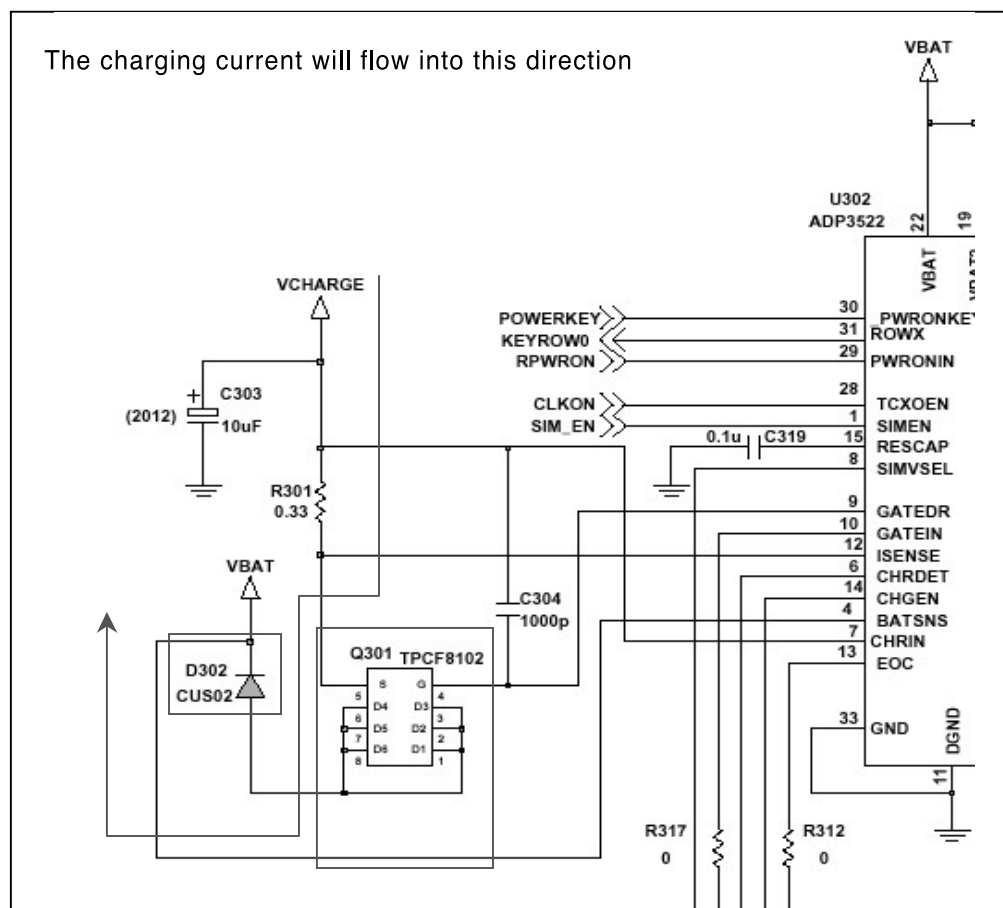
4.5 Charging Trouble

SETTING : Connect PIF, and set remote swit ch off at PIF.

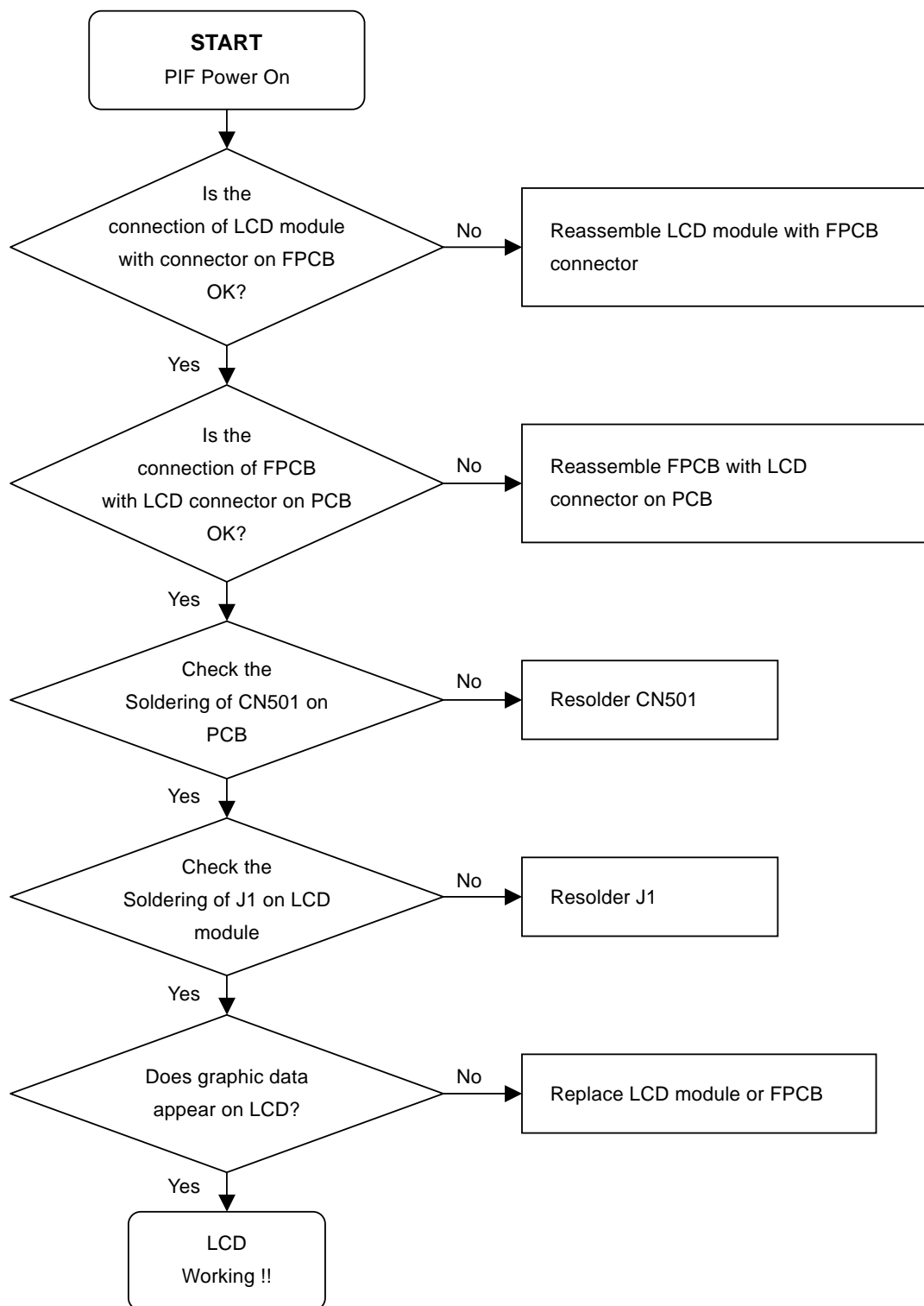


4. TROUBLE SHOOTING

◆ Test) Check R301, Q301, D302

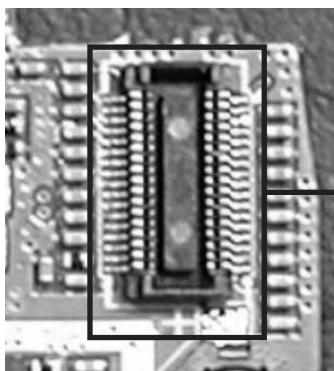


4.6 LCD Trouble

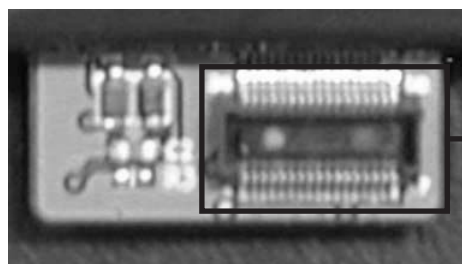


4. TROUBLE SHOOTING

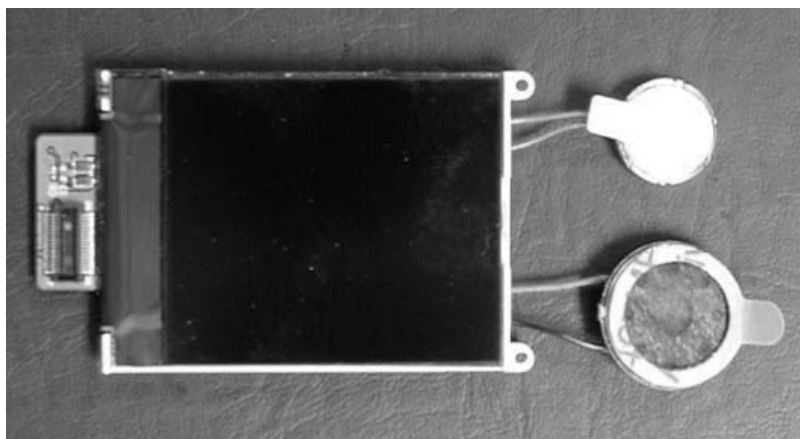
◆ Test) CN501 & J1 Check !!



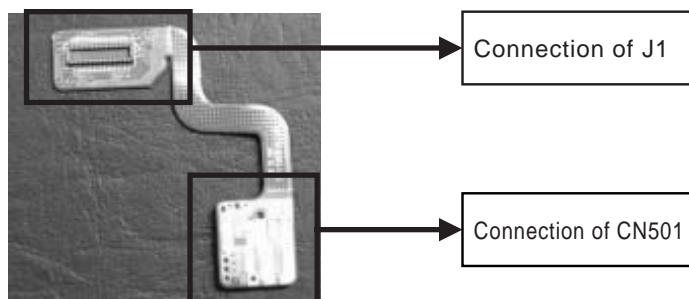
LCD connector on PCB



LCD connector on LCD PCB

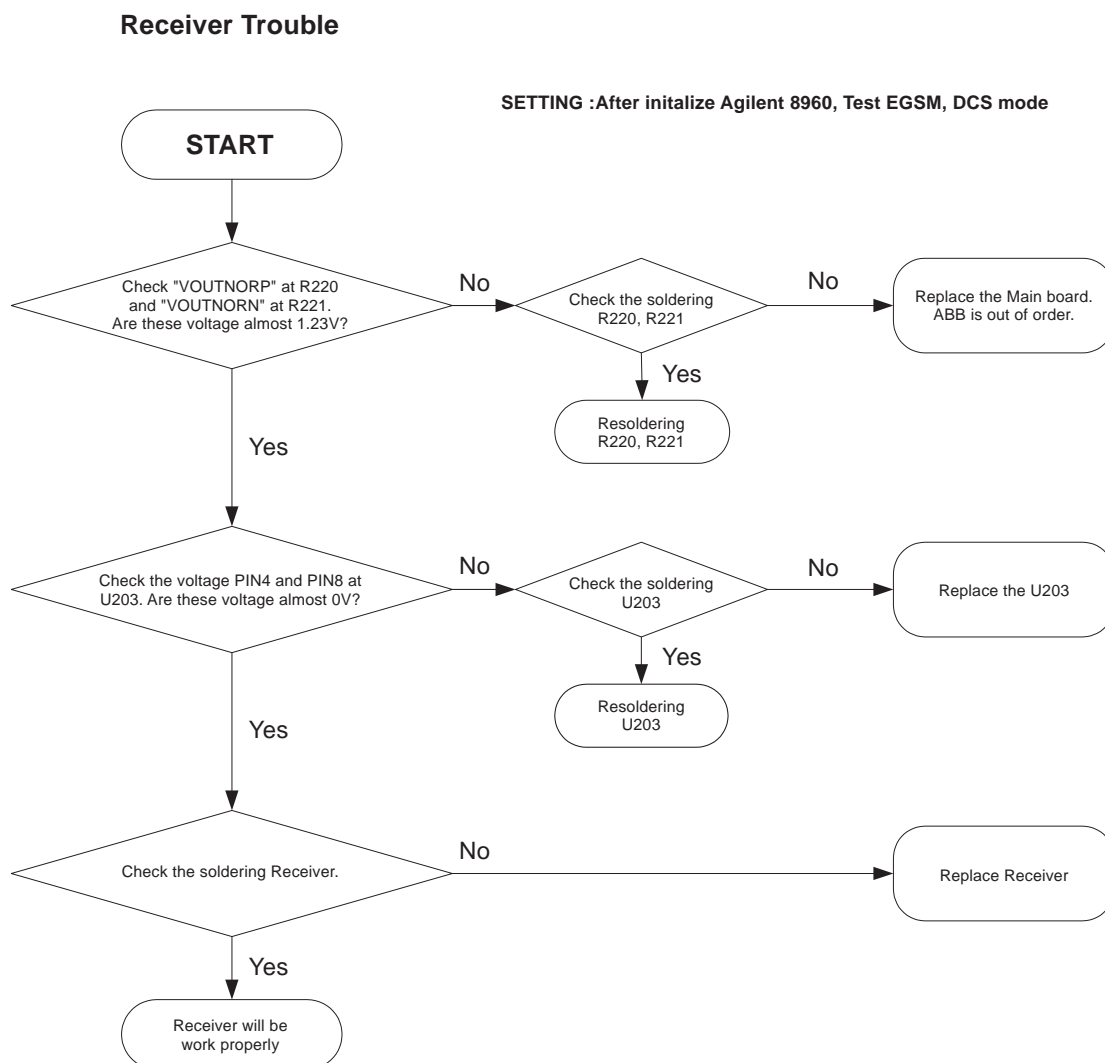


LCD module



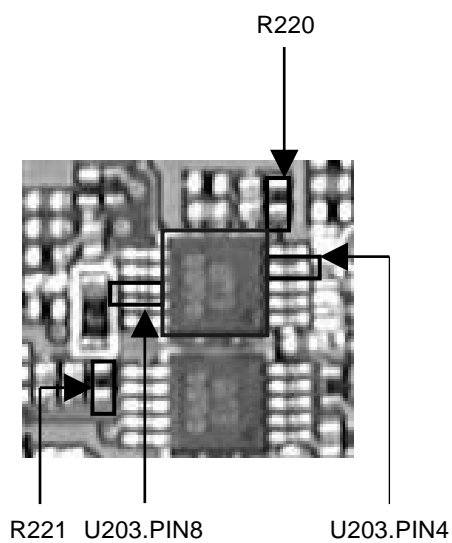
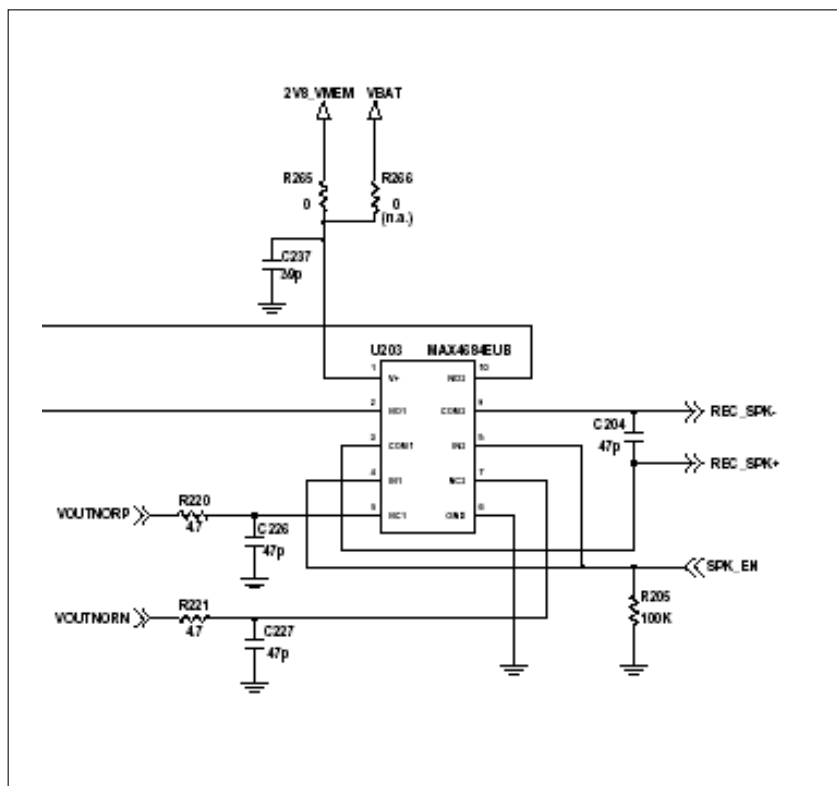
FPCB Ass y

4.7 Receiver Trouble

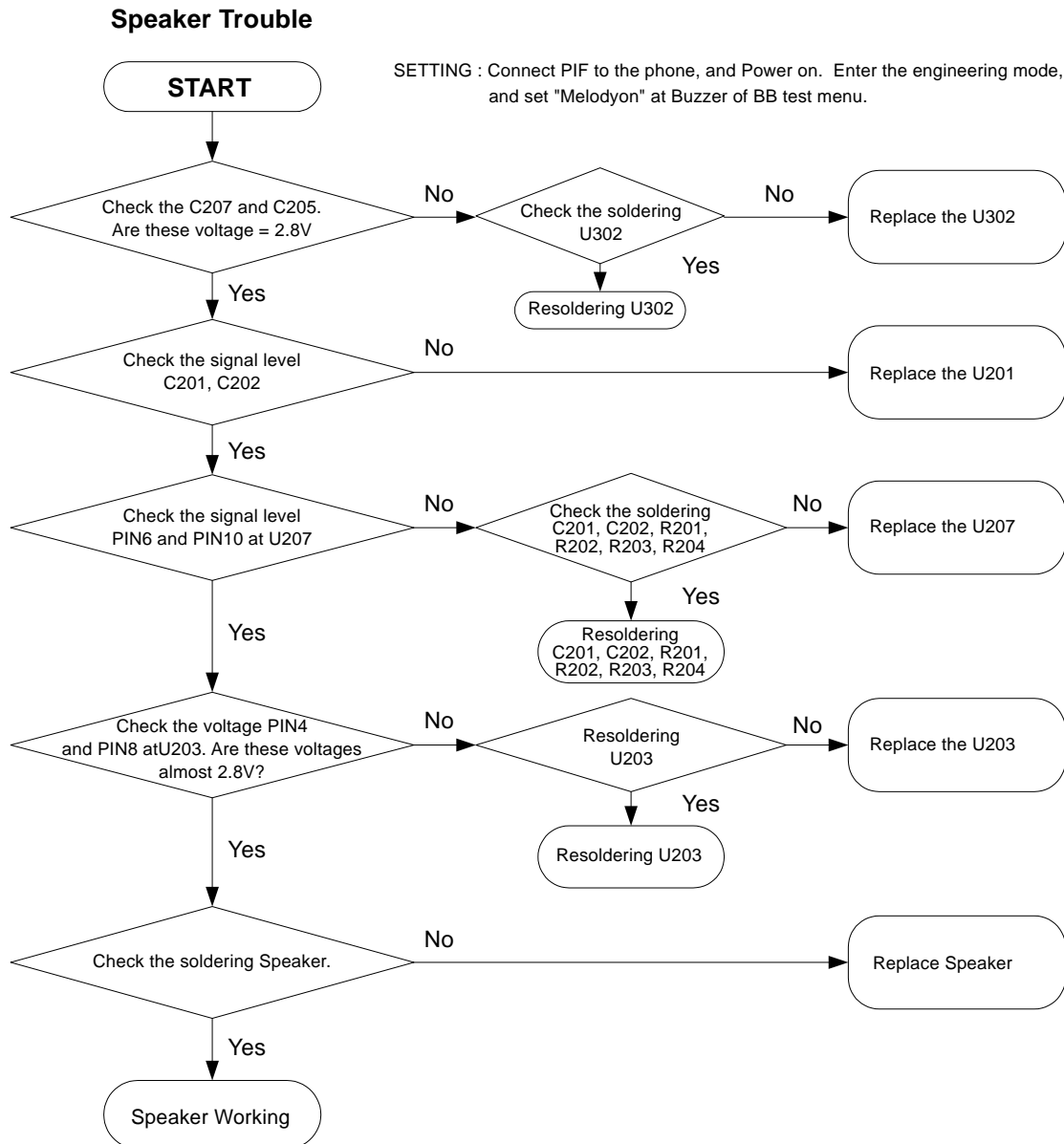


4. TROUBLE SHOOTING

◆ The Receiver part Circuit Diagram

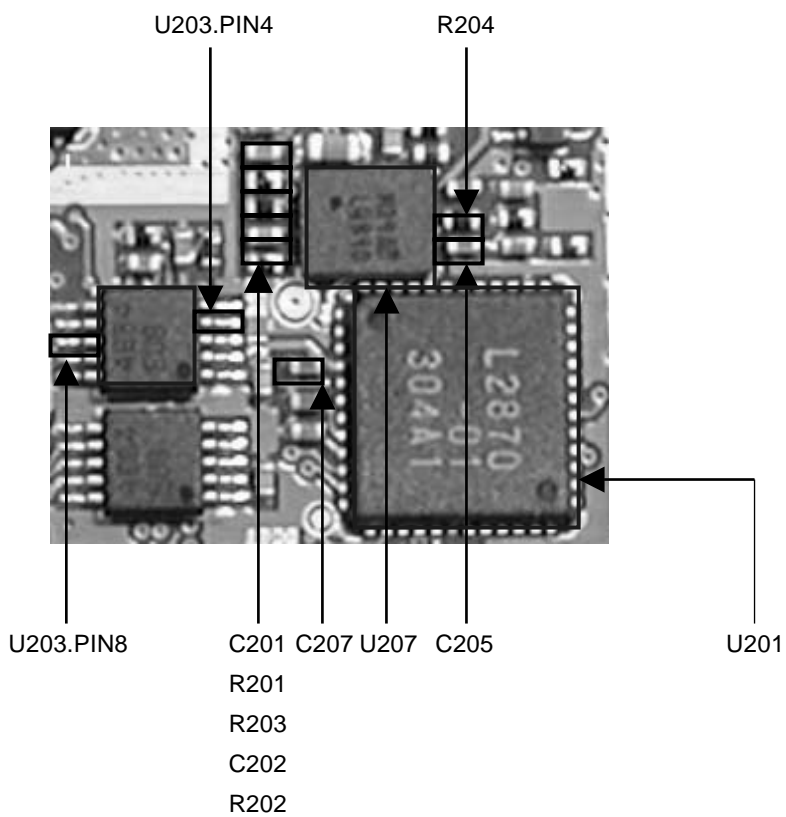
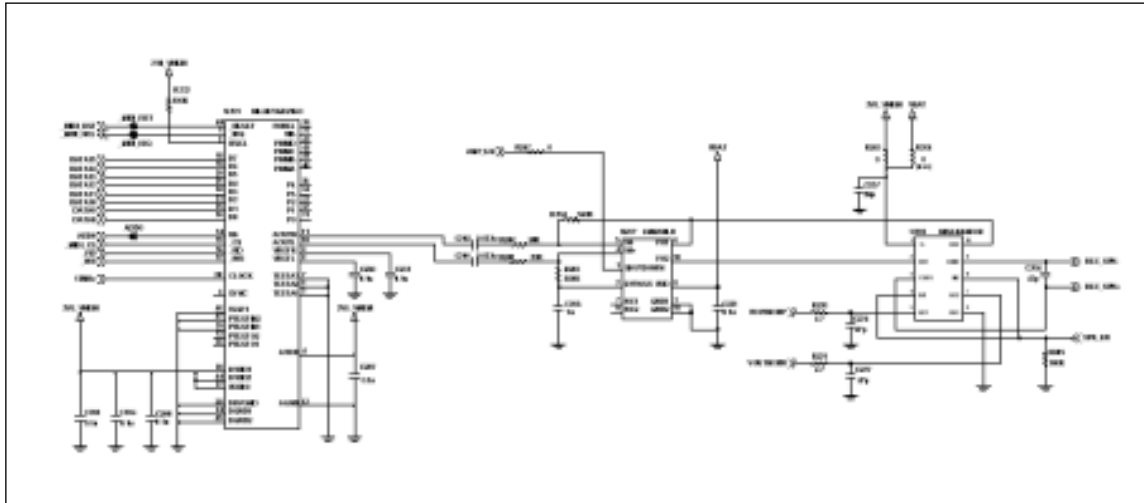


4.8 Speaker Trouble

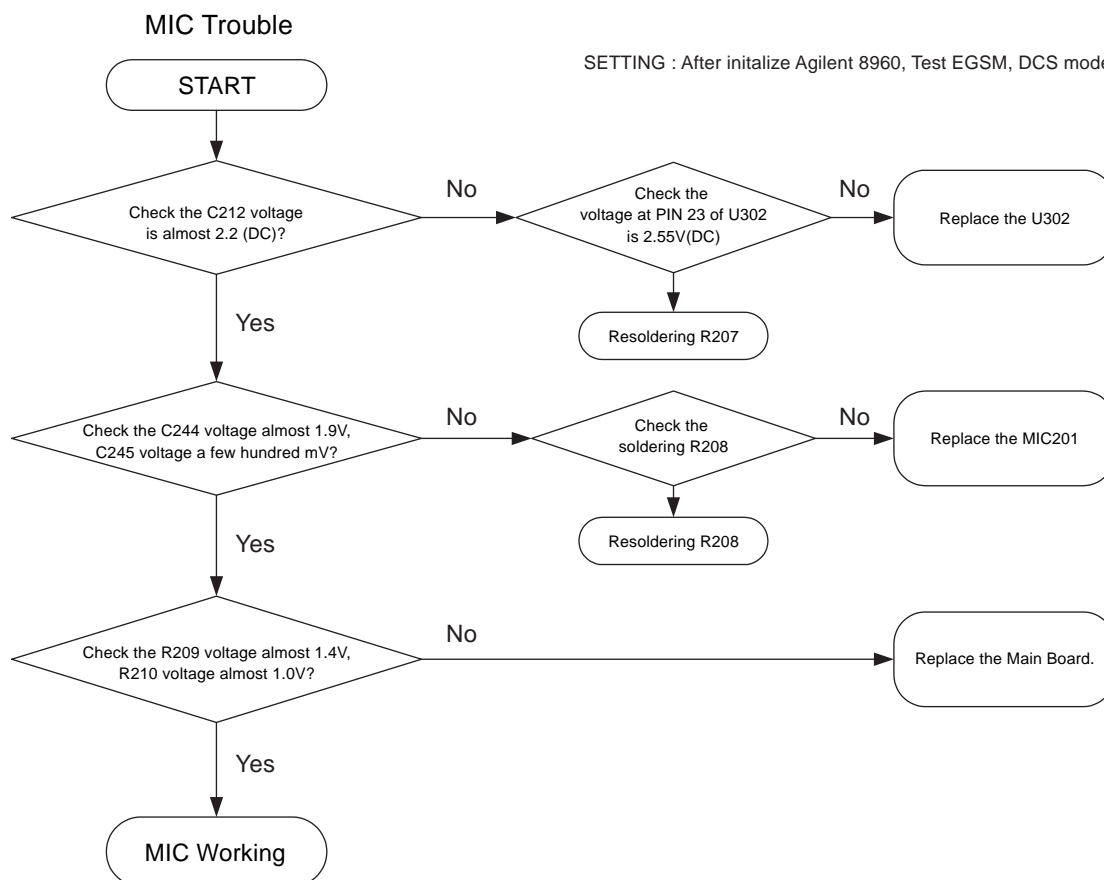


4. TROUBLE SHOOTING

◆ Speaker part Circuit Diagram

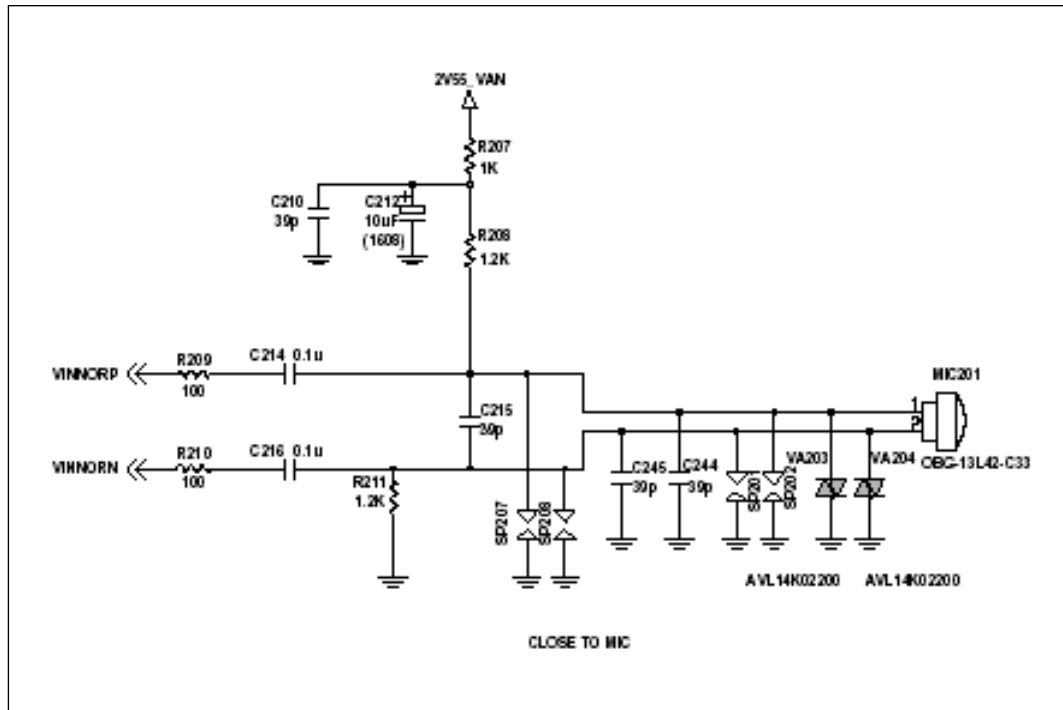


4.9 MIC Trouble



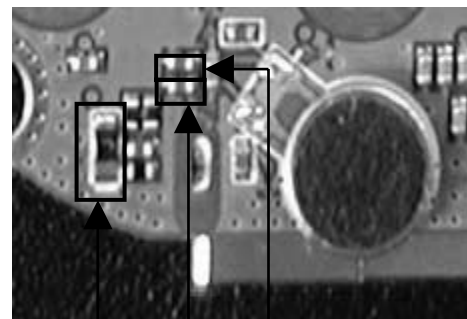
4. TROUBLE SHOOTING

◆ MIC Circuit Diagram



R210

R209



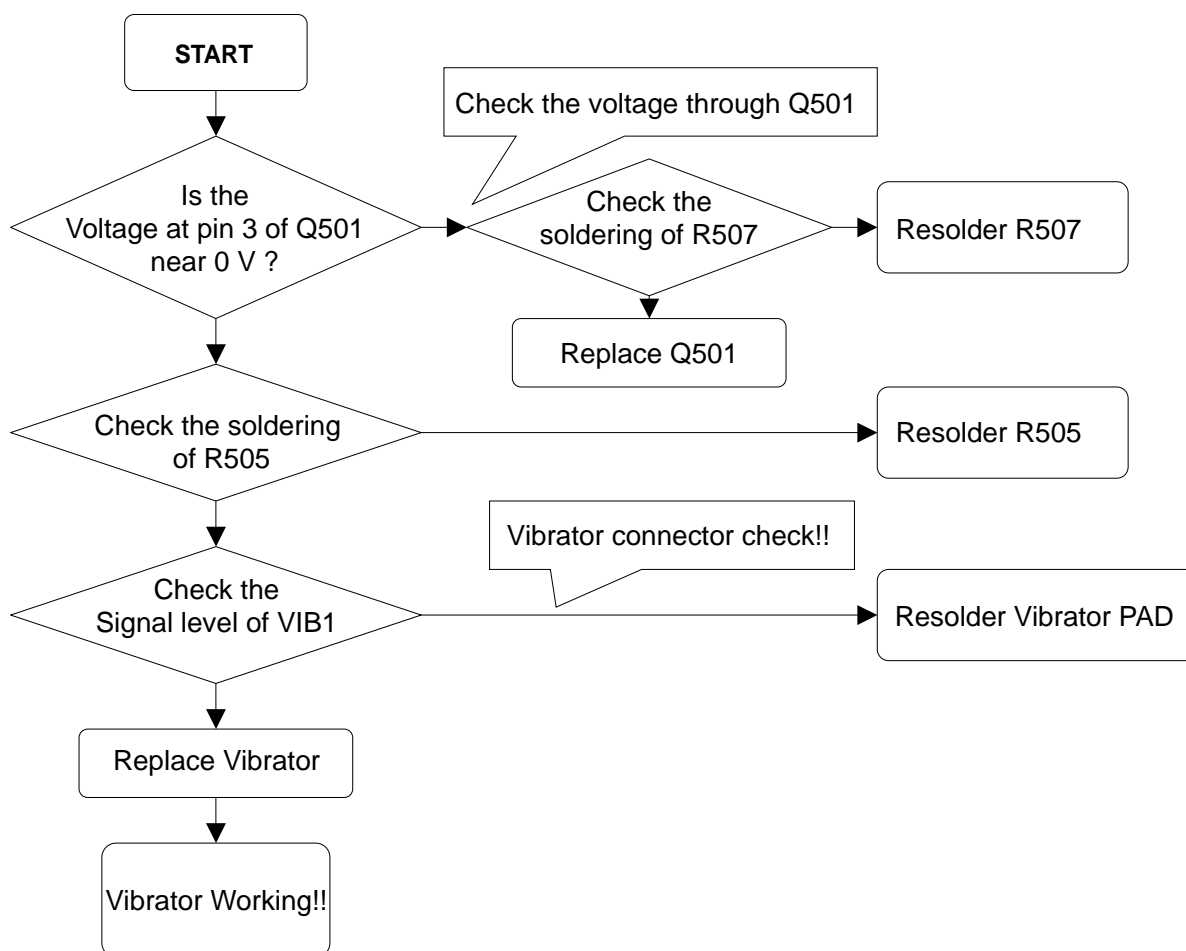
C212

C244

C245

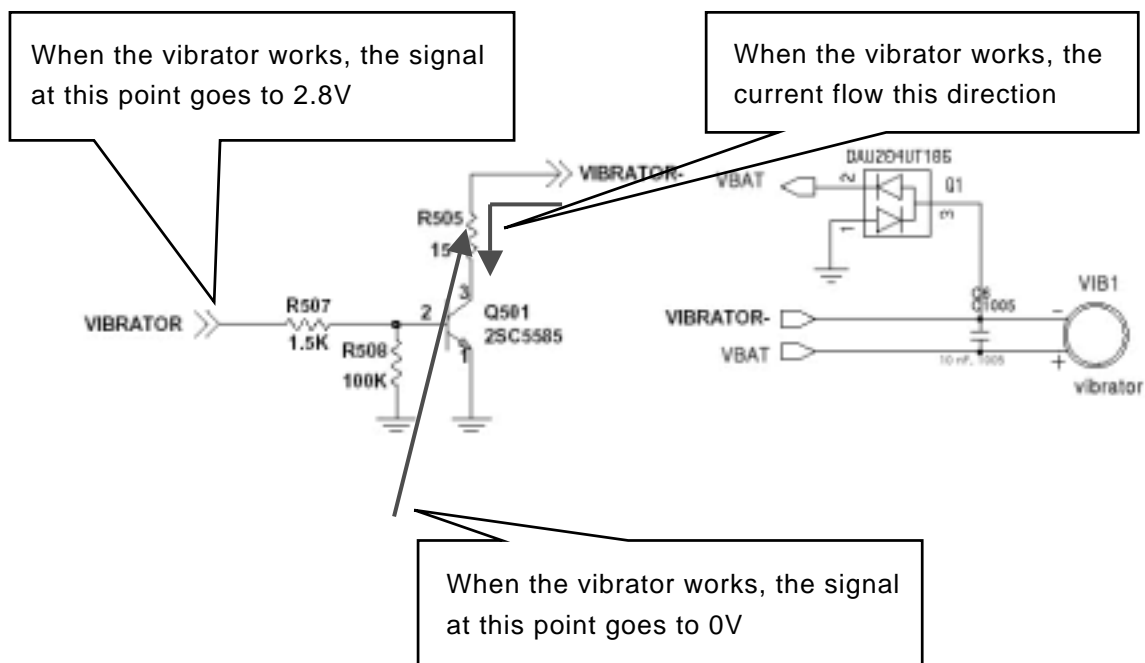
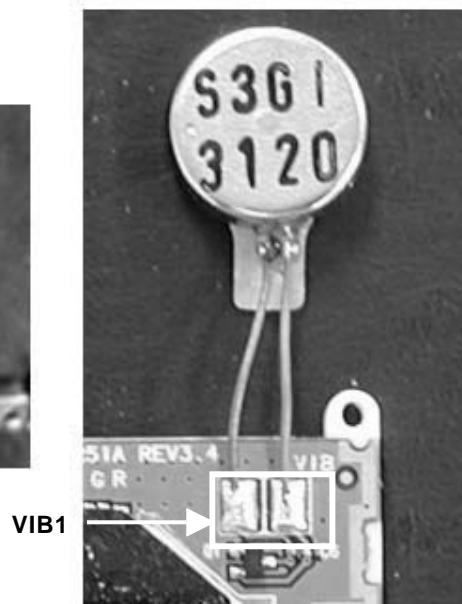
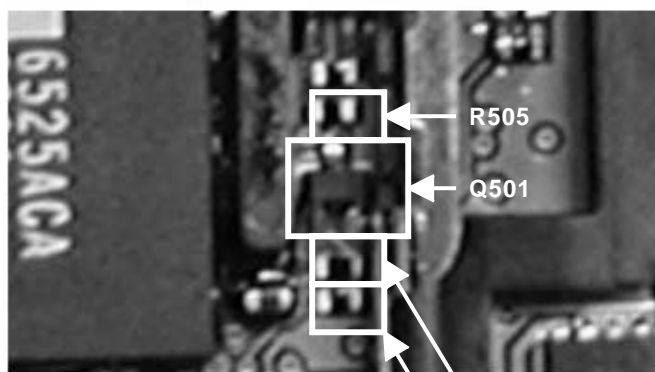
4.10 Vibrator Trouble

SETTING : After Initialize Agilent 8960, Test in EG SM, Connect PIF to the phone, and Power on.
Enter The engineering mode, and set Vibrator on at Vibration of BB test menu.



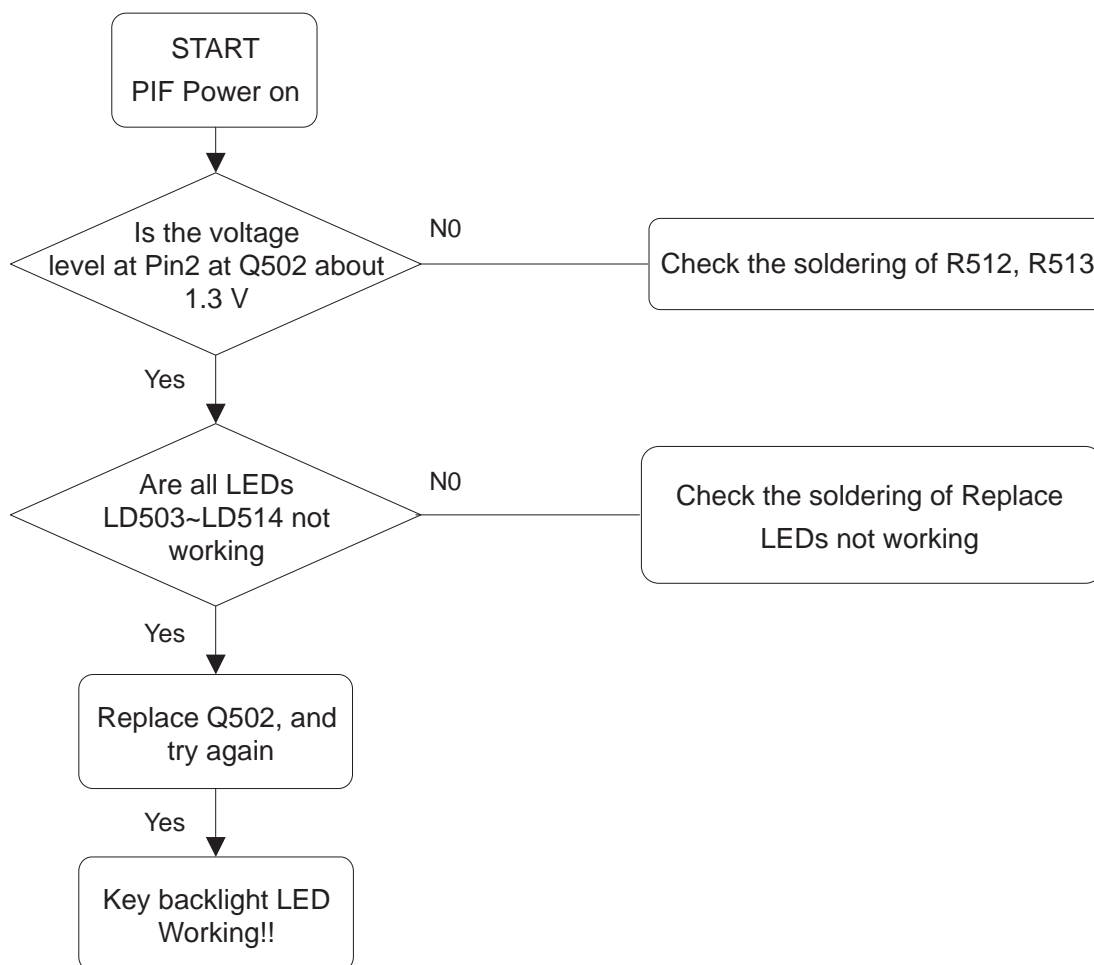
4. TROUBLE SHOOTING

◆ Test) Q501,R505,R507,R508 and Vibrator Check !!



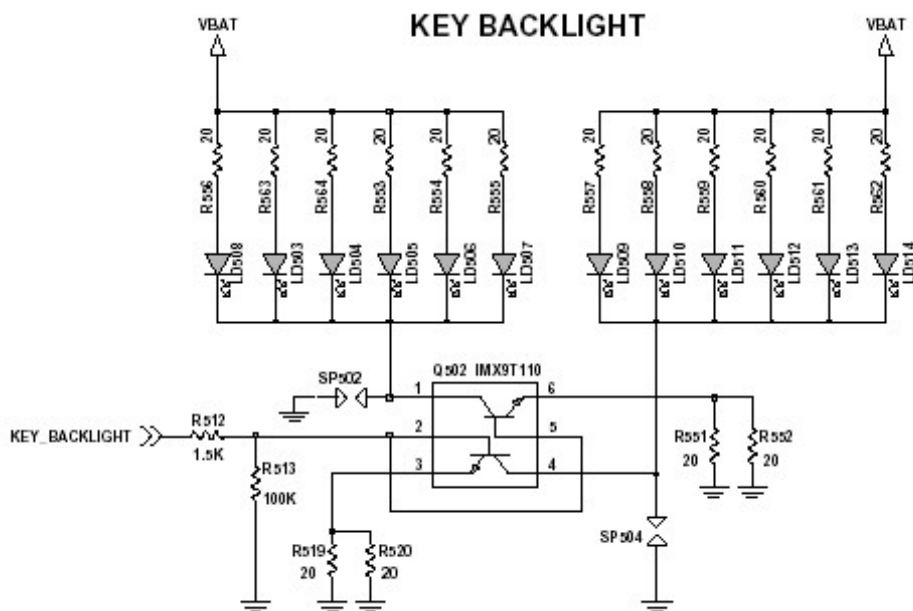
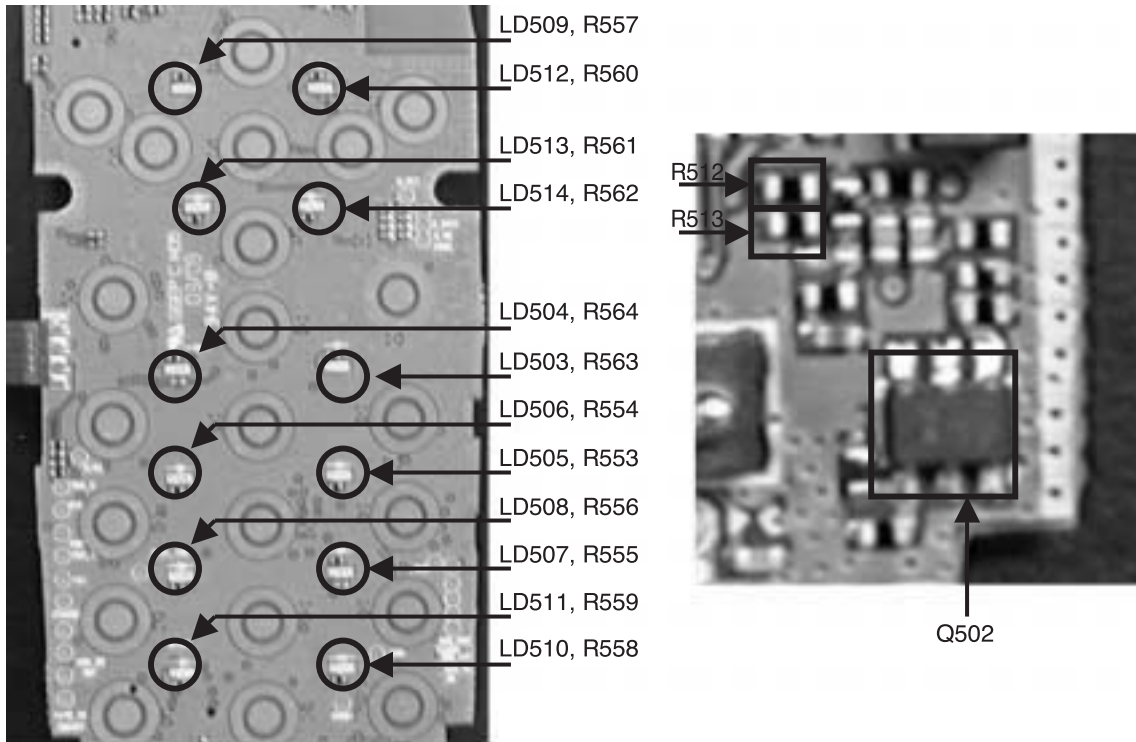
4.11 Key Backlight LED Trouble

SETTING : Connect PIF to the phone, and power on, Enter engineering mode, and set Backlight on at Backlight of BB test menu.

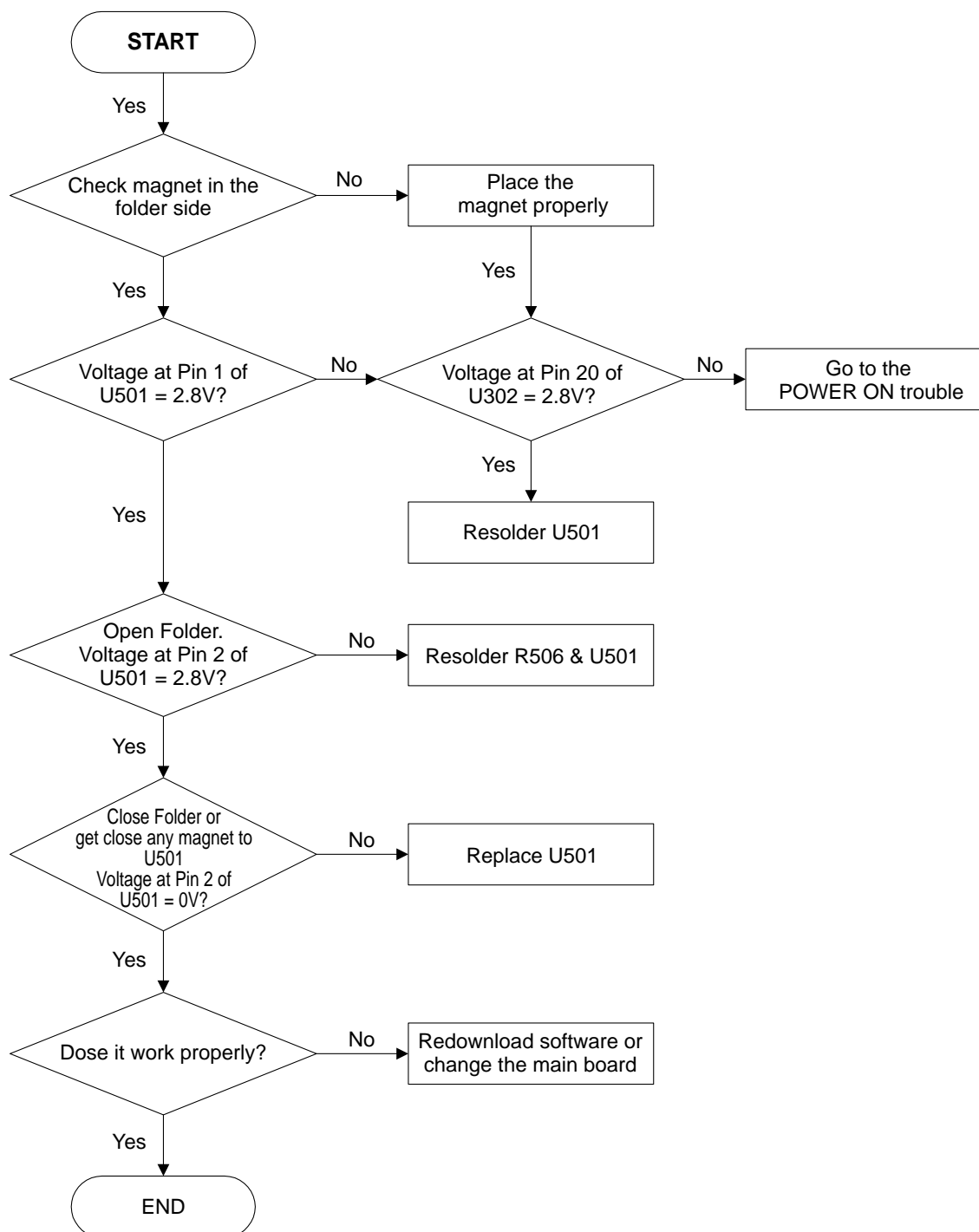


4. TROUBLE SHOOTING

◆ Test) Q502, R512, R513 and LD503 ~LD514 Check !!

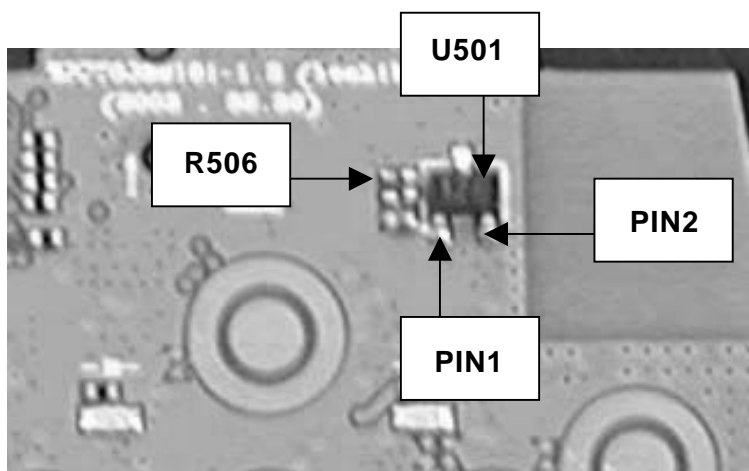


4.12 Folder on/off Trouble

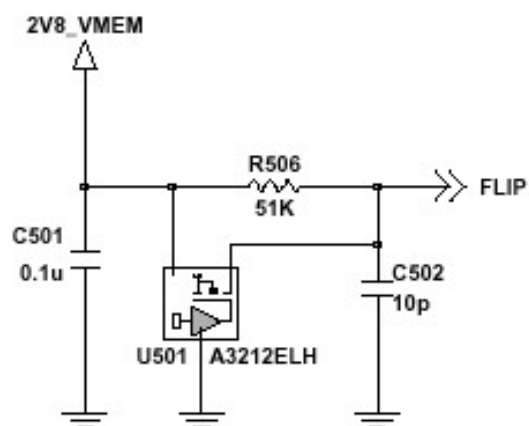


4. TROUBLE SHOOTING

◆ FLIP SWITCH

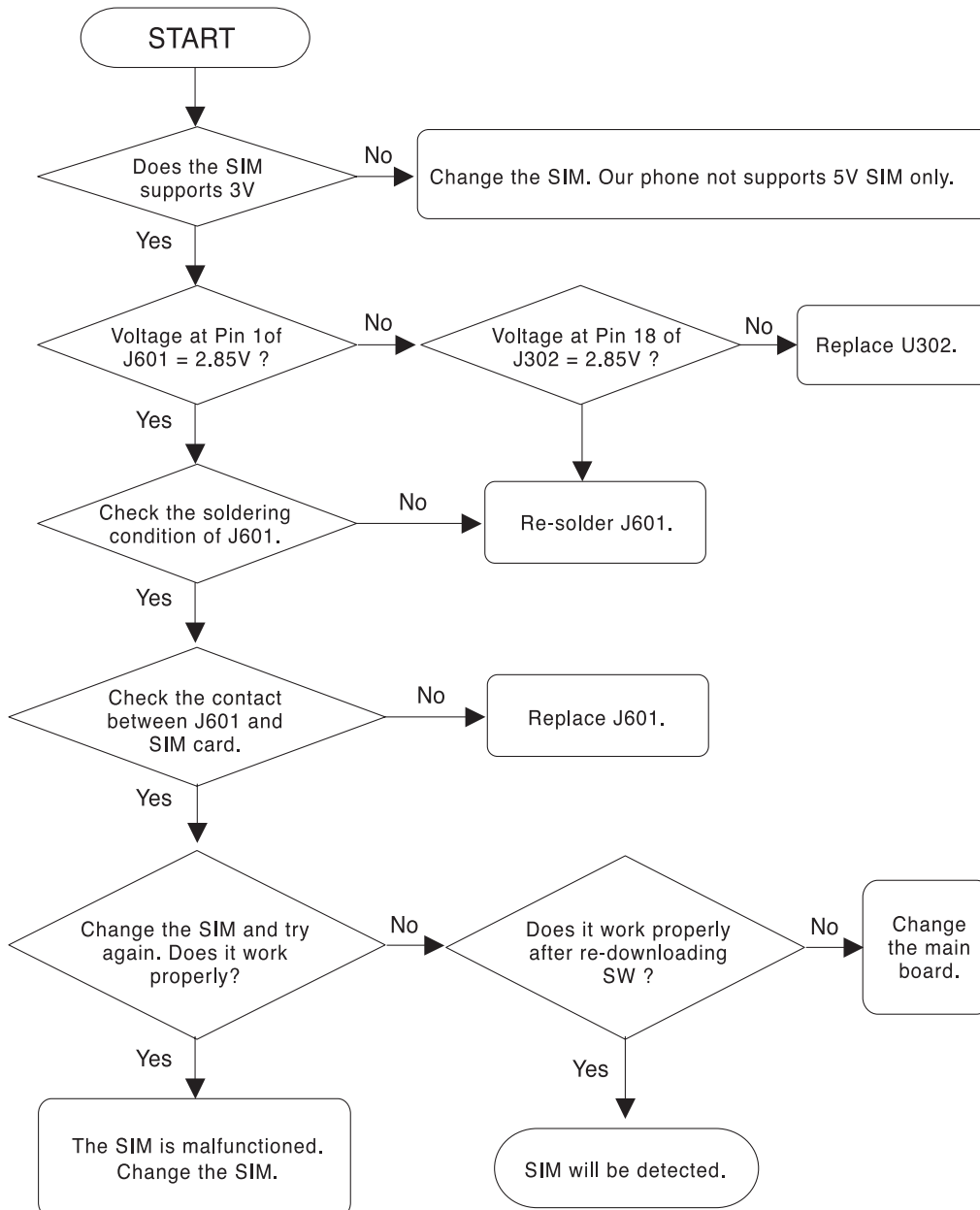


FLIP SWITCH



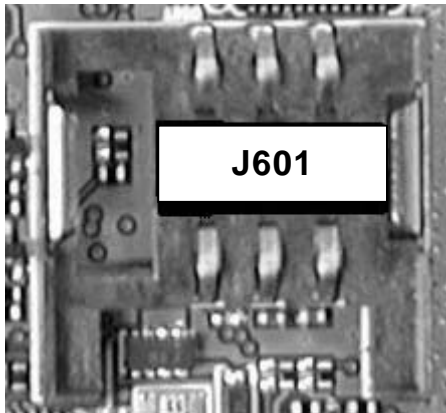
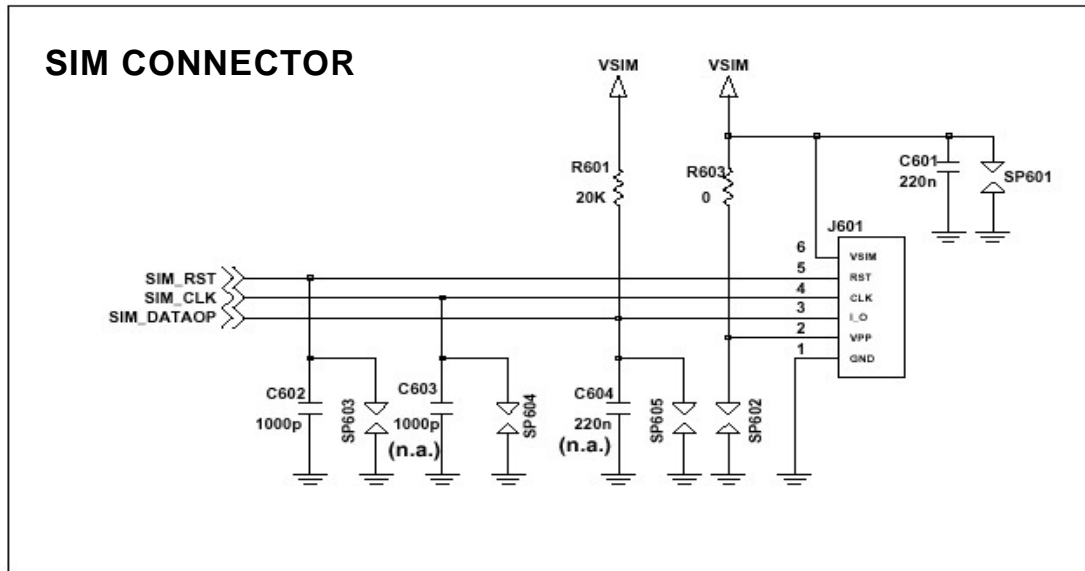
4.13 SIM Detect Trouble

SETTING : Insert the SIM into J301. Connect PIF to the phone, and power on.

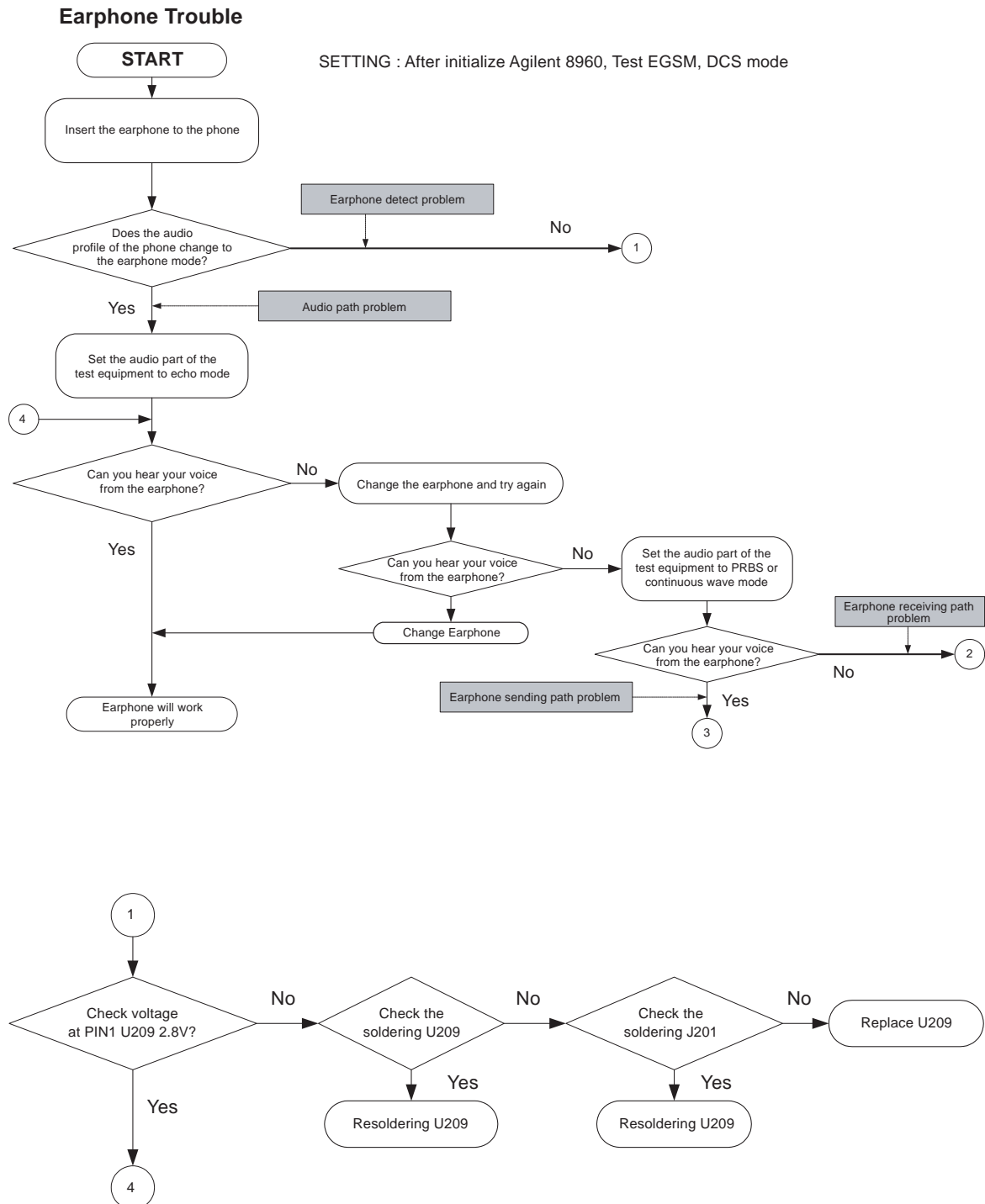


4. TROUBLE SHOOTING

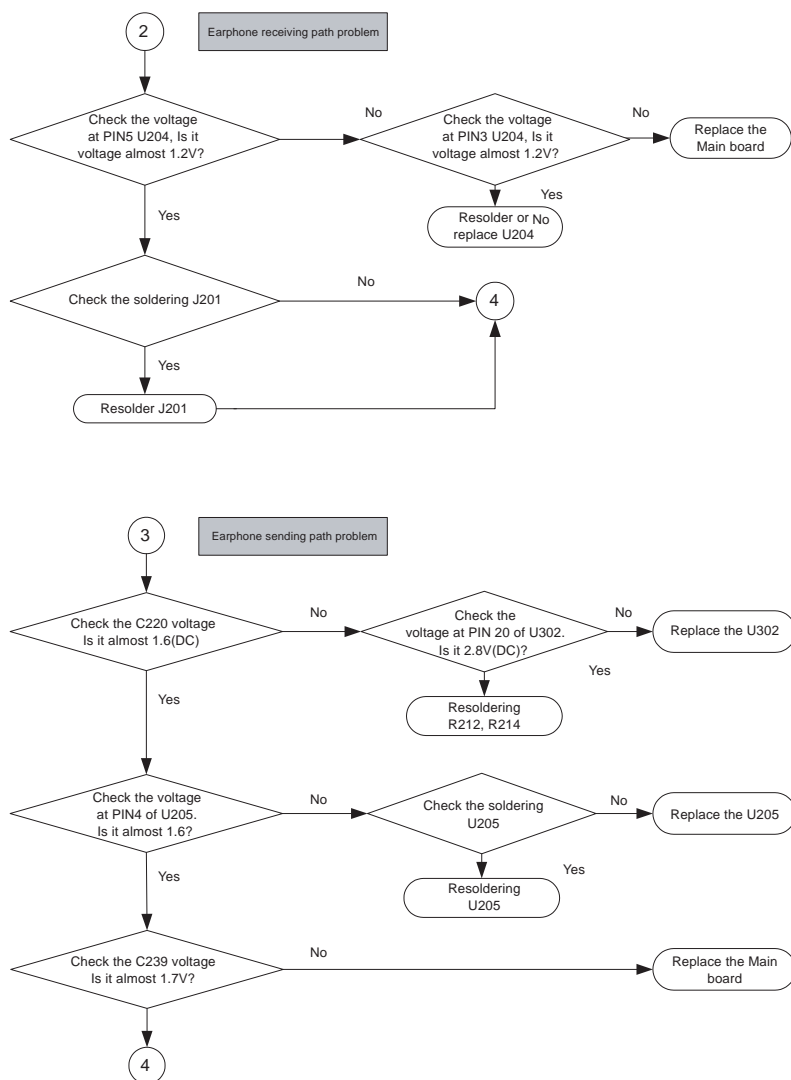
◆ Test) Check SIM Connector



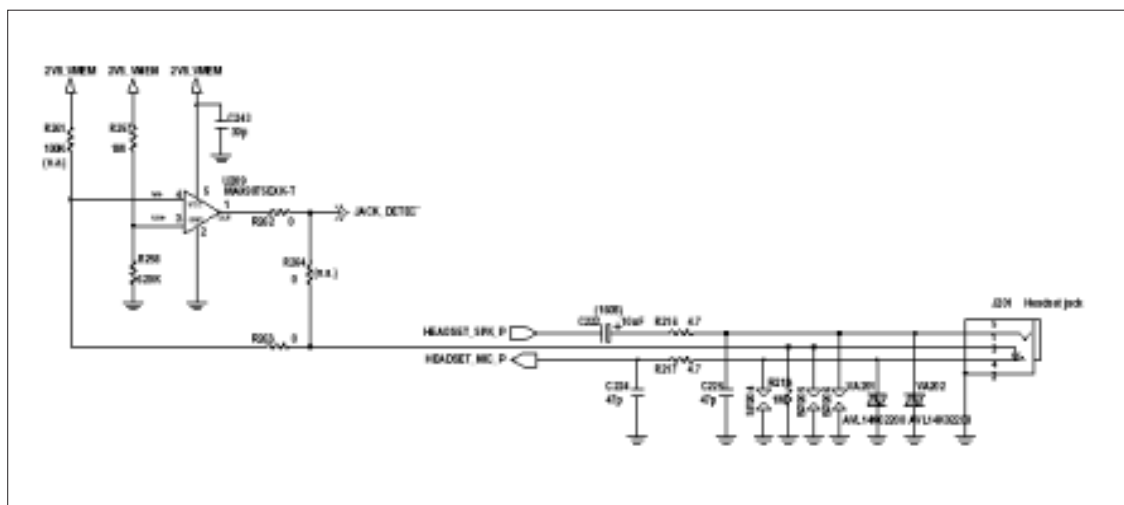
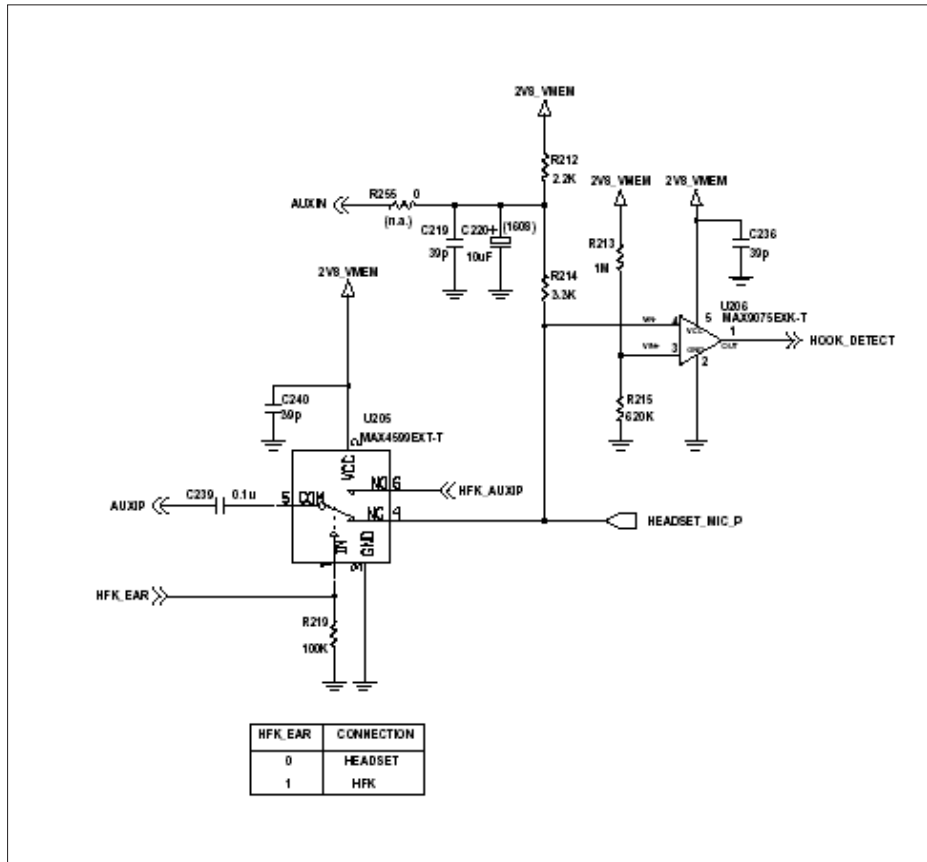
4.14 Earphone Trouble



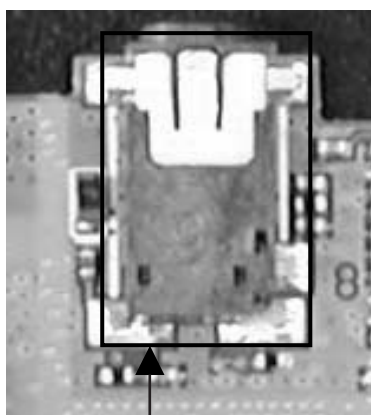
4. TROUBLE SHOOTING



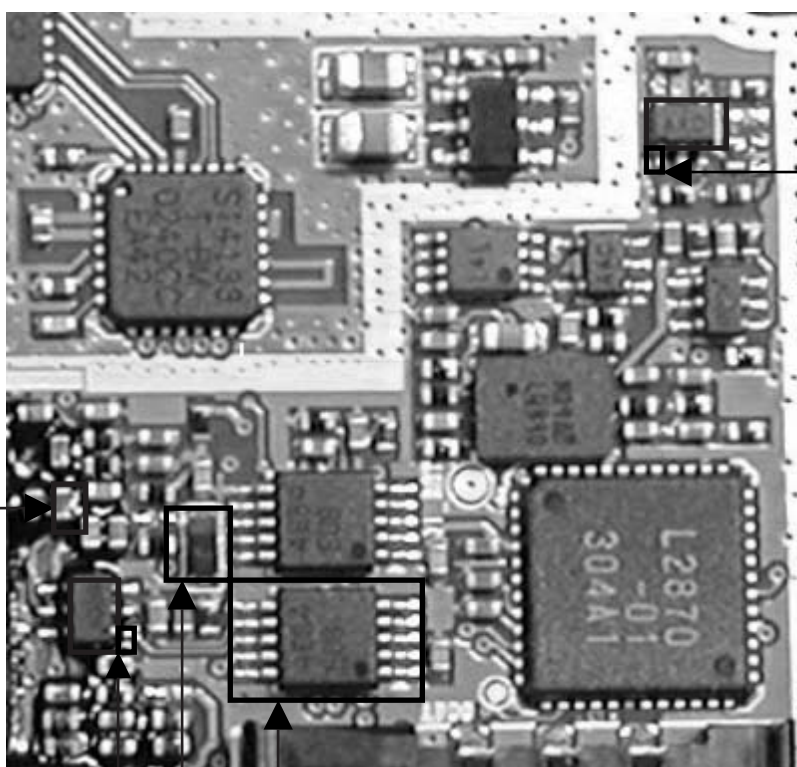
◆ Earphone part Circuit Diagram



4. TROUBLE SHOOTING



J201



C239

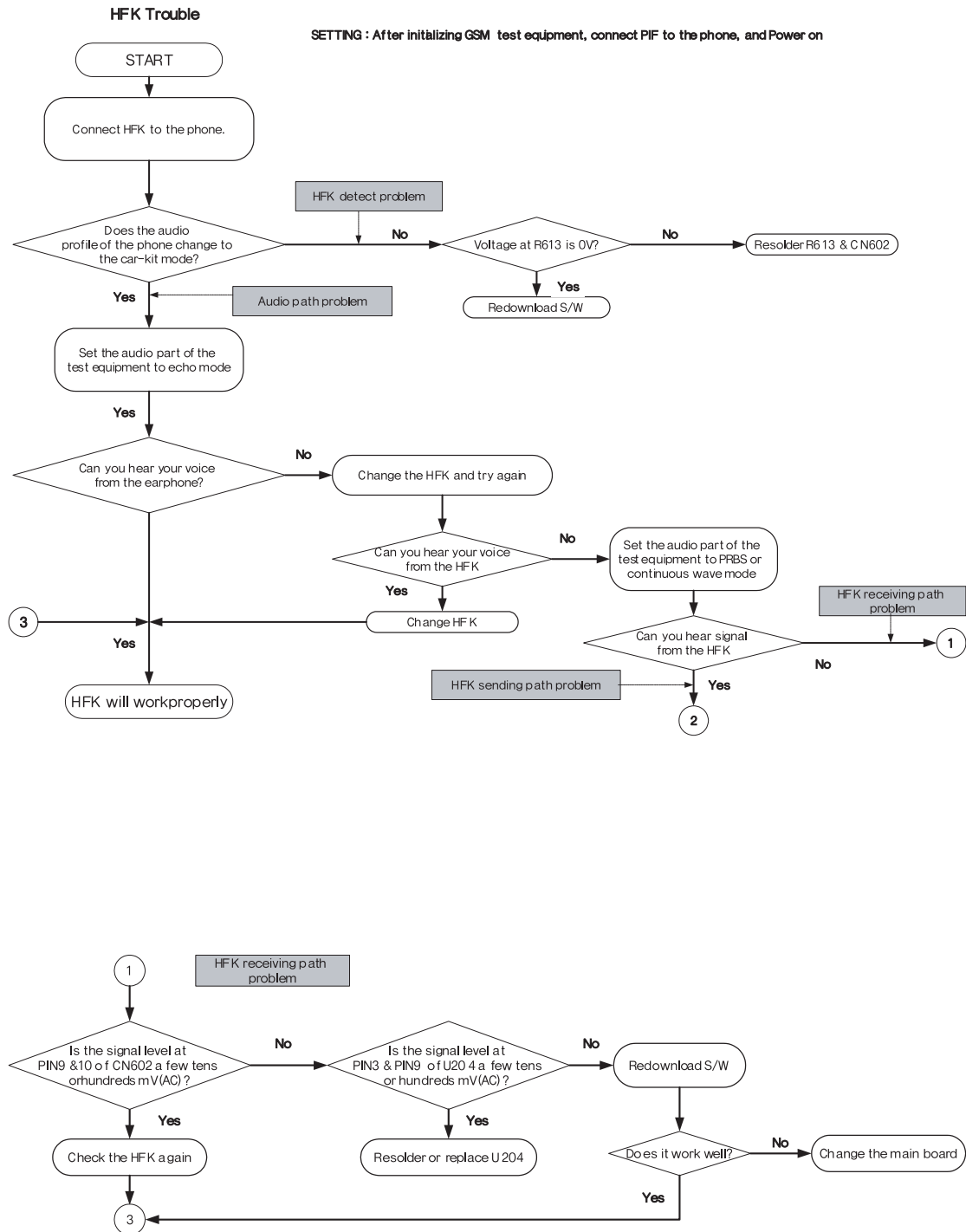
C220

U204

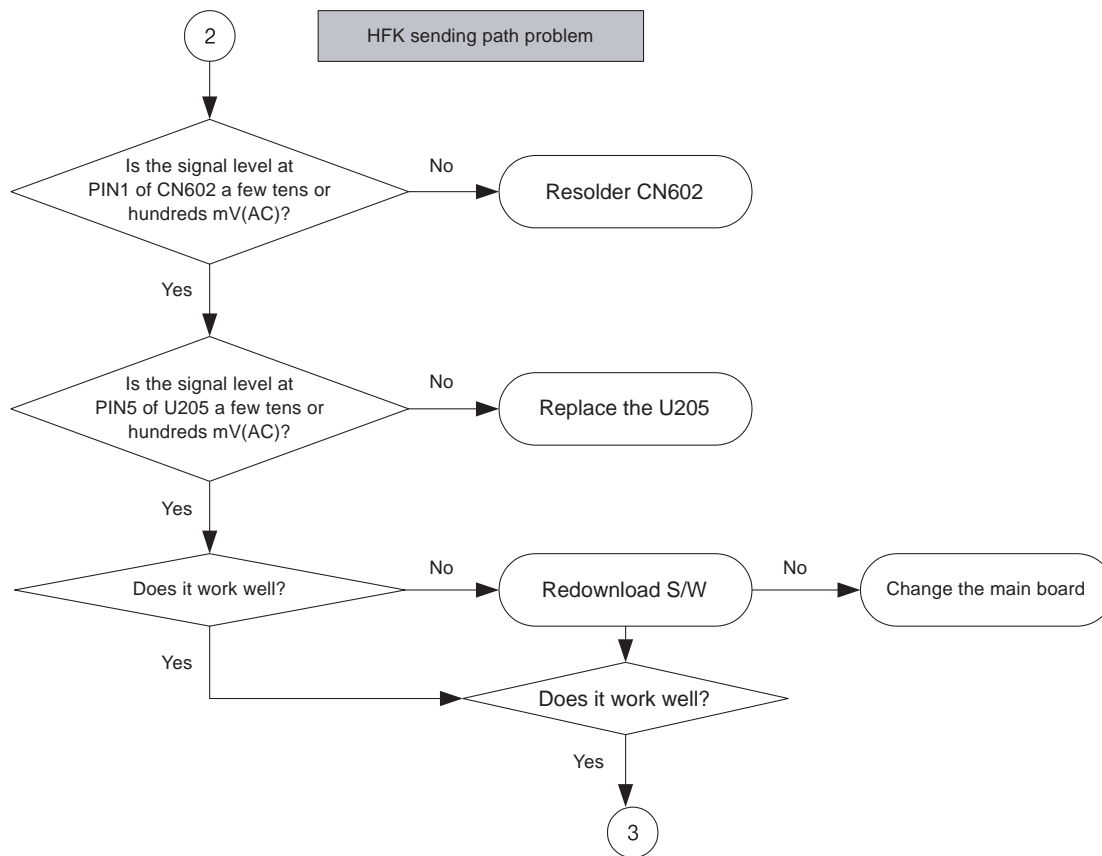
U209.PIN1

U205.PIN1

4.15 HFK Trouble



4. TROUBLE SHOOTING





5. DISASSEMBLY INSTRUCTION

5.1 Disassembly

1. Remove the battery, screws as shown above.

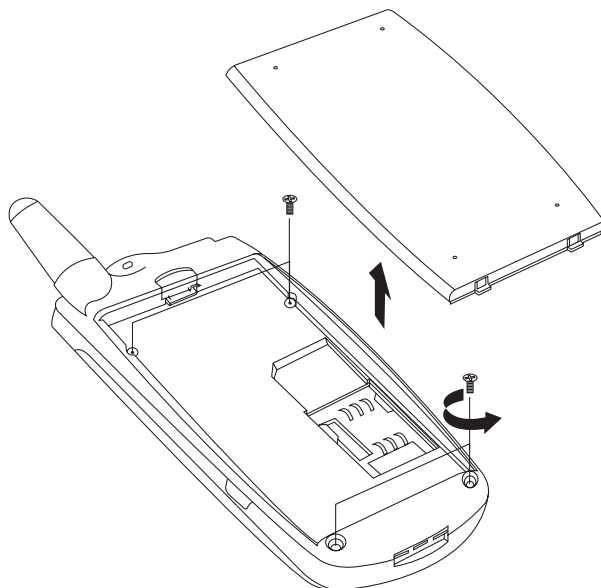


Figure 5-1. Removing battery pack, screws and antenna

2. Carefully lift up the bottom of rear cover first, then hold the covers and twist them.

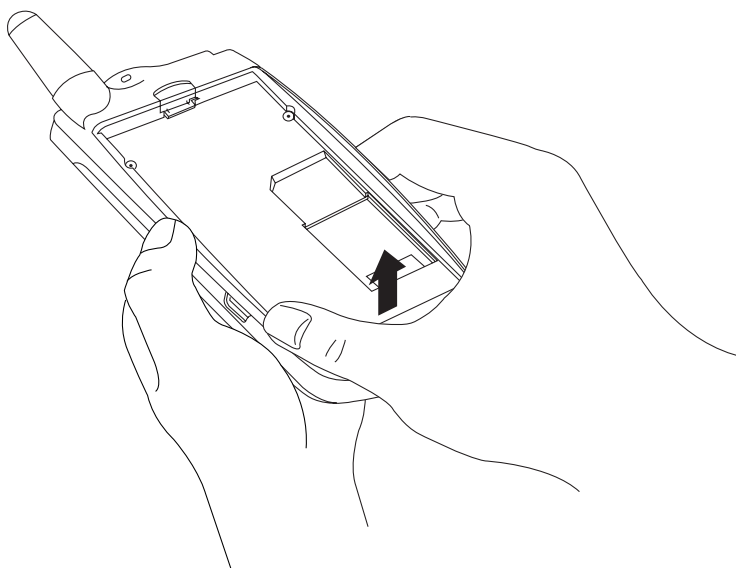


Figure 5-2. Disassembly of rear cover and front cover

5. DISASSEMBLY INSTRUCTION

3. Finally carefully remove the rear-cover from the hooks on the top of front-cover.

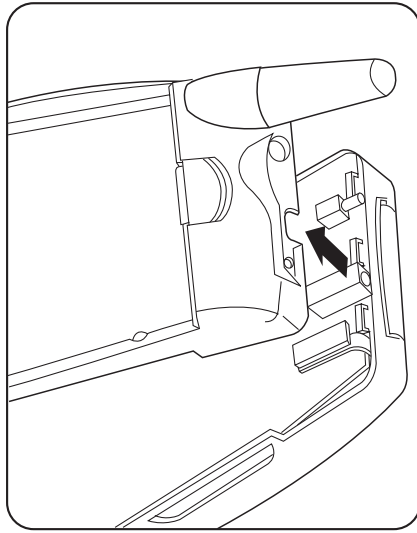


Figure 5-3. Disassembly from the hooks

4. Remove the pin shown below to unlock the PCB.

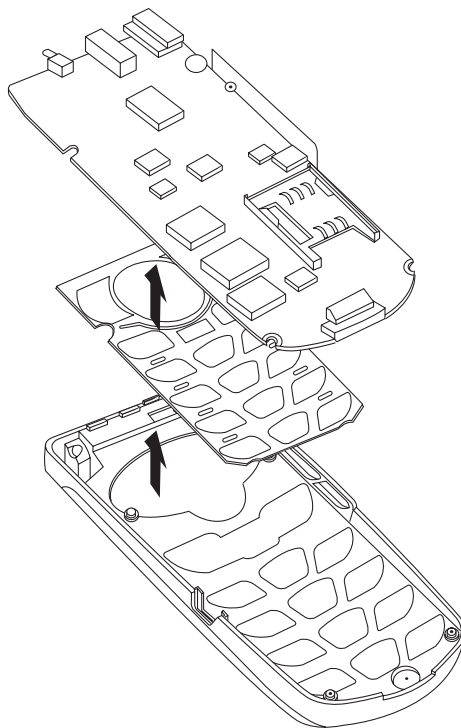
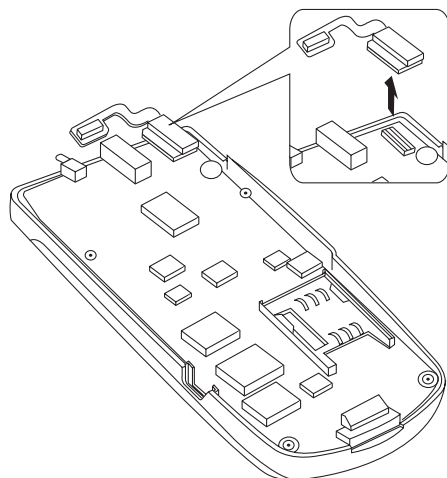


Figure 5-4. Removing battery pack, screws and antenna

5. DISASSEMBLY INSTRUCTION

5. Use a tweezers to remove the battery locker

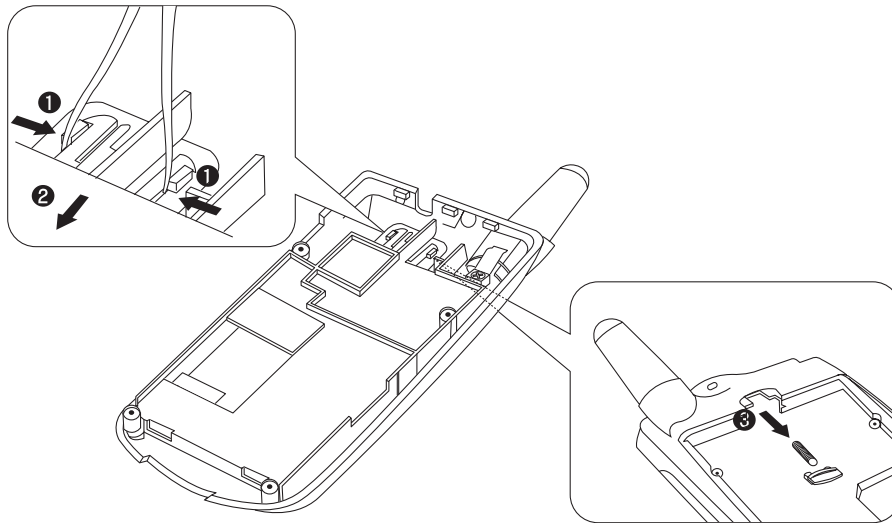


Figure 5-5. Removing battery locker

6. Remove the side keys

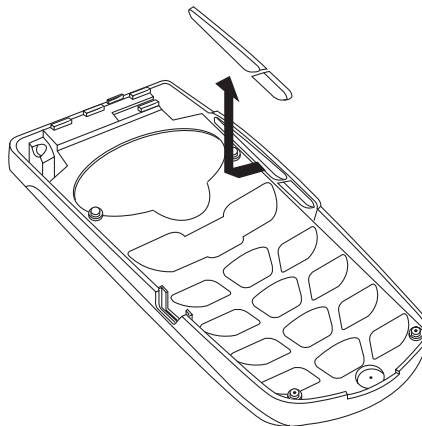


Figure 5-6. Removing side keys

7. Push away the hinge to remove the folder.

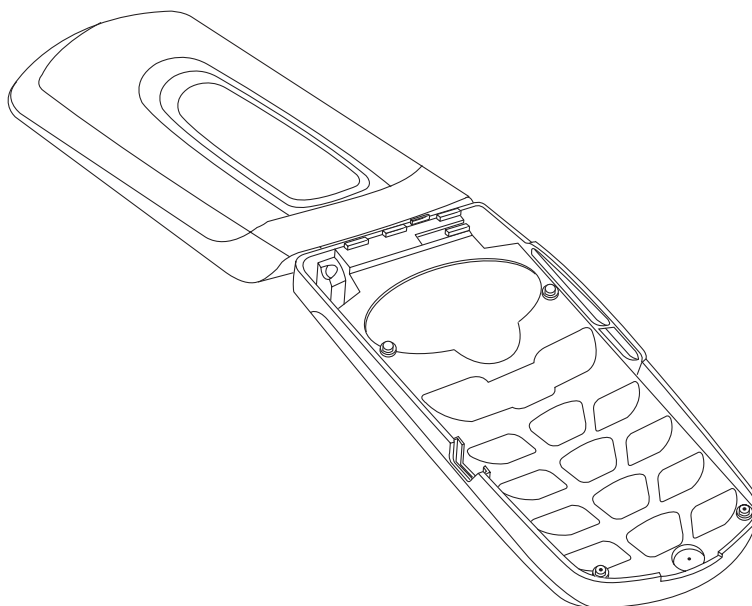


Figure 5-7. Detaching folder

8. Remove a hinge from the folder. Then detach screw caps and screws.

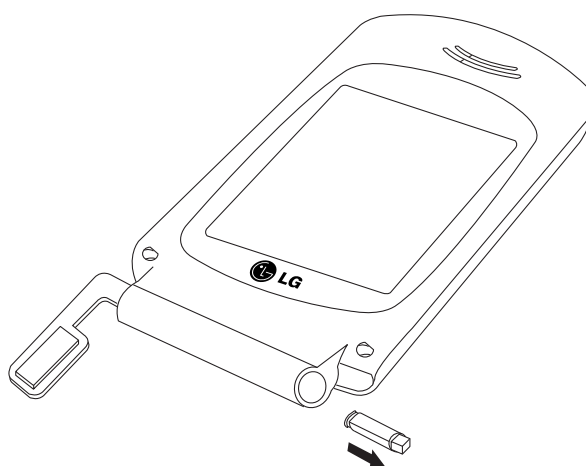


Figure 5-8. Removing hinge and screws.

5. DISASSEMBLY INSTRUCTION

9. Place the folder on a desk. Then hold the hinge and push it down carefully. Finally, detach it from the rest hooks shown above.

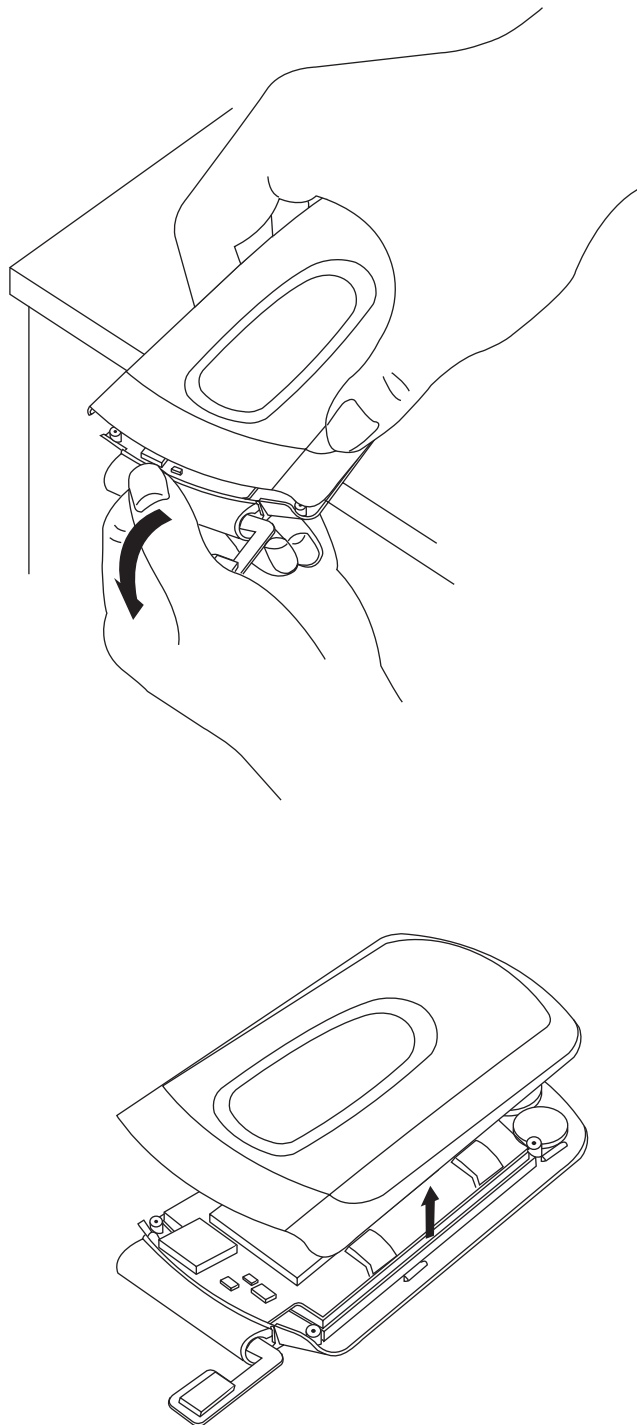


Figure 5-9. Disassembly of folder

10. Detach the rest components as shown below.

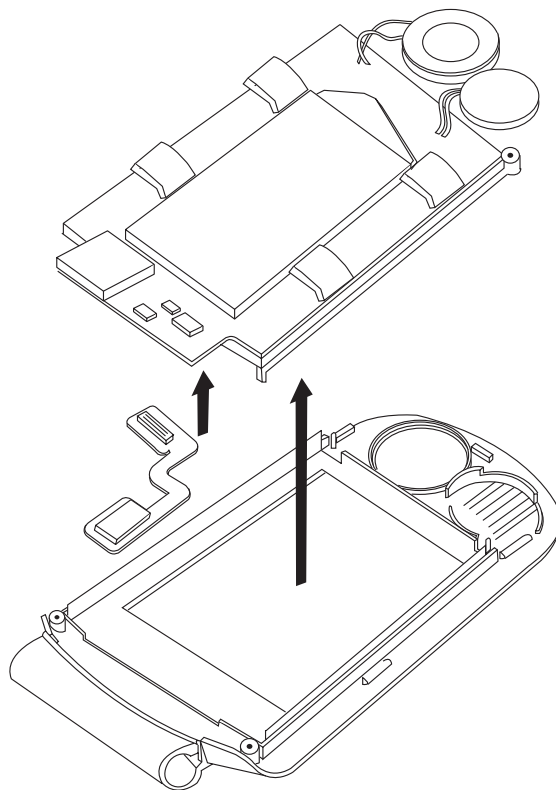


Figure 5-10. Disassembly of rest components.

6. DOWNLOAD AND CALIBRATION

6.1 Download

A. Download Setup

Figure 6-1 describes Download setup.

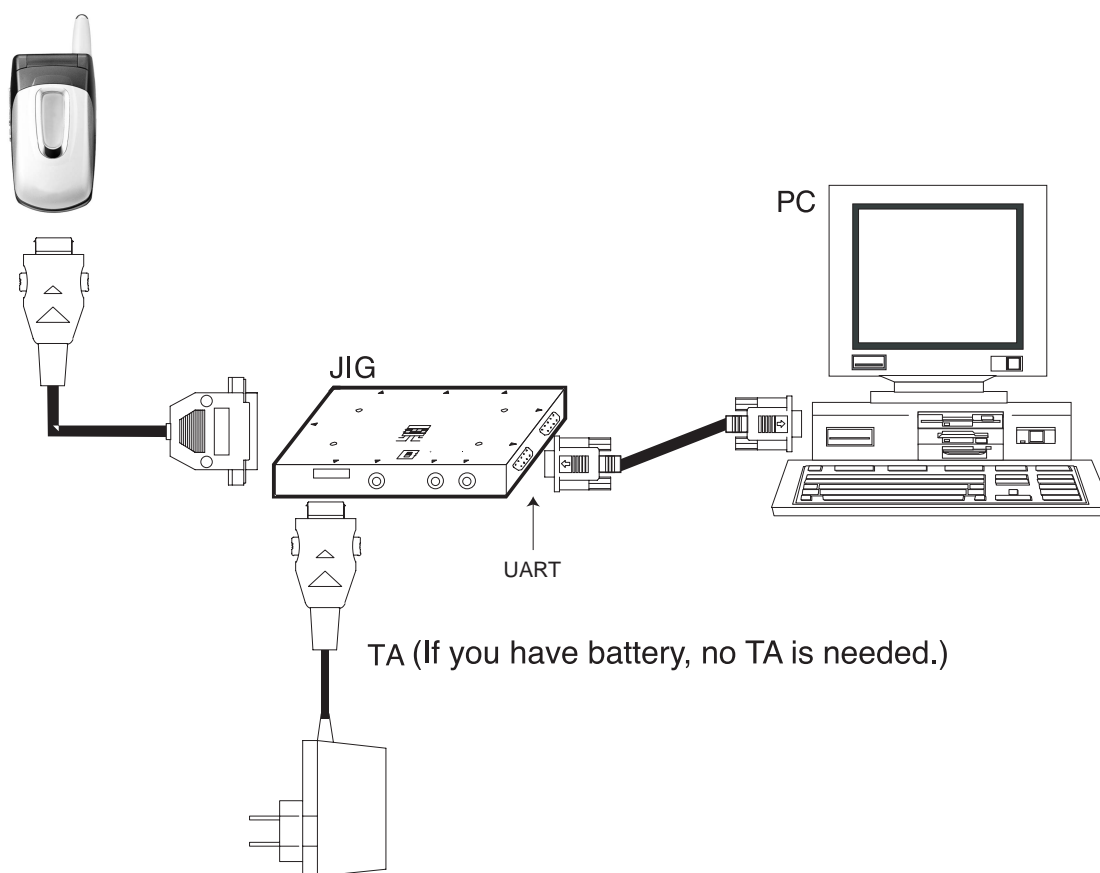
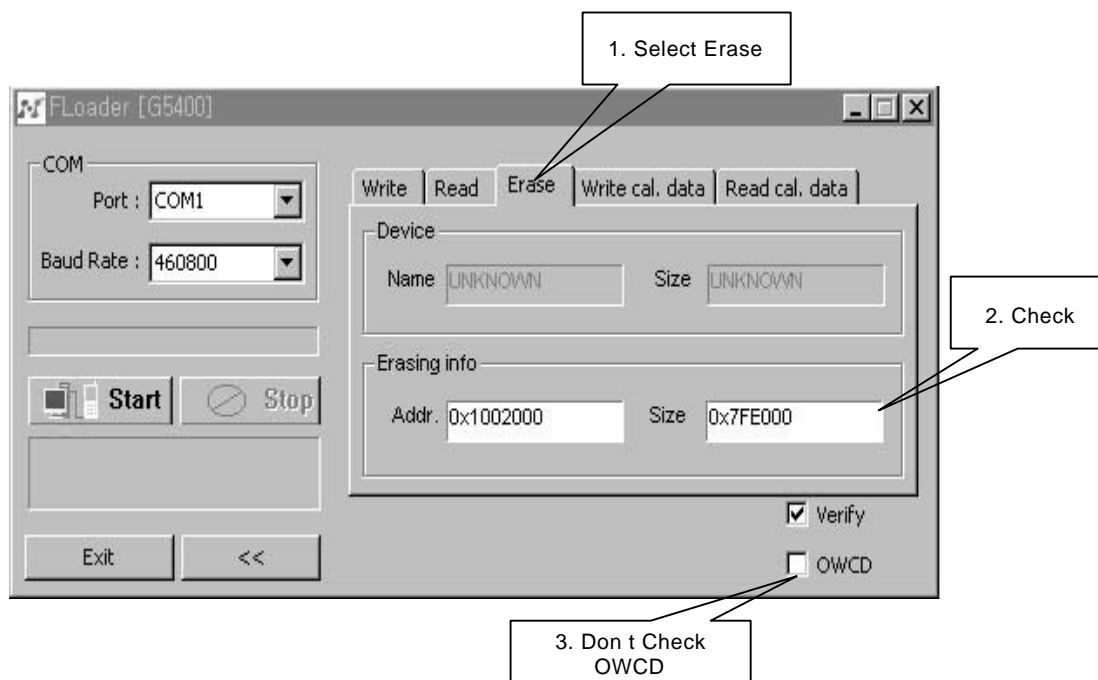


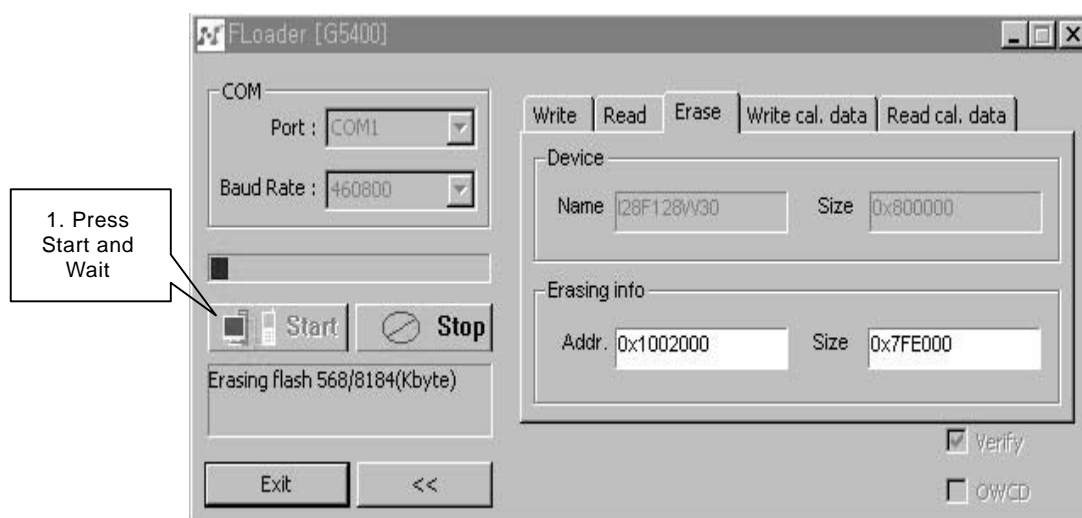
Figure 6-1. Download Setup

B. Download Procedure

1. Access Flash loader program in PC and select Erase.(Don't check OWCD)

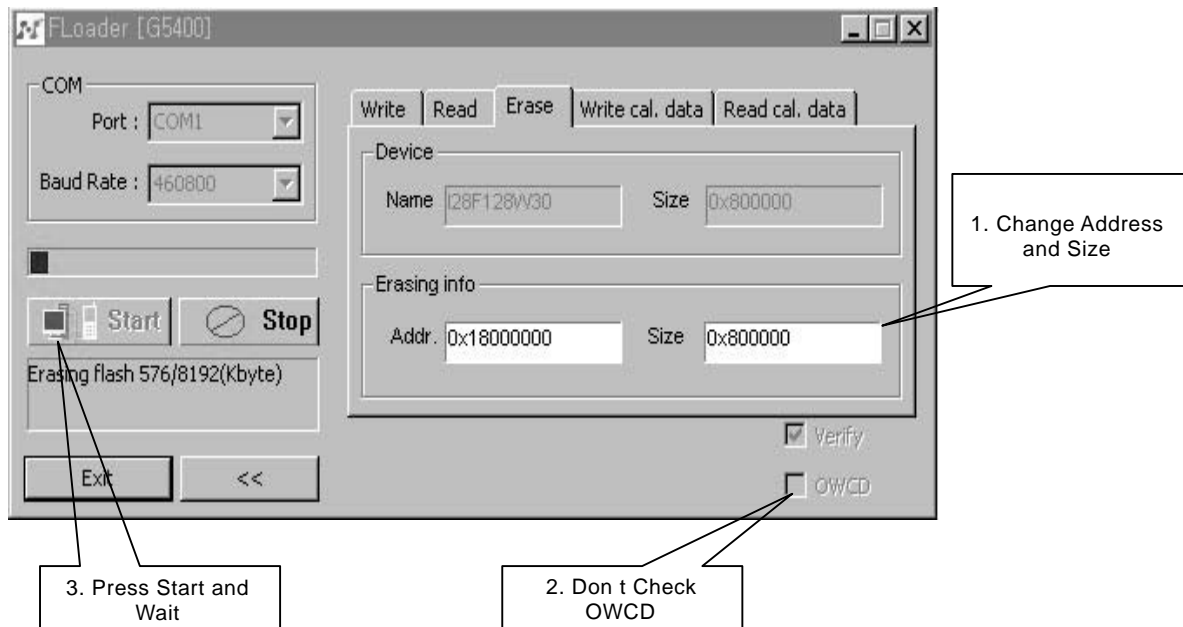



2. Press Start and Wait until Erase is completed.(Code $\emptyset\mu\emptyset^{\text{TM}}$ erase)

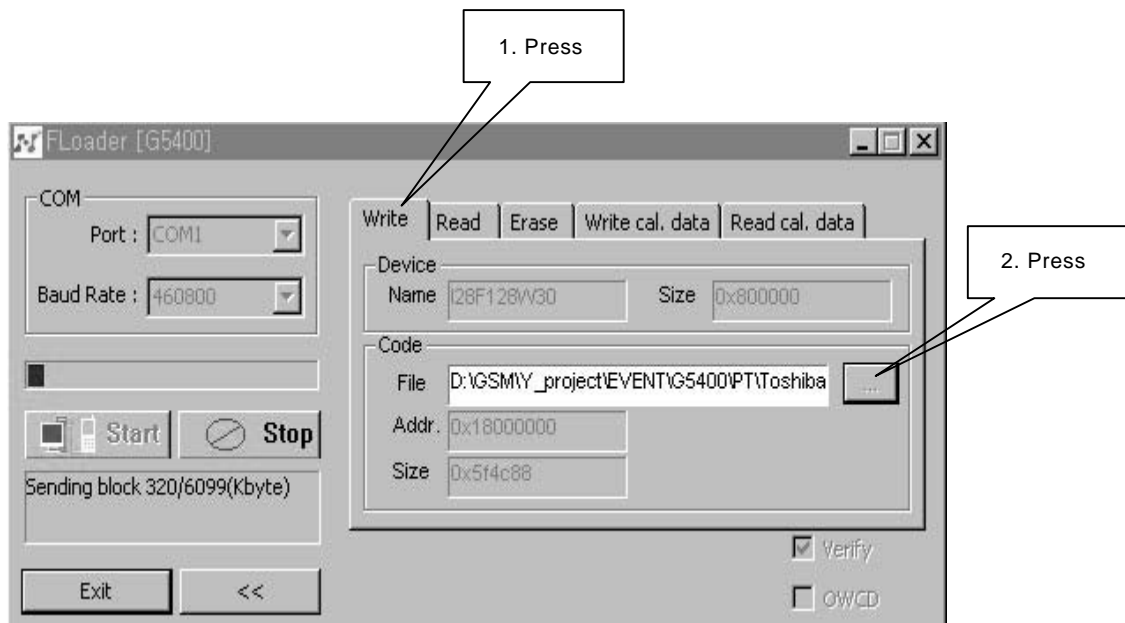


6. DOWNLOAD AND CALIBRATION

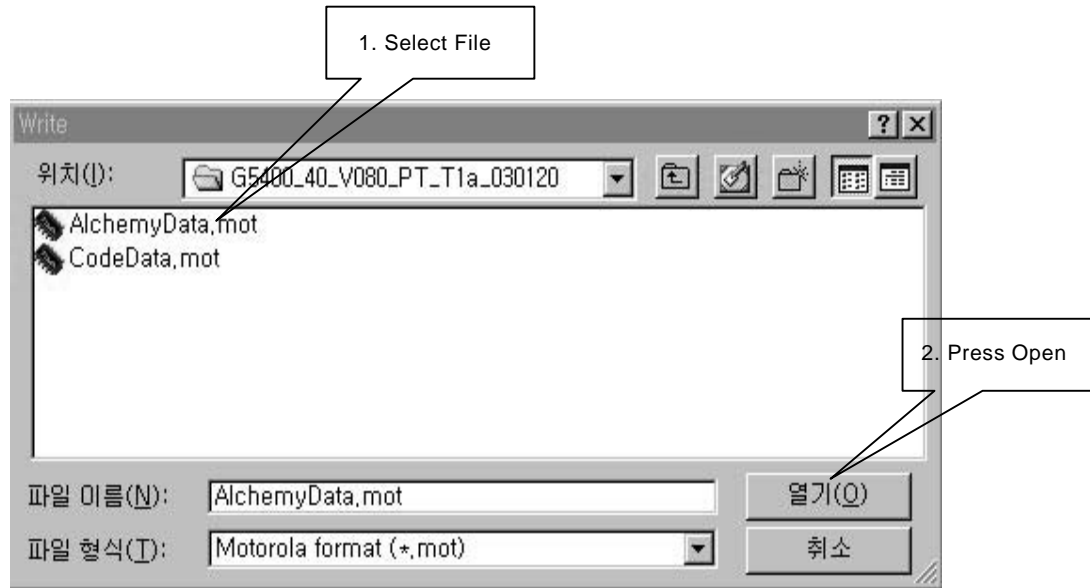
3. Change Address and Size(Address : 18000000, Size : 0x800000), and Press Start and Wait until Erase is completed again (Alchemy 8W8Cerase)



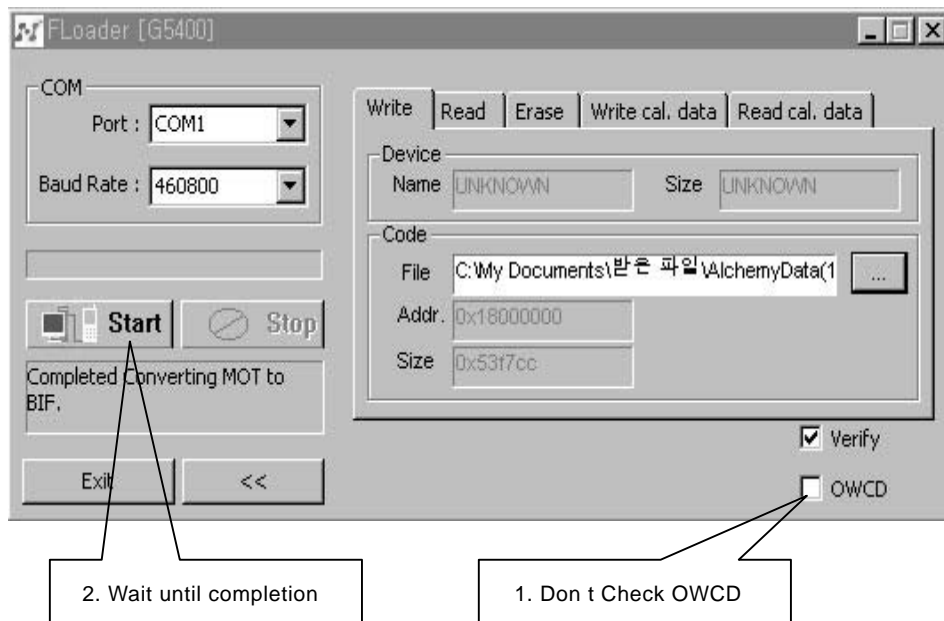
4. Press Write to start Download and press  Key to choose software (AlchemyData.mot)



5. Choose software

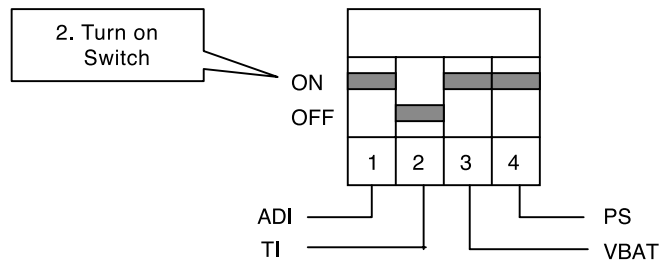
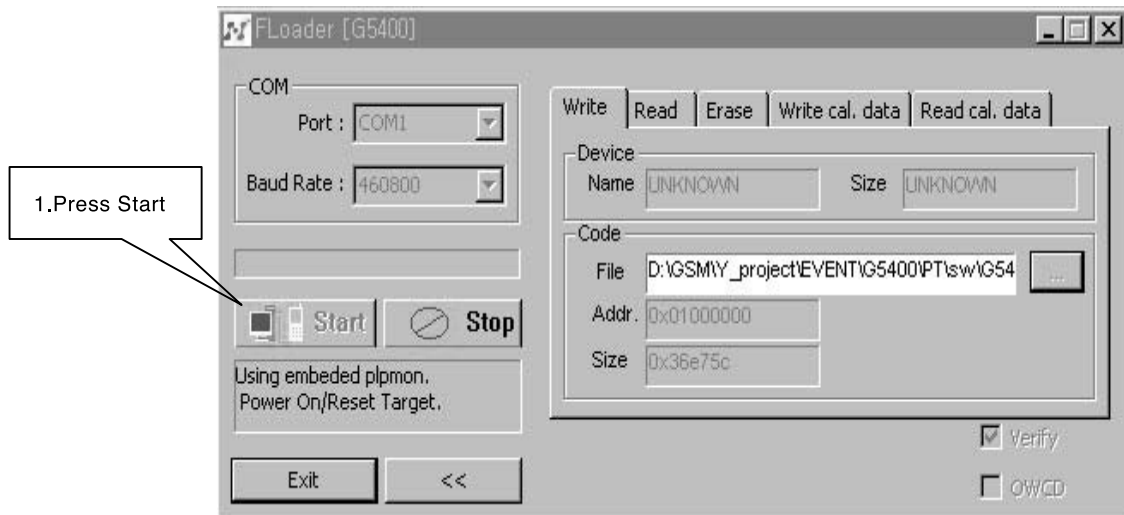


6. Wait until converting from MOT to BIF is completed(Don't check OWCD)

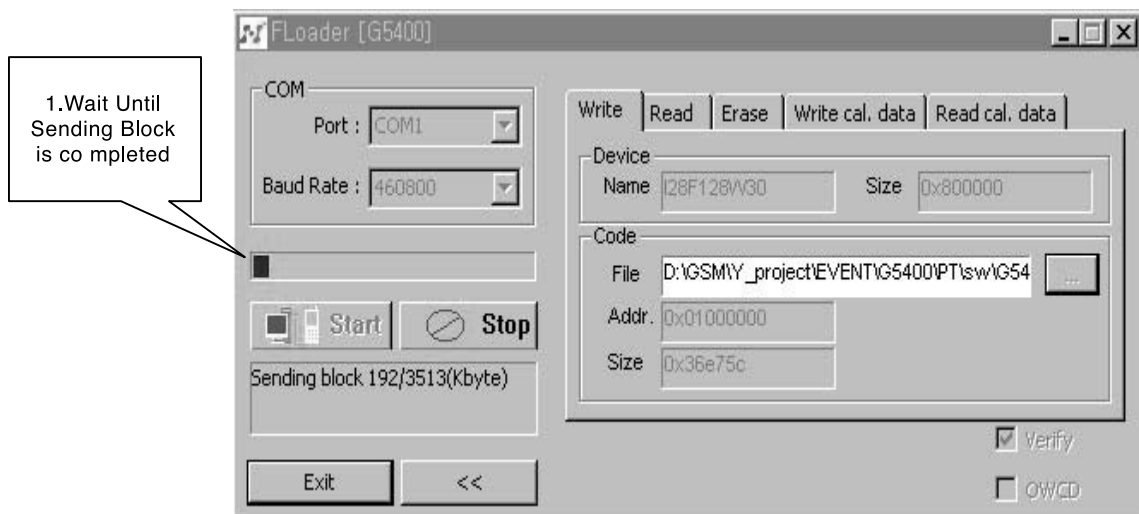


6. DOWNLOAD AND CALIBRATION

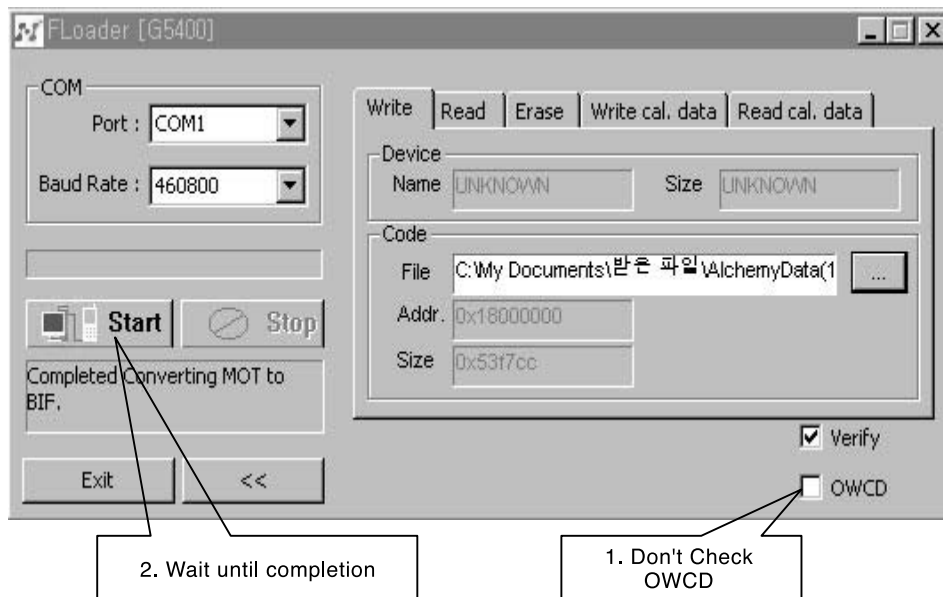
7. Press Start and Power on the phone using JIG remote Power on(Switch 1)



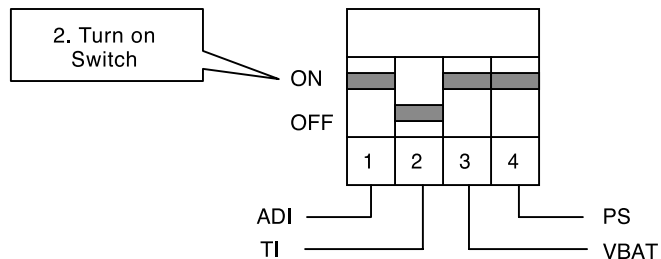
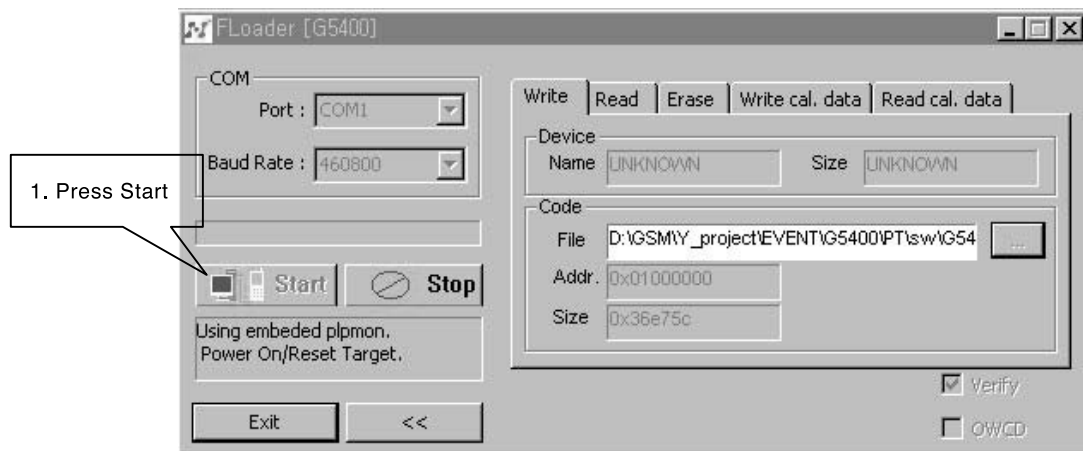
8. Wait until Sending Block is completed



9. Press Write to start Download and press  Key to choose software(CodeData.mot)

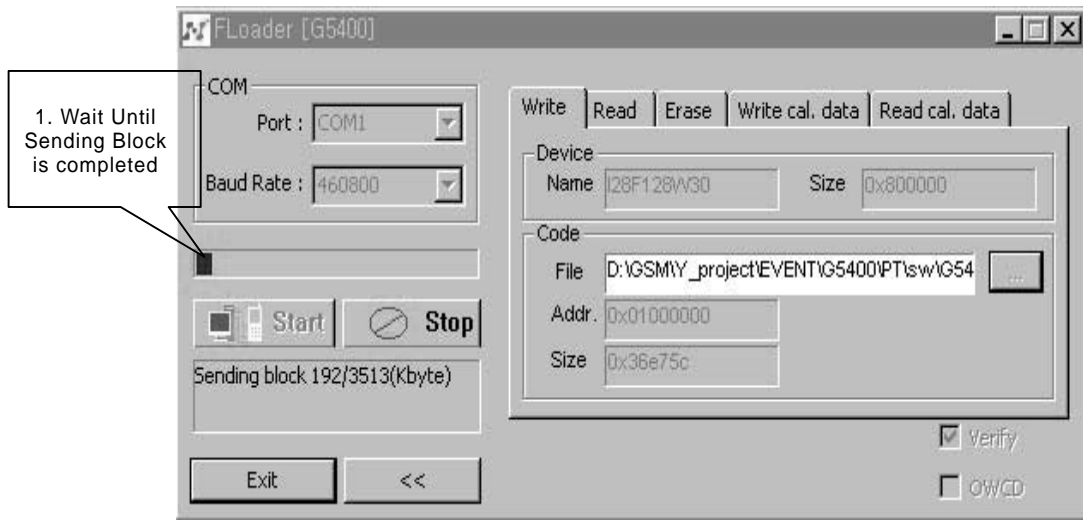


10. Choose software



6. DOWNLOAD AND CALIBRATION

11. Wait until Sending Block is completed



6.2 Calibration

A. Equipment List

Table 6-1. Calibration Equipment List

Equipment for Calibration	Type / Model	Brand
Wireless Communication Test Set	HP-8960	Agilent
RS-232 Cable and Test JIG		LG
RF Cable		LG
Power Supply	HP-66311B	Agilent
GPIO interface card	HP-GPIO	Agilent
Calibration & Final test software		LG
Test SIM Card		
PC (for Software Installation)	Pentium II class above 300MHz	

B. Equipment Setup

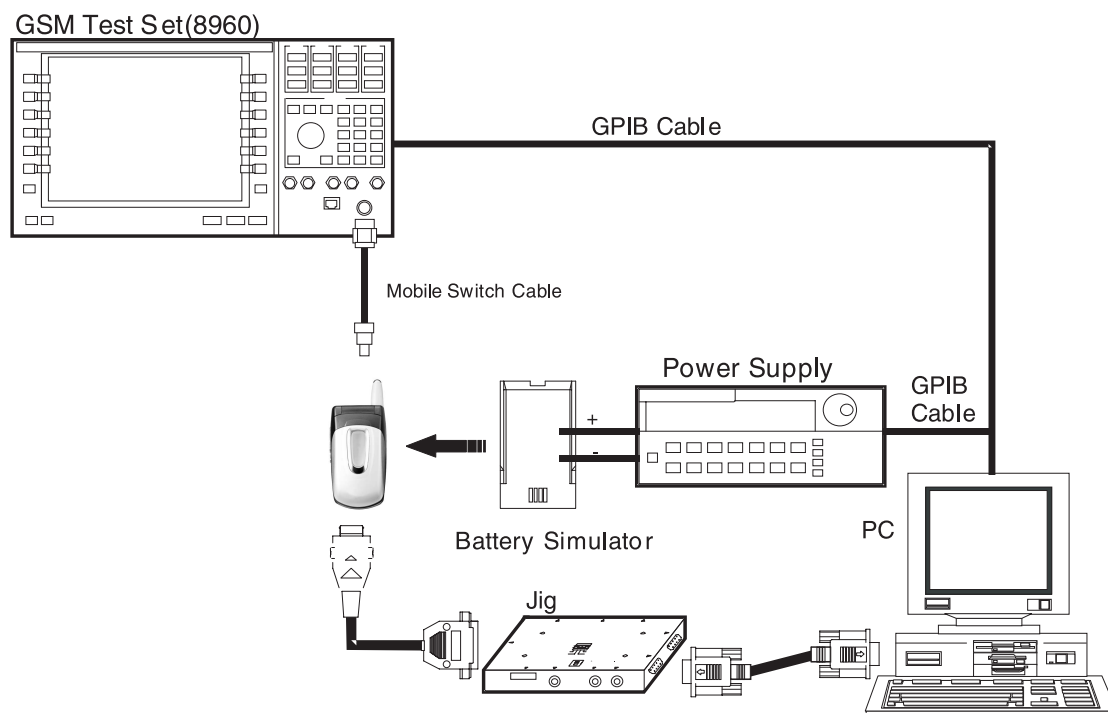


Figure 6-2.

6. DOWNLOAD AND CALIBRATION

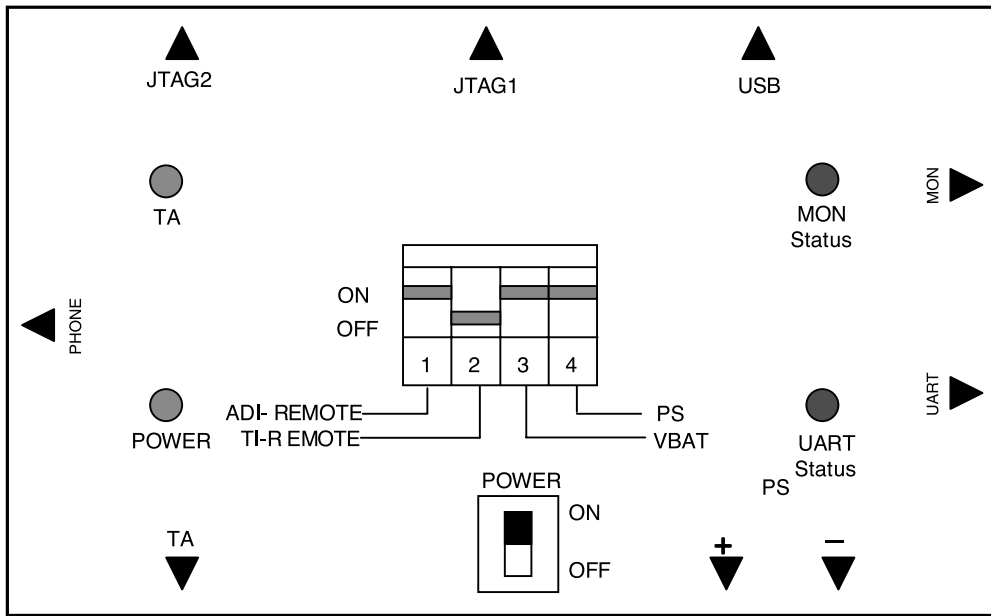


Figure 6-3. The top view of Test JIG

C. Test Jig Operation

Table 6-2. Calibration Equipment List

Power Source	Description
Power Supply	usually 4.0V
Travel Adaptor	Use TA, name is TA-20G(24pin)

Table 6-3. Calibration Equipment List

Switch Number	Name	Description
Switch 1	ADI-REMOTE	In ON state, phone is awaked. It is used ADI chipset.
Switch 2	TI-REMOTE	In ON state, phone is awaked. It is used TI chipset.
Switch 3	VBAT	Power is provided for phone from battery
Switch 4	PS	Power is provided for phone from Power supply

Table 6-4. Calibration Equipment List

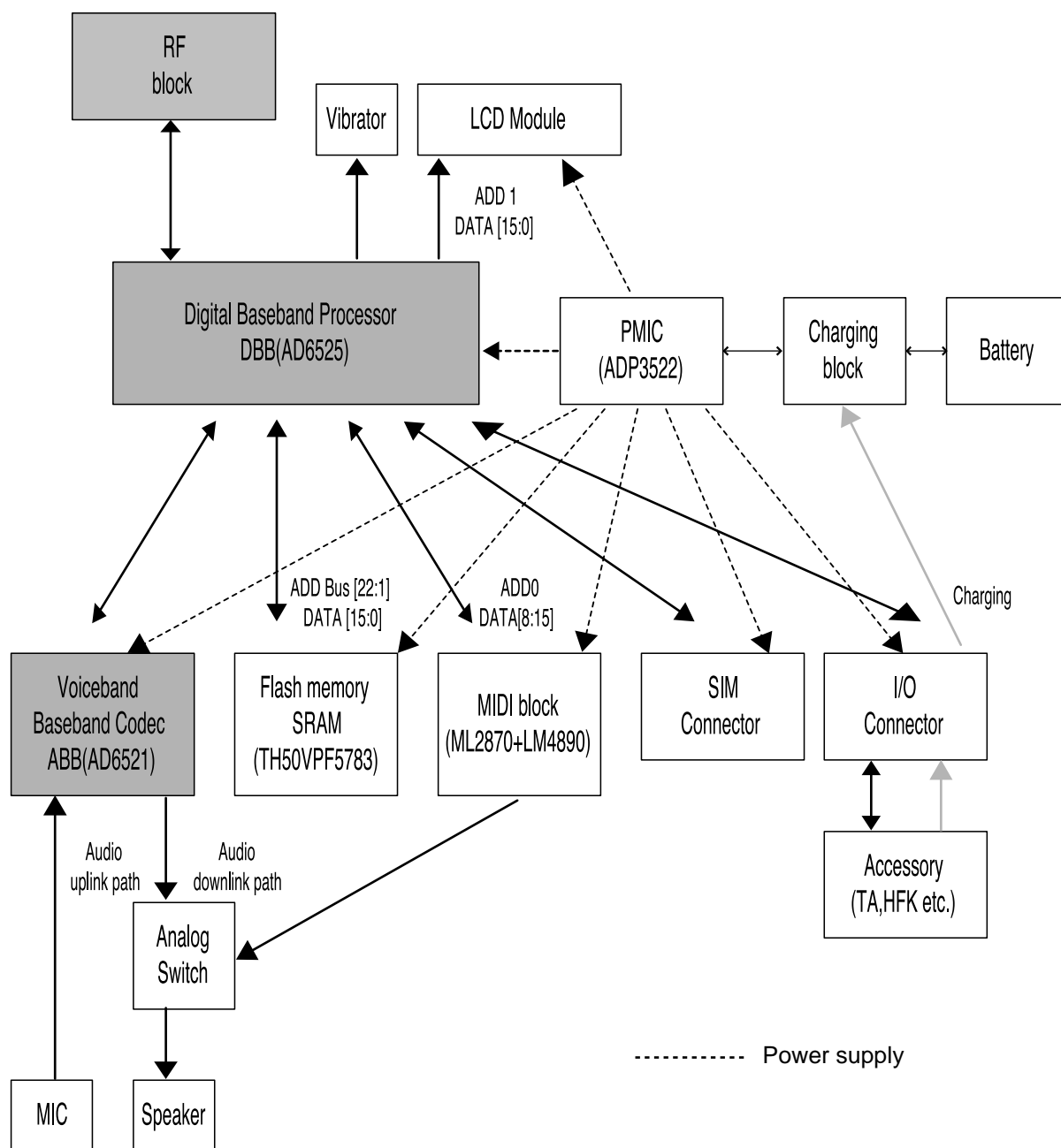
LED Number	Name	Description
LED 1	Power	Power is provided for Test Jig.
LED 2	TA	Indicate charging state of the phone battery
LED 3	UART	Indicate data transfer state through the UART port
LED 4	MON	Indicate data transfer state through the MON port

1. Connect as Fig 6-2(RS232 serial cable is connected between COM port of PC and MON port of TEST JIG, in general)
2. Set the Power Supply 4.0V
3. Set the 3rd, 4th of DIP SW ON state always
4. Press the Phone power key, if the Remote ON is used, 1st ON state

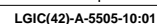
D. Procedure

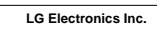
1. Connect as Fig 6-2(RS232 serial cable is connected between COM port of PC and MON port of TEST JIG, in general)
2. Power ON PC then enter into Windows 98(Remark : Windows 2000 system could be feasible)
3. Run AUTOCAL.exe, the AUTOCAL application window will be appeared.

7. BLOCK DIAGRAM

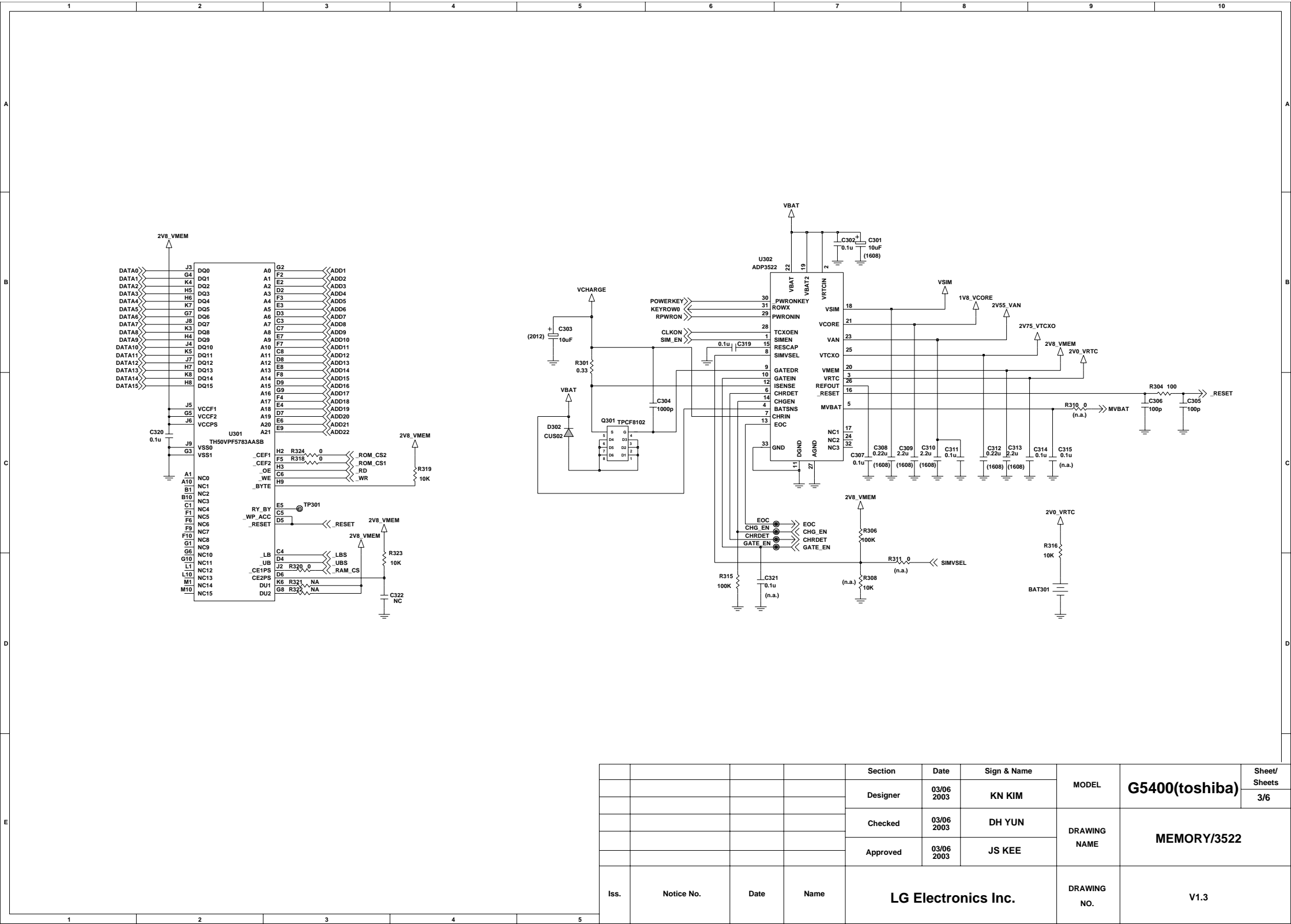


8.1 MAIN



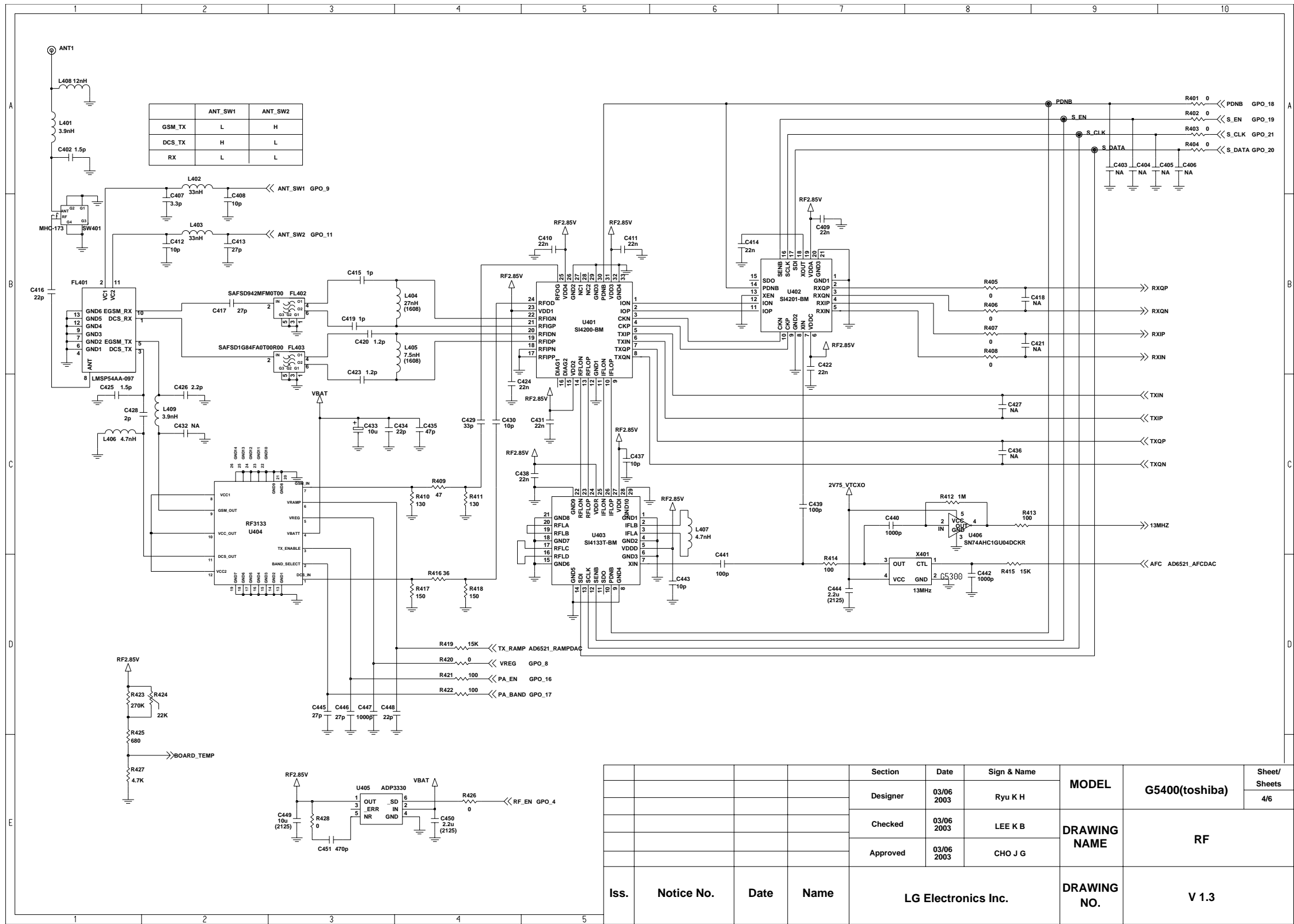


8.3 MIDI



				Section	Date	Sign & Name	MODEL	G5400(toshiba)	Sheet/ Sheets
				Designer	03/06 2003	KN KIM			3/6
				Checked	03/06 2003	DH YUN	DRAWING NAME	MEMORY/3522	
				Approved	03/06 2003	JS KEE			
Iss.	Notice No.	Date	Name	LG Electronics Inc.			DRAWING NO.	V1.3	

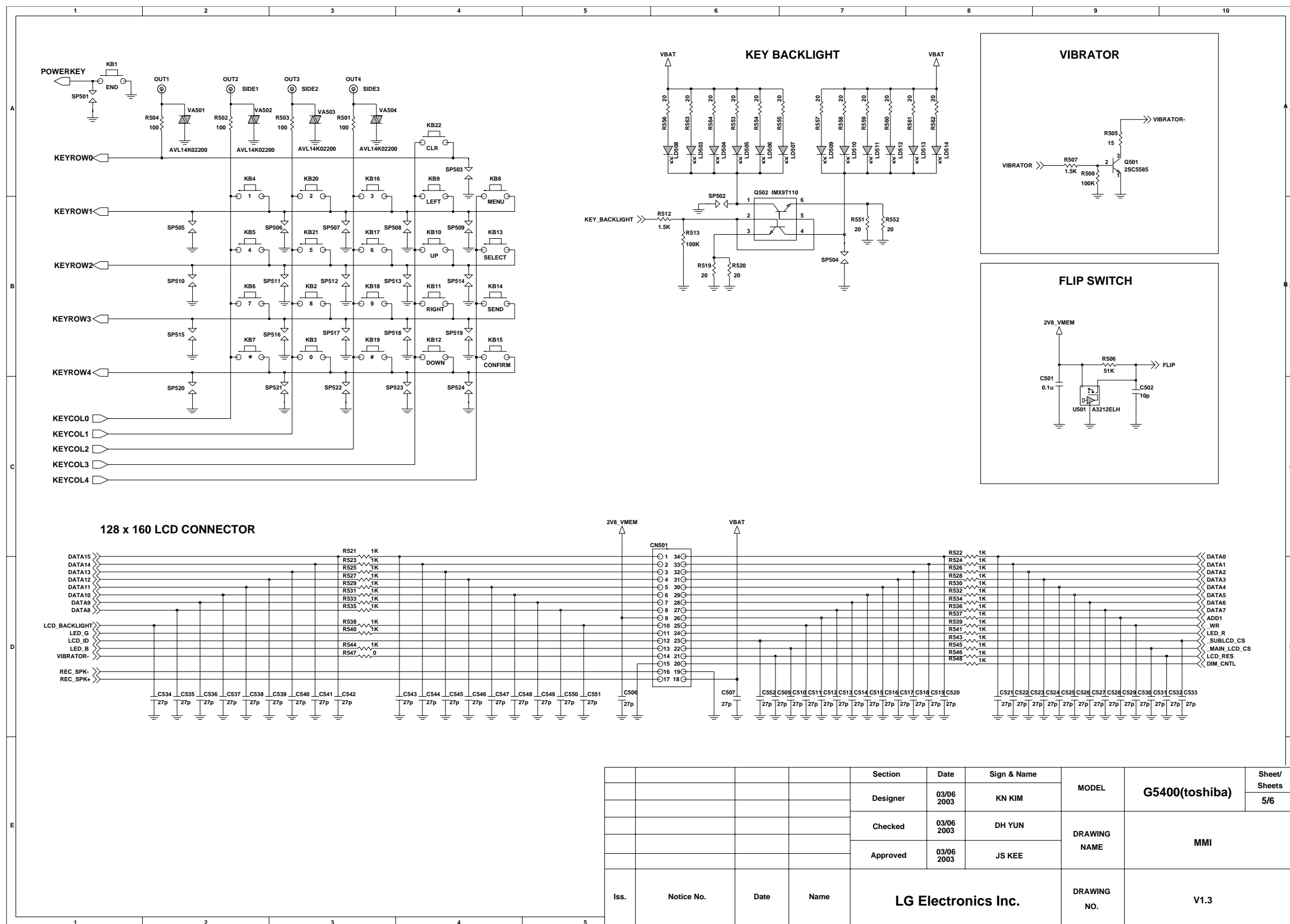
8.4 RF CIRCUIT



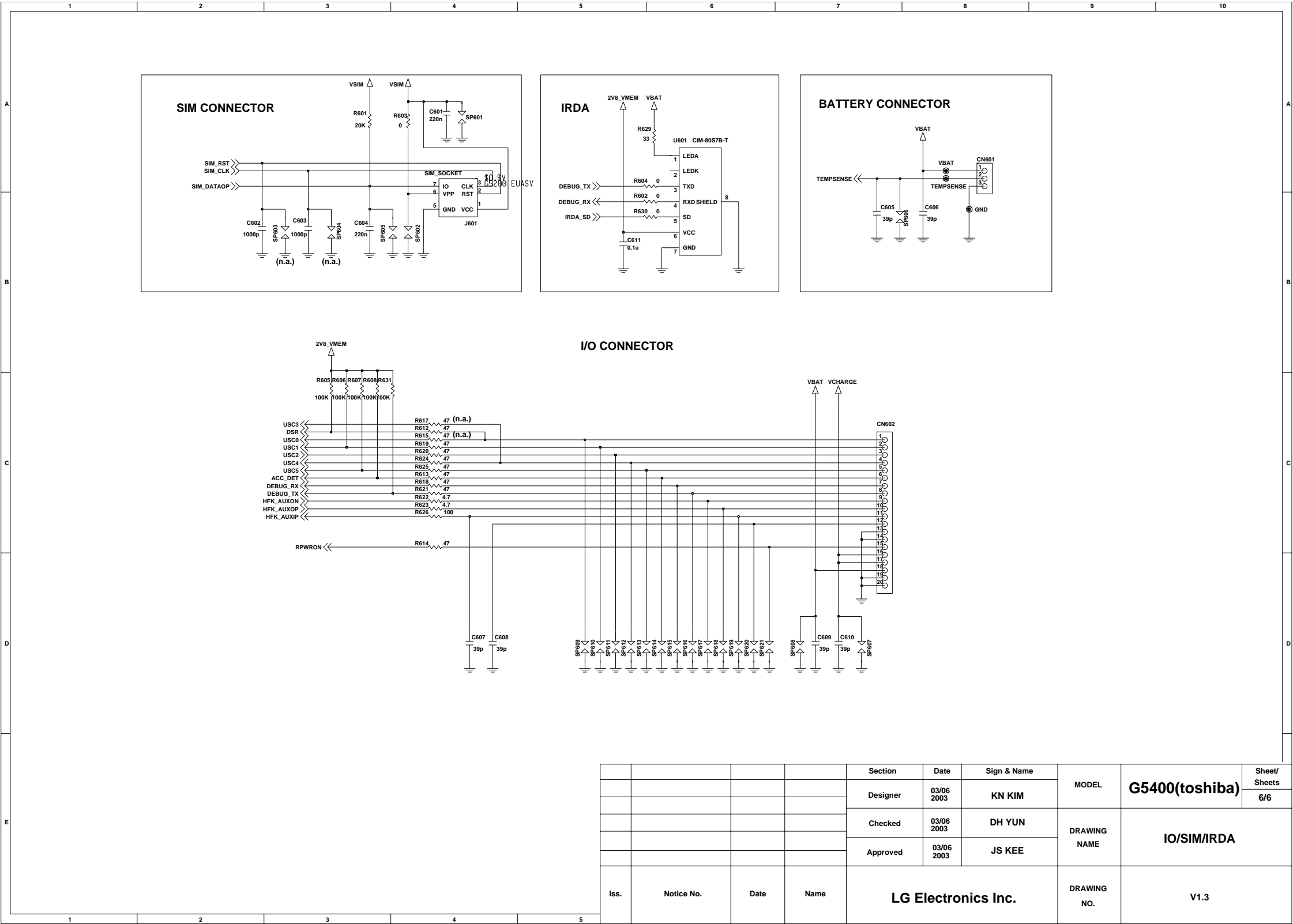
LGIC(42)-A-5505-10:01

LG Electronics Inc.

8.5 Keypad



8.6 SIM, IrDA, Battery etc



LG Electronics Inc.





10. ENGINEERING MODE

A. About Engineering Mode

Engineering mode is designed to allow a service man/engineer to view and test the basic functions provided by a handset.

B. Access Codes

The key sequence for switching the engineering mode on is 2945 'Select'. Pressing END will switch back to non-engineering mode operation.

C. Key Operation

Use Up and Down key to select a menu and press 'select' key to progress the test. Pressing 'back' key will switch back to the original test menu.

10.1 BB Test [MENU 1]

Baseband Test

A. LCD [1-1]

This menu is to test 7color LED.

- Red [1-1-1] :
- Blue [1-1-2] :
- White [1-1-3] :
- Yellow [1-1-4] :

B. LCD [1-2]

This menu is to test the LCD contrast.

- Contrast Value [1-2-1] : Change this value by up and down key.

C. Backlight [1-3]

This menu is to test the LCD Backlight and Keypad Backlight.

- Backlight On [1-3-1] : LCD Backlight and Keypad Backlight light on at the same time.
- Backlight Off [1-3-2] : LCD Backlight and Keypad Backlight light off at the same time.
- Backlight value [1-3-3] : This controls brightness of Backlight. When entering into the menu, the present backlight-value in the phone is displayed. Use Left/Right key to adjust the level of brightness. The value of the brightness set at last will be saved in the NVRAM.

D. Buzzer [1-4]

This menu is to test the melody sound.

- Melody on [1-4-1] : Melody sound is played through the speaker.
- Melody off [1-4-1] : Melody sound is off.

E. Vibrator [1-5]

This menu is to test the vibration mode.

- Vibrator On [1-5-1] : Vibration mode is on.

- Vibrator Off [1-5-2] : Vibration mode is off.

F. ADC (Analog to Digital Converter) [1-6]

This displays the value of each ADC.

- MVBAT ADC (Main Voltage Battery ADC) [1-6-1]
- AUX ADC (Auxiliary ADC) [1-6-2]
- TEMPER ADC (Temperature ADC) [1-6-3]

G. BATTERY [1-7]

- Bat Cal [1-7-1] :

This displays the value of Battery Calibration.

The following menus are displayed in order; BAT_LEV_4V, BAT_LEV_3_LIMIT, BAT_LEV_2_LIMIT, BAT_LEV_1_LIMIT, BAT_IDLE_LIMIT, BAT_INCALL_LIMIT, SHUT_DOWN_VOLTAGE, BAT_RECHARGE_LMT

- TEMP Cal [1-7-2] :

This displays the value of Temperature Calibration.

The following menus are displayed in order;

TEMP_HIGH_LIMIT, TEMP_HIGH_RECHARGE_LMT, TEMP_LOW_RECHARGE_LMT, TEMP_LOW_LIMIT

H. Audio [1-8]

This is a menu for setting the control register of Voiceband Baseband Codec chip.

Although the actual value can be written over, it returns to default value after switching off and on the phone.

- VbControl1 [1-8-1] : VbControl1 bit Register Value Setting
- VbControl2 [1-8-2] : VbControl2 bit Register Value Setting
- VbControl3 [1-8-3] : VbControl3 bit Register Value Setting
- VbControl4 [1-8-4] : VbControl4 bit Register Value Setting
- VbControl5 [1-8-5] : VbControl5 bit Register Value Setting
- VbControl6 [1-8-6] : VbControl6 bit Register Value Setting

I. DAI (Digital Audio Interface) [1-9]

This menu is to set the Digital Audio Interface Mode for Speech Transcoder and Acoustic testing.

- DAI AUDIO [1-9-1] : DAI audio mode
- DAI UPLINK [1-9-2] : Speech encoder test
- DAI DOWNLINK [1-9-3] : Speech decoder test
- DAI OFF [1-9-4] : DAI mode off

10.2 RF Test [MENU 2]

Radio Frequency Test

A. SAR Test [2-1]

This menu is to test the Specific Absorption Rate.

- SAR Test On [2-1-1] : Phone continuously process TX only. Call-setup equipment is not required.
- SAR Test Off [2-1-2] : TX process off

10.3 MF Mode [MENU 3]

This manufacturing mode is designed to do the baseband test automatically. Selecting this menu will process the test automatically, and phone displays the previous menu after completing the test.

A. All auto test [3-1]

LED, Backlight, Buzzer, Vibrator, LCD, Key Pad, and sub LCD are tested in order for a certain time.

B. LED [3-2]

LED color is designed to display to the following colors subsequently : Red, Blue, White, Yellow, Magenta, Green, Cyan

C. Backlight [3-3]

LCD Backlight and LED Backlight are on for about 1.5 seconds at the same time, then off.

D. Buzzer [3-4]

This menu is to test the volume of Melody. It rings in the following sequence. Volume 1, Volume 2, Volume 3, Volume 0 (mute), Volume 4, Volume 5.

E. Vibrator [3-5]

Vibrator is on for about 1.5 seconds.

H. LCD [3-6]

Main LCD screen resolution tests horizontally and vertically one by one and fills the screen.

G. Key pad [3-7]

When a pop-up message shows 'Press Any Key', you may press any keys including side keys, but not [Soft2 Key]. If the key is working properly, name of the key is displayed on the screen. Test will be completed in 15 minutes automatically and the screen displays the previous one.

H. Sub LCD [3-8]

10.4 Trace option [MENU 4]

This is NOT a necessary menu to be used by neither engineers nor users.

10.5 Call Timer [MENU 5]

A. All calls [5-1]

This displays total conversation time. User cannot reset this value.

B. Reset settings [5-2]

This resets total conversation time to this, [00:00:00].

10.6 Fact. Reset [MENU 6]

This Factory Reset menu is to format data block in the flash memory and this procedure set up the default value in data block.

10.7 S/W version [MENU 7]

This displays software version stored in the phone.

Attention

- Fact. Reset (i.e.Factory Reset) should be only used during the Manufacturing process.
- Servicemen should NOT progress this menu, otherwise some of valuable data such as Setting value, RF Calibration data, etc. cannot be restored again.

11. STAND ALONE TEST

11.1 Introduction

This manual explains how to examine the status of RX and TX of the model.

A. Tx Test

TX test - this is to see if the transmitter of the phones is activating normally.

B. Rx Test

RX test - this is to see if the receiver of the phones is activating normally.

11.2 Setting Method

A. COM port

- a. Move your mouse on the "Connect" button, then click the right button of the mouse and select "Com setting".
- b. In the "Dialog Menu", select the values as explained below.
 - Port : select a correct COM port
 - Baudrate : 38400
 - Leave the rest as default values

B. Tx

1. Selecting Channel

- Select one of GSM or DCS Band and input appropriate channel.

2. Selecting APC

- a. Select either Power level or Scaling Factor.
- b. Power level
 - Input appropriate value GSM (between 5~19) or DCS (between 0~15)
- c. Scaling Factor
 - A 'Ramp Factor' appears on the screen.
 - You may adjust the shape of the Ramp or directly input the values.

C. Rx

1. Selecting Channel

- Select one of GSM or DCS Band and input appropriate channel.

2. Gain Control Index (0~ 26) and RSSI level

- See if the value of RSSI is close to -16dBm when setting the value between 0 ~ 26 in Gain Control Index.
- Normal phone should indicate the value of RSSI close to -16dBm.

11.3 Means of Test

- Select a COM port
- Set the values in Tx or Rx
- Select band and channel
- After setting them all above, press connect button.
- Press the start button

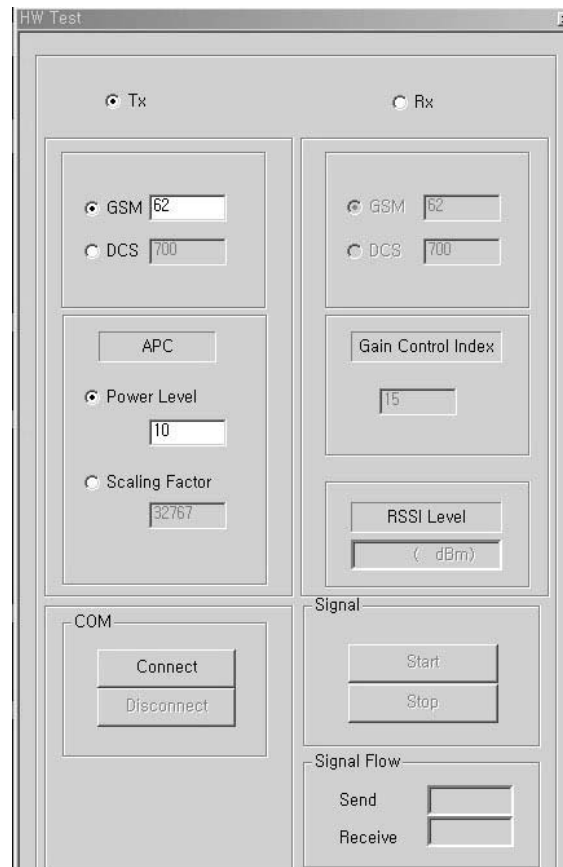


Figure 11-1. HW test program

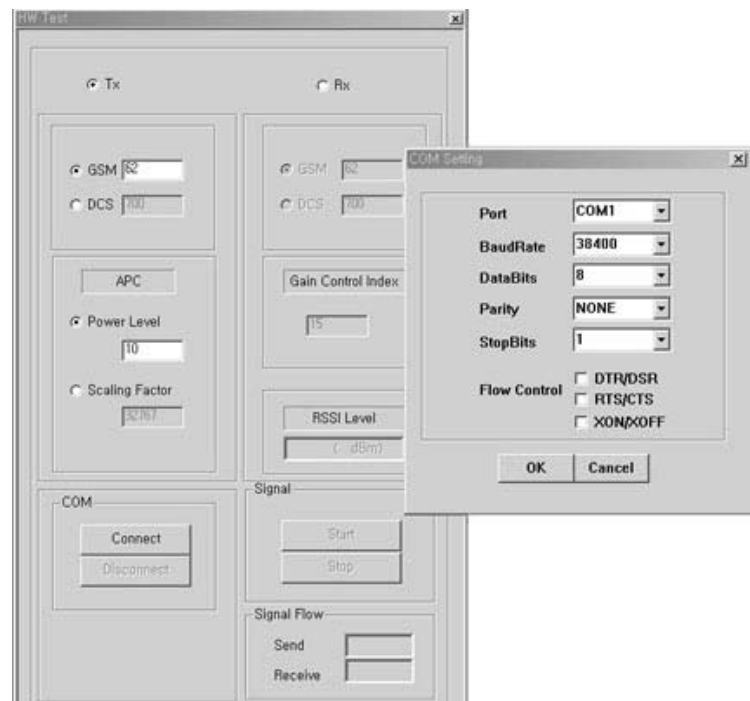


Figure 11-2. HW test setting

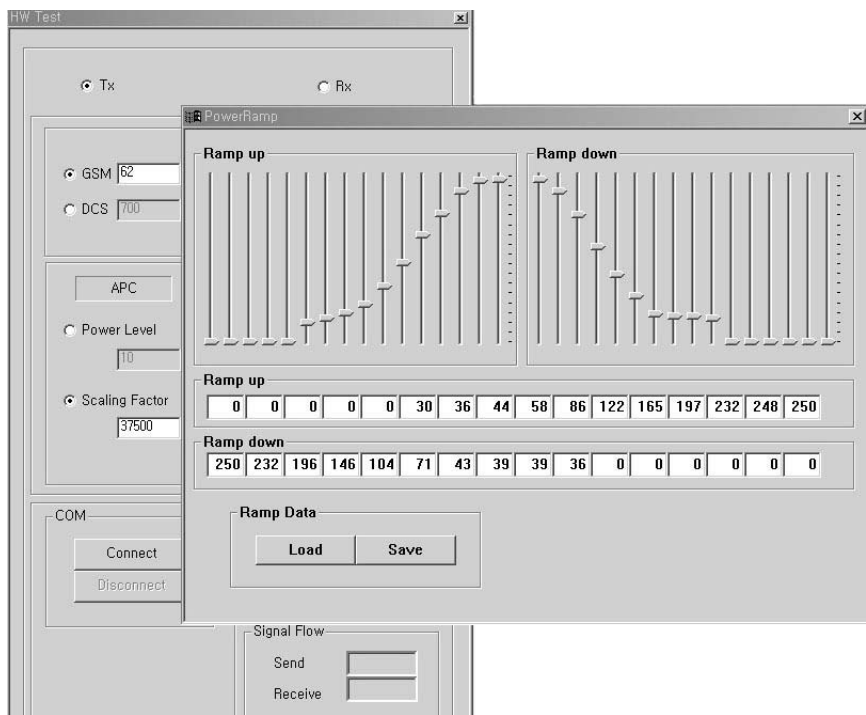


Figure 11-3. Ramping profile

12.AUTO CALIBRATION

12.1 Overview

Autocal (Auto Calibration) is the PC side Calibration tool that perform Tx ,Rx and Battery Calibration with Agilent 8960(GSM call setting instrument) and Tektronix PS2521G(Programmable power supply).

Autocal generate calibration data by communicating with phone and measuring equipment then write it into calibration data block of flash memory in GSM phone.

12.2 Requirements

- PC or Notebook installed with Microsoft Windows 98/ME/2000/XP
- Auto Calibration program(Autocal.exe)
- GSM Phone
- LGE PIF JIG, Serial Cable, Data Cable
- Agilent 8960(Call Setting Instrument)
- Tektronix PS2521G(Programmable Power Supply)

12.3 Menu and Settings

- File(F) → Clear View : Clear Calibration Status window texts
- File(F) → Save View : Save Calibration Status window texts
- File(F) → Save Setting : Save Current Calibration settings to setting file(*.cal)
- File(F) → Load Setting : Load saved Calibration setting
- File(F) → Make BIN ALL : Make binary file after calibration finished
- File(F) → Make BIN BAT.Cal only : Make binary file of battery cal data only after calibration finished
- File(F) → Make & Write BIN : Make binary file after calibration finished then download it to the Flash Memory
- View(V) → Tools : Enable or disable Tool bar
- View(V) → Status : Enable or disable status bar
- Connection(C) Connect : Connect the phone with PC. This procedure checks whether the PC is connected "ag8960 " or not. After that it performs sync. procedure with phone. If the sync. procedure is successful state column on status bar changed to SETUP, else you should disconnect phone and try again from the beginning and also check the whole connection. All measurement is performed at state SETUP.
- Connection(C) → Port Setting : Show COM port setting dialog and Baudrate you can change,etc.
- GPIB(G) → Connect : Connect the Ag8960 GPIB card with PC.

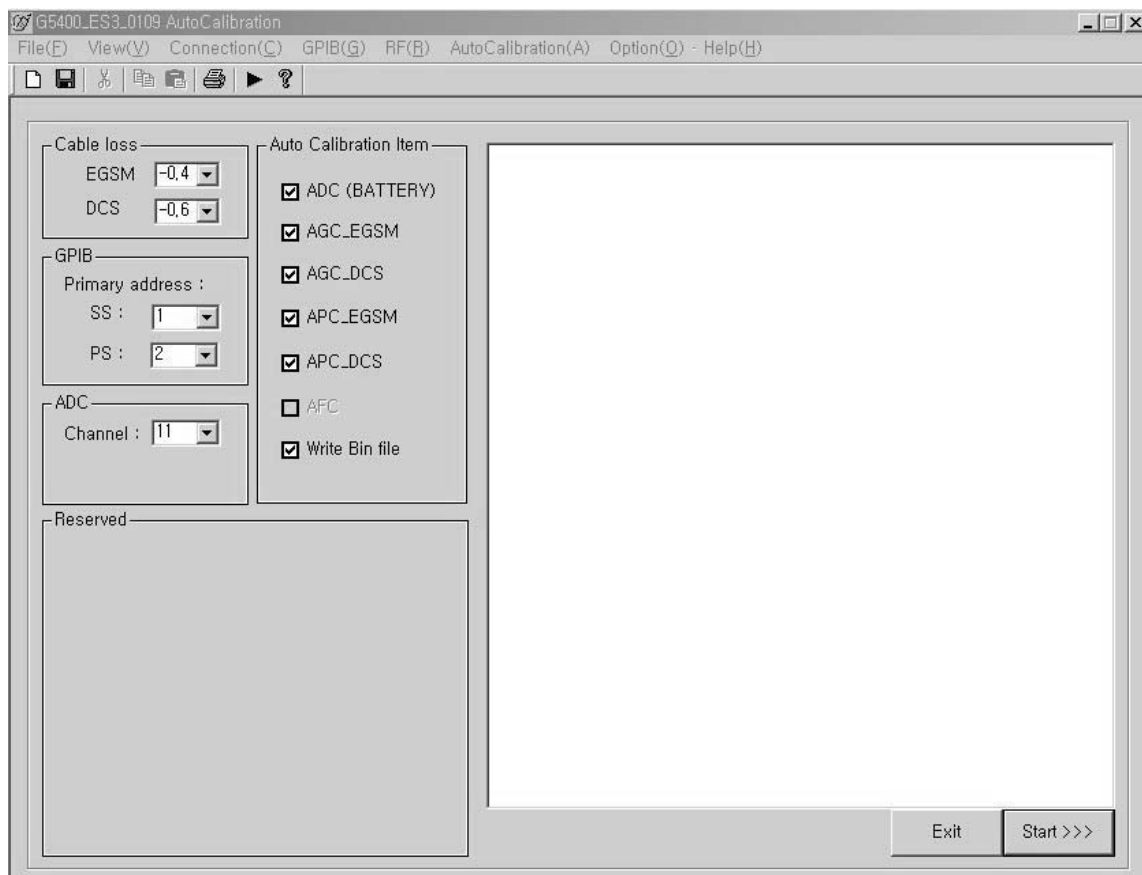


Figure 12-1. Auto Calibration Program

- Screen → Cable loss : Enter the RF cable loss GSM and DCS
- Screen → GPIB(Primary address) : Enter the SS(Ag8960) and PS(Tektronix PS2521G) GPIB address
- Screen → ADC Channel : Default ADC Calibration Channel
- Screen → Auto Calibration Item : Default Calibration Settings about Tx, Rx, ADC and write BIN file

12.4 AGC

This procedure is for Rx calibration.

In this procedure, We can get RSSI correction value. Set band EGSM and press Start button the result window will show correction values per every power level and gain code and the same measure is performed per every frequency.

12.5 APC

This procedure is for Tx calibration.

In this procedure you can get proper scale factor value and measured power level.

12.6 ADC

This procedure is for battery calibration.

You can get main Battery Config Table and temperature Config Table

12.7 Setting

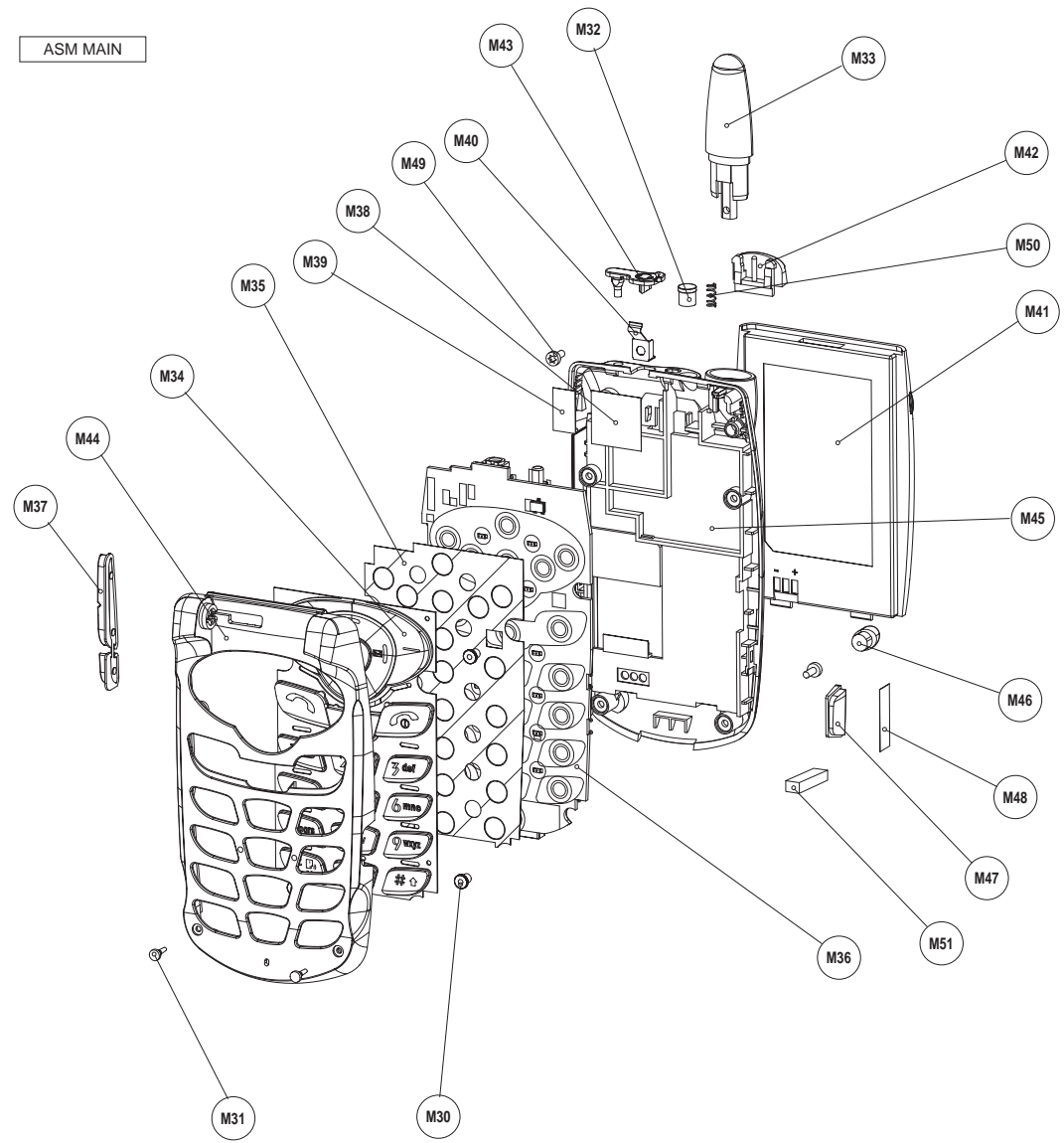
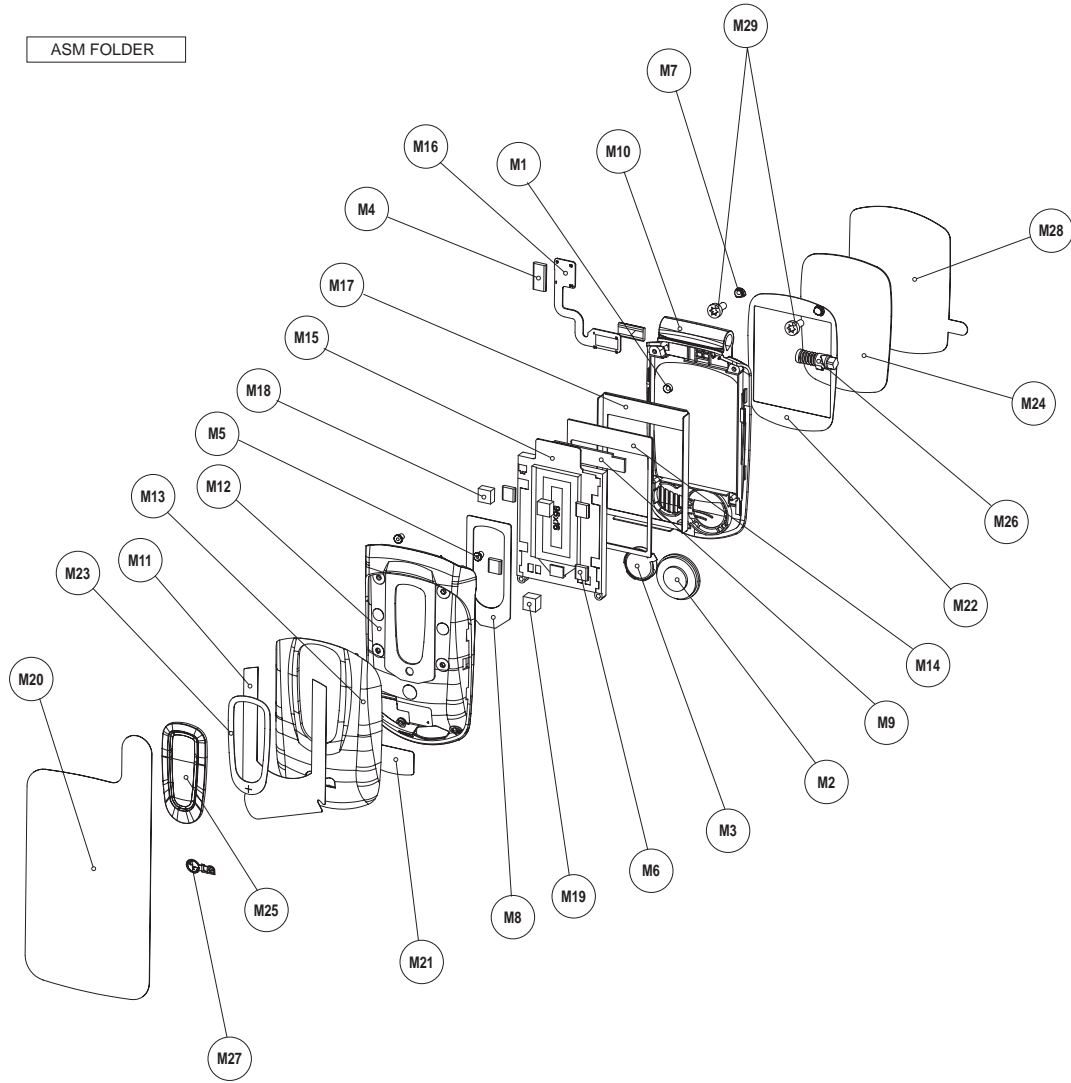
check com port and cable loss. Select automatic calibration item. If you uncheck one item calibration will stop from the unchecked item. This is useful when you want to process only one item.

12.8 How to do calibration

- A. Connect cable between phone and serial port of PC.
- B. Connect Ag8960 equipment and Power Supply and phone.
- C. Set correct port and baud rate.
- D. Press Start button. AutoCal process all calibration procedure
 - i. AGC EGSM
 - ii. AGC DCS
 - iii. APC EGSM
 - iv. APC DCS
 - v. ADC
- E. After finished all measurement. The state is return to SETUP.
- F. The Cal file will be generated and then the calibration data will be written into phone and then will be reset.

13. EXPLODED VIEW & REPLACEMENT PART LIST

13.1 Exploded View



13. EXPLODED VIEW & REPLACEMENT PART LIST

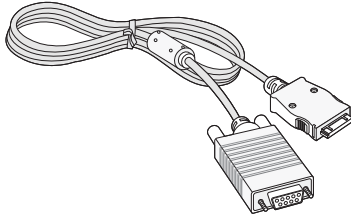
< Parts List of Exploded View >

No	Level	Location No.	Part Number	Description	Qty	Specification	Service
	1		TGFF0005001	GSM(FOLDER)	1	G5400 EUASV	No
	2	APEY00	APEY0056501	PHONE	1	G5400 EUASV	Yes
	3	ACGG00	ACGG0021501	COVER ASSY,FOLDER	1	G5400 EUASV	Yes
	4	ACGH00	ACGH0011901	COVER ASSY,FOLDER(LOWER)	1	G5400 EUASV	Yes
M10	5	MCJH00	MCJH0009201	COVER,FOLDER(LOWER)	1	G5400 EUASV	Yes
M10	5	MCJH00	MCJH0009202	COVER,FOLDER(LOWER)	1	G5400 EUAMS DARK BLUE	Yes
M1	5	MMAA00	MMAA0000601	MAGNET,SWITCH	1	LG-G510,511,512 common use, DIA : 3.0mm+1.5t	Yes
	4	ACGJ00	ACGJ0019601	COVER ASSY,FOLDER(UPPER)	1	G5400 SV	Yes
M12	5	MCJJ00	MCJJ0012901	COVER,FOLDER(UPPER)	1	G5400 EUASV	No
	5	MCJJ00	MCJJ0012902	COVER,FOLDER(UPPER)	1	G5400 EUAMS DARK BLUE	No
M13	5	MDAE00	MDAE0012101	DECO,FOLDER(UPPER)	1	G5400 EUASV	No
M13	5	MDAE00	MDAE0012103	DECO,FOLDER(UPPER)	1	G5400 MYRSRS	No
M5	5	MICZ00	MICZ0003801	INSERT	2	M1.4x3.0	No
M8	5	MPBQ00	MPBQ0007201	PAD,LCD(SUB)	1	G5400 EUASV	Yes
M27	5	MPFF00	MPFF0006101	PLATE,LOGO	1		Yes
M23	5	MTAE00	MTAE0007001	TAPE,WINDOW(SUB)	1	G5400 SUB WINDOW	Yes
M21	5	MTAZ00	MTAZ0012301	TAPE	1	G5400 SV 10x17 Artpaper	No
	4	ACGK00	ACGK0020801	COVER ASSY,FRONT	1	G5400 EUASV	Yes
M31	5	MBHY00	MBHY0003503	BUMPER	2	LG-510,511,512,common use for METALIC SILVER,diameter=2.4	Yes
M31	5	MBHY00	MBHY0003506	BUMPER	2	LG-510,511,512,common use for DARK BLUE,diameter=2.4	Yes
M37	5	MBJL00	MBJL0006501	BUTTON,SIDE	1	G5400 EUA SV	Yes
M44	5	MCJK00	MCJK0014201	COVER,FRONT	1	G5400 EUASV	Yes
M44	5	MCJK00	MCJK0014202	COVER,FRONT	1	G5400 EUAMS DARK BLUE	Yes
M30	5	MICZ00	MICZ0003801	INSERT	4	M1.4x3.0	No
M48	5	MTAB00	MTAB0020202	TAPE,PROTECTION	1	50X83 PROTECTION TAPE	No
M47	5	MWAG00	MWAG0002101	WINDOW,IRDA	1	G5400 EUASV	Yes
	4	AWAB00	AWAB0005001	WINDOW ASSY,LCD	1	G5400 SV MAIN WINDOW	Yes
M22	5	MTAD00	MTAD0012401	TAPE,WINDOW	1	G5400 MAIN WINDOW	No
M24	5	MWAC00	MWAC0024801	WINDOW,LCD	1	G5400 MAIN 1.0t	No
M25	4	AWAB01	AWAB0004701	WINDOW ASSY,LCD	1	G5400 MAIN WINDOW,	Yes
	5	BFAA00	BFAA0009101	FILM,INMOLD	1	G5400 SUB WINDOW	No
	5	MWAF00	MWAF0008401	WINDOW,LCD(SUB)	1	G5400 SUB INMOLD	No
M28	4	GMZZ00	GMZZ0001901	SCREW MACHINE	2	1.4 mm,3.5 mm,MSWR3(BK) ,N ,STR , - , t OF HEAD=1.0,DIA OF HEAD=3.1	Yes
M7	4	MCCH00	MCCH0011901	CAP,SCREW	2	G5400 EUASV, FOLDER	Yes
M7	4	MCCH00	MCCH0011902	CAP,SCREW	2	G5400 EUAMS DARK BLUE, FOLDER	Yes
M4	4	MGAD00	MGAD0025301	GASKET,SHIELD FORM	2	5x10x1.5t hard	Yes
M6	4	MGAD01	MGAD0025201	GASKET,SHIELD FORM	4	5x5x1.5t hard	Yes
M26	4	MHFD00	MHFD0004101	HINGE,FOLDER	1	5400 (5PHI) 5Kg-T	Yes
M17	4	MHGD00	MHGD0001501	HOLDER,LCD	1	G5400 LCD HOLDER	Yes

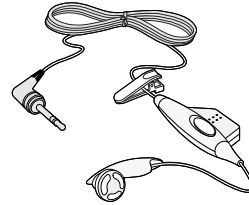
13. EXPLODED VIEW & REPLACEMENT PART LIST

No	Level	Location No.	Part Number	Description	Qty	Specification	Service
M9	4	MPBG	MPBG0010102	PAD,LCD	1	6X33.5X1.0t	Yes
M14	4	MPBG00	MPBG0010101	PAD,LCD	1	G5400 MAIN LCD	Yes
M18	4	MPBG02	MPBG0010103	PAD,LCD	2	5X5X3t	Yes
M19	4	MPBG03	MPBG0010104	PAD,LCD	1	5X5X4t	Yes
M20	4	MTAB00	MTAB0009001	TAPE,PROTECTION	1	PROTECTION, FOLDER	No
M16	4	SACY00	SACY0007801	PCB ASSY,FLEXIBLE	1		Yes
	5	ENBY00	ENBY0013401	CONNECTOR,BOARD TO BOARD	1	34 PIN,0.4 mm,STRAIGHT ,Au ,B to B G5400	No
	5	ENBY01	ENBY0013401	CONNECTOR,BOARD TO BOARD	1	34 PIN,0.4 mm,STRAIGHT ,Au ,B to B G5400	No
	5	MTAZ00	MTAZ0012302	TAPE	1	4X12	Yes
	5	SPCY00	SPCY0012501	PCB,FLEXIBLE	1	POLYI ,.45 mm,DOUBLE ,V1.1	No
M2	4	SPK1	SUSY0006202	SPEAKER	1	ASSY ,8 ohm,92 dB,17 mm,G5400 DUAL SPEAKER	Yes
M15	4	SVLM00	SVLM0005201	LCD MODULE	1	Main:128*160 (1.5"),Sub:96*16 ,A/Area:28.02*35.028 ,65K CSTN(S6B33B0A)/SUB MONO(S6B0723)	Yes
M3	4	VIB1	SJMY0002802	VIBRATOR,MOTOR	1	3 V,0.08 A,12*15 ,G5300 VIBRATOR (0.5t PAD)	Yes
	3	ACGM00	ACGM0017701	COVER ASSY,REAR	1	G5400	Yes
M49	4	GMZZ00	GMZZ0001901	SCREW MACHINE	1	1.4 mm,3.5 mm,MSWR3(BK) ,N ,STR , - , t OF HEAD=1.0,DIA OF HEAD=3.1	Yes
M43	4	MCCC00	MCCC0007601	CAP,EARPHONE JACK	1	SILVER	Yes
M43	4	MCCC00	MCCC0007602	CAP,EARPHONE JACK	1	RED	Yes
M40	4	MCIA00	MCIA0006601	CONTACT,ANTENNA	1		Yes
M45	4	MCJN00	MCJN0011301	COVER,REAR	1	G5400 EUASV	Yes
M45	4	MCJN00	MCJN0011302	COVER,REAR	1	G5400 MYSRS	Yes
M5	4	MICZ00	MICZ0003801	INSERT	1	M1.4x3.0	No
M38	4	MIDZ00	MIDZ0024801	INSULATOR	1	G5400 INSULATOR, 12X13	Yes
M39	4	MIDZ01	MIDZ0024802	INSULATOR	1	G5400 INSULATOR, 5X9	Yes
M42	4	MLEA00	MLEA0008501	LOCKER,BATTERY	1	G5400 EUASV	Yes
M42	4	MLEA00	MLEA0008502	LOCKER,BATTERY	1	G5400 MYSRS	Yes
M50	4	MSDB00	MSDB0001701	SPRING,COIL	1	G7000	Yes
M33	4	SNGF00	SNGF0001601	ANTENNA,GSM,FIXED	1	3.0 ,-2.0 dBd,P427C ,	Yes
M35	3	ADCA00	ADCA0010501	DOME ASSY,METAL	1	G5400	Yes
M49	3	GMZZ00	GMZZ0001901	SCREW MACHINE	4	1.4 mm,3.5 mm,MSWR3(BK) ,N ,STR , - , t OF HEAD=1.0,DIA OF HEAD=3.1	Yes
M34	3	MBJA00	MBJA0008401	BUTTON,DIAL	1	G5400 ENGLISH	Yes
M32	3	MCCF00	MCCF0002003	CAP,MOBILE SWITCH	1	LG-510,511,512,common use,METALIC SILVER	Yes
M32	3	MCCF00	MCCF0002005	CAP,MOBILE SWITCH	1	LG-510,511,512,common use,RED	Yes
M46	3	MCCH00	MCCH0011801	CAP,SCREW	2	G5400 EUASV, MAIN	Yes
M46	3	MCCH00	MCCH0011802	CAP,SCREW	2	G5400 MYSRS, MAIN	Yes
M51	3	MGAD01	MGAD0006001	GASKET,SHIELD FORM	1	G7000 10x5x1.5t	Yes
	3	MIC201	SUMY0004602	MICROPHONE	1	ASSY ,-42 dB,6*1.1 ,G5400 MIC	Yes
	3	MLAK00	MLAK0006801	LABEL,MODEL	1	English, 30.5X21.5	No
	3	MTAZ00	MTAZ0011201	TAPE	2	G5400 EUASV, MAIN SCREW CAP	No

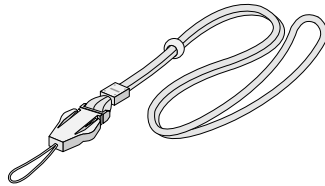
13.2 Accessories



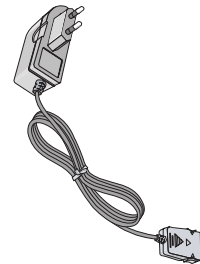
DATA CABLE



EAR PHONE / EAR MIKE SET



HANDSTRAP



ADAPTOR, AC-DC

Level	Location No.	Description	Part No.	QTY	Specification	Service
2	SGDY00	DATA CABLE	SGDY0003003	1	LG-510W/G10, CABLE W/O POWER BULK	YES
2	MHBY00	HANDSTRAP	MHBY0001101	1	Neck Strap 400mm (CDMA,common use)	YES
2	SGEY00	EAR PHONE/EAR MIKE SET	SGEY0002901	1	G7000,G5200 Common use, 3P EAR MIC	YES
2	SSAD00	ADAPTOR,AC-DC	SSAD0007801	1	100-240V,60 Hz,5.2 V,850 mA, CE,85VAC~264VAC / 50HZ~60HZ	YES

13. EXPLODED VIEW & REPLACEMENT PART LIST

13.3 Replacement Part List

< Mechanic components >

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
1		TGFF0005001	GSM(FOLDER)	1	G5400 EUASV	No	
2	APEY00	APEY0056501	PHONE	1	G5400 EUASV	Yes	SILVER
3	ACGG00	ACGG0021501	COVER ASSY,FOLDER	1	G5400 EUASV	Yes	SILVER
4	ACGH00	ACGH0011901	COVER ASSY,FOLDER(LOWER)	1	G5400 EUASV	Yes	SILVER
5	MCJH00	MCJH0009201	COVER,FOLDER(LOWER)	1	G5400 EUASV	Yes	SILVER
5	MMAA00	MMAA0000601	MAGNET,SWITCH	1	LG-G510,511,512 common use, DIA : 3.0mm+1.5t	Yes	
4	ACGJ00	ACGJ0019601	COVER ASSY,FOLDER(UPPER)	1	G5400 SV	Yes	SILVER
5	MCJJ00	MCJJ0012901	COVER,FOLDER(UPPER)	1	G5400 EUASV	No	SILVER
5	MDAE00	MDAE0012101	DECO,FOLDER(UPPER)	1	G5400 EUASV	No	SILVER
5	MICZ00	MICZ0003801	INSERT	2	M1.4x3.0	No	SILVER
5	MPBQ00	MPBQ0007201	PAD,LCD(SUB)	1	G5400 EUASV	Yes	SILVER
5	MPFF00	MPFF0006101	PLATE,LOGO	1		Yes	
5	MTAE00	MTAE0007001	TAPE,WINDOW(SUB)	1	G5400 SUB WINDOW	Yes	SILVER
5	MTAZ00	MTAZ0012301	TAPE	1	G5400 SV 10x17 Artpaper	No	SILVER
4	ACGK00	ACGK0020801	COVER ASSY,FRONT	1	G5400 EUASV	Yes	SILVER
5	MBHY00	MBHY0003503	BUMPER	2	LG-510,511,512,common use for METALIC SILVER,diameter=2.4	Yes	METALIC SILVER
5	MBJL00	MBJL0006501	BUTTON,SIDE	1	G5400 EUA SV	Yes	SILVER
5	MCJK00	MCJK0014201	COVER,FRONT	1	G5400 EUASV	Yes	SILVER
5	MICZ00	MICZ0003801	INSERT	4	M1.4x3.0	No	SILVER
5	MWAG00	MWAG0002101	WINDOW,IRDA	1	G5400 EUASV	Yes	SILVER
4	AWAB00	AWAB0005001	WINDOW ASSY,LCD	1	G5400 SV MAIN WINDOW	Yes	SILVER
5	MTAD00	MTAD0012401	TAPE,WINDOW	1	G5400 MAIN WINDOW	Yes	SILVER
5	MWAC00	MWAC0024801	WINDOW,LCD	1	G5400 MAIN 1.0t	Yes	SILVER
4	AWAB01	AWAB0004701	WINDOW ASSY,LCD	1	G5400 MAIN WINDOW,	Yes	SILVER
5	BFAA00	BFAA0009101	FILM,INMOLD	1	G5400 SUB WINDOW	No	SILVER
5	MWAF00	MWAF0008401	WINDOW,LCD(SUB)	1	G5400 SUB INMOLD	No	SILVER
4	GMZZ00	GMZZ0001901	SCREW MACHINE	2	1.4 mm,3.5 mm,MSWR3(BK) ,N ,STR , - , t OF HEAD=1.0,DIA OF HEAD=3.1	Yes	
4	MCCH00	MCCH0011901	CAP,SCREW	2	G5400 EUASV, FOLDER	Yes	SILVER
4	MGAD00	MGAD0025301	GASKET,SHIELD FORM	2	5x10x1.5t hard	Yes	SILVER
4	MGAD01	MGAD0025201	GASKET,SHIELD FORM	4	5x5x1.5t hard	Yes	SILVER
4	MHFD00	MHFD0004101	HINGE,FOLDER	1	5400 (5PHI) 5Kg-T	Yes	SILVER
4	MHGD00	MHGD0001501	HOLDER,LCD	1	G5400 LCD HOLDER	Yes	SILVER
4	MPBG00	MPBG0010101	PAD,LCD	1	G5400 MAIN LCD	Yes	SILVER
4	SACY00	SACY0007801	PCB ASSY,FLEXIBLE	1		Yes	
5	ENBY00	ENBY0013401	CONNECTOR,BOARD TO BOARD	1	34 PIN,0.4 mm,STRAIGHT ,Au ,B to B G5400	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	ENBY01	ENBY0013401	CONNECTOR,BOARD TO BOARD	1	34 PIN,0.4 mm,STRAIGHT ,Au ,B to B G5400	Yes	
5	SPCY00	SPCY0012501	PCB,FLEXIBLE	1	POLYI ,.45 mm,DOUBLE ,V1.1	Yes	
4	SPK1	SUSY0006202	SPEAKER	1	ASSY ,8 ohm,92 dB,17 mm,G5400 DUAL SPEAKER	Yes	
4	SVLM00	SVLM0005201	LCD MODULE	1	Main:128*160 (1.5"),Sub:96*16 ,A/Area:28.02*35.028 ,65K CSTN(S6B33B0A)/SUB MONO(S6B0723)	Yes	
4	VIB1	SJMY0002802	VIBRATOR,MOTOR	1	3 V,0.08 A,12*15 ,G5300 VIBRATOR (0.5t PAD)	Yes	
3	ACGM00	ACGM0017701	COVER ASSY,REAR	1	G5400	Yes	SILVER
4	GMZZ00	GMZZ0001901	SCREW MACHINE	1	1.4 mm,3.5 mm,MSWR3(BK) ,N ,STR , - , t OF HEAD=1.0,DIA OF HEAD=3.1	Yes	
4	MCCC00	MCCC0007601	CAP,EARPHONE JACK	1		Yes	SILVER
4	MCIA00	MCIA0006601	CONTACT,ANTENNA	1		Yes	SILVER
4	MCJN00	MCJN0011301	COVER,REAR	1		Yes	SILVER
4	MICZ00	MICZ0003801	INSERT	1	M1.4x3.0	No	SILVER
4	MLEA00	MLEA0008501	LOCKER,BATTERY	1	G5400 EUASV	Yes	SILVER
4	MSDB00	MSDB0001701	SPRING,COIL	1	G7000	Yes	PEARL WHITE
4	SNGF00	SNGF0001601	ANTENNA,GSM,FIXED	1	3.0 , -2.0 dBd,P427C ,	Yes	
3	ADCA00	ADCA0010501	DOME ASSY,METAL	1	G5400	Yes	SILVER
3	GMZZ00	GMZZ0001901	SCREW MACHINE	4	1.4 mm,3.5 mm,MSWR3(BK) ,N ,STR , - , t OF HEAD=1.0,DIA OF HEAD=3.1	Yes	
3	MBJA00	MBJA0008401	BUTTON,DIAL	1	G5400 ENGLISH	Yes	SILVER
3	MCCF00	MCCF0002003	CAP,MOBILE SWITCH	1	LG-510,511,512,common use,METALIC SILVER	Yes	METALIC WHITE
3	MCCH00	MCCH0011801	CAP,SCREW	2	G5400 EUASV, MAIN	Yes	SILVER
3	MGAD01	MGAD0006001	GASKET,SHIELD FORM	1	G7000 10x5x1.5t	Yes	PEARL WHITE
3	MIC201	SUMY0004602	MICROPHONE	1	ASSY , -42 dB,6*1.1 ,G5400 MIC	Yes	
3	MLAK00	MLAK0006801	LABEL,MODEL	1	English, 30.5X21.5	Yes	
3	MTAZ00	MTAZ0011201	TAPE	2	G5400 EUASV, MAIN SCREW CAP	Yes	SILVER

13. EXPLODED VIEW & REPLACEMENT PART LIST

< Main PCB >

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
3	SAFY00	SAFY0060801	PCB ASSY,MAIN	1	G5400 PCB main assy,dual foler,65K Color LCD,7color backlight sub LCD,32poy MIDI	Yes	
4	SAFA00	SAFA0020401	PCB ASSY,MAIN,AUTO	1		Yes	
5	BAT301	ENJE0003001	CONN,JACK/PLUG,EARPHONE	1	2 ,2 PIN,W3000 Back Up Battery Holder	Yes	
5	C101	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C102	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C103	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C104	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C105	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C106	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C107	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C108	ECCH0000163	CAP,CERAMIC,CHIP	1	47 nF,10V,K,X5R,HD,1005,R/TP	Yes	
5	C109	ECCH0000143	CAP,CERAMIC,CHIP	1	1 nF,50V,K,X7R,HD,1005,R/TP	Yes	
5	C111	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C112	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C113	ECCH0000110	CAP,CERAMIC,CHIP	1	10 pF,50V,D,NP0,TC,1005,R/TP	Yes	
5	C114	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C115	ECCH0000276	CAP,CERAMIC,CHIP	1	1 uF,10V,Z,Y5V,HD,1608,R/TP	Yes	
5	C117	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C118	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C119	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C120	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C121	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C124	ECCH0000155	CAP,CERAMIC,CHIP	1	10 nF,16V,K,X7R,HD,1005,R/TP	Yes	
5	C130	ECCH0000155	CAP,CERAMIC,CHIP	1	10 nF,16V,K,X7R,HD,1005,R/TP	Yes	
5	C131	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C132	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C133	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C134	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C201	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C202	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C203	ECCH0000276	CAP,CERAMIC,CHIP	1	1 uF,10V,Z,Y5V,HD,1608,R/TP	Yes	
5	C204	ECCH0000122	CAP,CERAMIC,CHIP	1	47 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C205	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C206	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C207	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C208	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C210	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C212	ECTH0001901	CAP,TANTAL,CHIP	1	10 uF,6.3V ,M ,L _ESR ,1608 ,R/TP	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	C214	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C215	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C216	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C219	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C220	ECTH0001901	CAP,TANTAL,CHIP	1	10 uF,6.3V ,M ,L _ESR ,1608 ,R/TP	Yes	
5	C221	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C222	ECTH0001901	CAP,TANTAL,CHIP	1	10 uF,6.3V ,M ,L _ESR ,1608 ,R/TP	Yes	
5	C224	ECCH0000122	CAP,CERAMIC,CHIP	1	47 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C225	ECCH0000122	CAP,CERAMIC,CHIP	1	47 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C226	ECCH0000122	CAP,CERAMIC,CHIP	1	47 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C227	ECCH0000122	CAP,CERAMIC,CHIP	1	47 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C230	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C231	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C232	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C235	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C236	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C237	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C239	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C240	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C241	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C242	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C243	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C244	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C245	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C301	ECTH0001901	CAP,TANTAL,CHIP	1	10 uF,6.3V ,M ,L _ESR ,1608 ,R/TP	Yes	
5	C302	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C303	ECTH0002001	CAP,TANTAL,CHIP	1	10 uF,10V ,M ,STD ,2012 ,R/TP	Yes	
5	C304	ECCH0000143	CAP,CERAMIC,CHIP	1	1 nF,50V,K,X7R,HD,1005,R/TP	Yes	
5	C305	ECCH0000128	CAP,CERAMIC,CHIP	1	100 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C306	ECCH0000128	CAP,CERAMIC,CHIP	1	100 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C307	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C308	ECCH0000280	CAP,CERAMIC,CHIP	1	0.22 uF,10V ,K ,X7R ,HD ,1608 ,R/TP	Yes	
5	C309	ECCH0005801	CAP,CERAMIC,CHIP	1	2.2 uF,6.3V ,K ,X5R ,TC ,1608 ,R/TP	Yes	
5	C310	ECCH0005801	CAP,CERAMIC,CHIP	1	2.2 uF,6.3V ,K ,X5R ,TC ,1608 ,R/TP	Yes	
5	C311	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C312	ECCH0000280	CAP,CERAMIC,CHIP	1	0.22 uF,10V ,K ,X7R ,HD ,1608 ,R/TP	Yes	
5	C313	ECCH0005801	CAP,CERAMIC,CHIP	1	2.2 uF,6.3V ,K ,X5R ,TC ,1608 ,R/TP	Yes	
5	C314	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C319	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C320	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C402	ECCH0000103	CAP,CERAMIC,CHIP	1	1.5 pF,50V,C,NP0,TC,1005,R/TP	Yes	
5	C407	ECCH0000171	CAP,CERAMIC,CHIP	1	3.3 pF,16V ,J ,NP0 ,TC ,1005 ,R/TP	Yes	
5	C408	ECCH0000110	CAP,CERAMIC,CHIP	1	10 pF,50V,D,NP0,TC,1005,R/TP	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	C409	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C410	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C411	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C412	ECCH0000110	CAP,CERAMIC,CHIP	1	10 pF,50V,D,NP0,TC,1005,R/TP	Yes	
5	C413	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C414	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C415	ECCH0000102	CAP,CERAMIC,CHIP	1	1 pF,50V,C,NP0,TC,1005,R/TP	Yes	
5	C416	ECCH0000115	CAP,CERAMIC,CHIP	1	22 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C417	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C419	ECCH0000102	CAP,CERAMIC,CHIP	1	1 pF,50V,C,NP0,TC,1005,R/TP	Yes	
5	C420	ECCH0000701	CAP,CERAMIC,CHIP	1	1.2 pF,50V ,C ,NP0 ,TC ,1005 ,R/TP	Yes	
5	C422	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C423	ECCH0000701	CAP,CERAMIC,CHIP	1	1.2 pF,50V ,C ,NP0 ,TC ,1005 ,R/TP	Yes	
5	C424	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C425	ECCH0000103	CAP,CERAMIC,CHIP	1	1.5 pF,50V,C,NP0,TC,1005,R/TP	Yes	
5	C426	ECCH0000901	CAP,CERAMIC,CHIP	1	2.2 pF,50V ,C ,NP0 ,TC ,1005 ,R/TP	Yes	
5	C428	ECCH0000176	CAP,CERAMIC,CHIP	1	2 pF,50V ,C ,NP0 ,TC ,1005 ,R/TP	Yes	
5	C429	ECCH0000186	CAP,CERAMIC,CHIP	1	33 pF,50V ,J ,NP0 ,TC ,1005 ,R/TP	Yes	
5	C430	ECCH0000110	CAP,CERAMIC,CHIP	1	10 pF,50V,D,NP0,TC,1005,R/TP	Yes	
5	C431	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C433	ECTZ0003901	CAP,TANTAL,CHIP,MAKER	1	10 uF,16V ,M ,STD ,ETC ,R/TP	Yes	
5	C434	ECCH0000115	CAP,CERAMIC,CHIP	1	22 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C435	ECCH0000122	CAP,CERAMIC,CHIP	1	47 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C437	ECCH0000110	CAP,CERAMIC,CHIP	1	10 pF,50V,D,NP0,TC,1005,R/TP	Yes	
5	C438	ECCH0000179	CAP,CERAMIC,CHIP	1	22 nF,16V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C439	ECCH0000128	CAP,CERAMIC,CHIP	1	100 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C440	ECCH0000143	CAP,CERAMIC,CHIP	1	1 nF,50V,K,X7R,HD,1005,R/TP	Yes	
5	C441	ECCH0000128	CAP,CERAMIC,CHIP	1	100 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C442	ECCH0000143	CAP,CERAMIC,CHIP	1	1 nF,50V,K,X7R,HD,1005,R/TP	Yes	
5	C443	ECCH0000110	CAP,CERAMIC,CHIP	1	10 pF,50V,D,NP0,TC,1005,R/TP	Yes	
5	C444	ECCH0000379	CAP,CERAMIC,CHIP	1	2.2 uF,6.3V ,K ,X5R ,HD ,2012 ,R/TP	Yes	
5	C445	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C446	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C447	ECCH0000143	CAP,CERAMIC,CHIP	1	1 nF,50V,K,X7R,HD,1005,R/TP	Yes	
5	C448	ECCH0000115	CAP,CERAMIC,CHIP	1	22 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C449	ECCH0003401	CAP,CERAMIC,CHIP	1	10 uF,6.3V ,Z ,Y5V ,HD ,2012 ,R/TP	Yes	
5	C450	ECCH0000379	CAP,CERAMIC,CHIP	1	2.2 uF,6.3V ,K ,X5R ,HD ,2012 ,R/TP	Yes	
5	C451	ECCH0000139	CAP,CERAMIC,CHIP	1	470 pF,50V,K,X7R,HD,1005,R/TP	Yes	
5	C501	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	C502	ECCH0000110	CAP,CERAMIC,CHIP	1	10 pF,50V,D,NP0,TC,1005,R/TP	Yes	
5	C506	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C507	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C509	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	C510	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C511	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C512	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C513	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C514	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C515	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C516	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C517	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C518	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C519	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C520	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C521	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C522	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C523	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C524	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C525	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C526	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C527	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C528	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C529	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C530	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C531	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C532	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C533	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C534	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C535	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C536	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C537	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C538	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C539	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C540	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C541	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C542	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C543	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C544	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C545	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C546	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C547	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C548	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C549	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C550	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C551	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C552	ECCH0000117	CAP,CERAMIC,CHIP	1	27 pF,50V,J,NP0,TC,1005,R/TP	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	C601	ECCH0001811	CAP,CERAMIC,CHIP	1	0.22 uF,50V ,Z ,Y5V ,HD ,1005 ,R/TP	Yes	
5	C602	ECCH0000143	CAP,CERAMIC,CHIP	1	1 nF,50V,K,X7R,HD,1005,R/TP	Yes	
5	C605	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C606	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C607	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C608	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C609	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C610	ECCH0000120	CAP,CERAMIC,CHIP	1	39 pF,50V,J,NP0,TC,1005,R/TP	Yes	
5	C611	ECCH0000182	CAP,CERAMIC,CHIP	1	0.1 uF,10V ,K ,X5R ,HD ,1005 ,R/TP	Yes	
5	CN501	ENBY0013402	CONNECTOR,BOARD TO BOARD	1	34 PIN,0.4 mm,STRAIGHT ,Au ,B to B G5400	Yes	
5	CN601	MTCB0000702	TERMINAL,PIN	1	7.4*2.8 4.3T Mold 2.2T 3P	Yes	BLACK
5	CN602	ENEY0003101	CONN,RECEPTACLE	1	18 PIN,0 ,	Yes	
5	D101	EDSY0005701	DIODE,SWITCHING	1	EMT3 ,80 V,4 A,R/TP ,	Yes	
5	D302	EDSY0012101	DIODE,SWITCHING	1	US-FLAT ,30 V,1 A,R/TP ,2.5*1.25*0.6(t)	Yes	
5	FL401	SFAY0001901	FILTER,SEPERATOR	1	880/960 ,1710/1880 ,1.3 dB,1.5 dB,30 dB,25 dB,ETC ,5.4*4.0*1.8	Yes	
5	FL402	SFSY0012202	FILTER,SAW	1	942.5 MHz,2.0*2.5*1.0 ,SMD ,	Yes	
5	FL403	SFSY0012302	FILTER,SAW	1	1842.5 MHz,2.0*2.5*1.0 ,SMD ,	Yes	
5	J201	ENJE0002301	CONN,JACK/PLUG,EARPHONE	1	3,5 PIN,G7000 EAR JACK 3 pole, 5 pin KSD	Yes	
5	J601	ENSY0007602	CONN,SOCKET	1	6 PIN,ETC , , mm,Height 2.7mm	Yes	
5	L401	ELCH0001420	INDUCTOR,CHIP	1	3.9 nH,S ,1005 ,R/TP ,CDMA	Yes	
5	L402	ELCH0005006	INDUCTOR,CHIP	1	33 nH,J ,1005 ,R/TP ,	Yes	
5	L403	ELCH0005006	INDUCTOR,CHIP	1	33 nH,J ,1005 ,R/TP ,	Yes	
5	L404	ELCH0002715	INDUCTOR,CHIP	1	27 nH,G ,1608 ,R/TP ,coil inductor	Yes	
5	L405	ELCH0002714	INDUCTOR,CHIP	1	7.5 nH,G ,1608 ,R/TP ,coil inductor	Yes	
5	L406	ELCH0005013	INDUCTOR,CHIP	1	4.7 nH,S ,1005 ,R/TP ,	Yes	
5	L407	ELCH0005013	INDUCTOR,CHIP	1	4.7 nH,S ,1005 ,R/TP ,	Yes	
5	L408	ELCH0005003	INDUCTOR,CHIP	1	12 nH,J ,1005 ,R/TP ,	Yes	
5	L409	ELCH0001420	INDUCTOR,CHIP	1	3.9 nH,S ,1005 ,R/TP ,CDMA	Yes	
5	LD503	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD504	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD505	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD506	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD507	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD508	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD509	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD510	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD511	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD512	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD513	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	
5	LD514	EDLH0004502	DIODE,LED,CHIP	1	BLUE ,1608 ,R/TP ,0.35T	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	Q301	EQFP0004201	TR,FET,P-CHANNEL	1	2.9*1.9*0.8(t) ,0.7 W,20 V,-6.0 A,R/TP ,NDC652P upgrade(substitution) item	Yes	
5	Q501	EQBN0007101	TR,BJT,NPN	1	EMT3 ,0.15 W,R/TP ,LOW FREQUENCY	Yes	
5	Q502	EQBN0004801	TR,BJT,NPN	1	SMT6 ,0.2 W,R/TP ,	Yes	
5	R101	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R103	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R104	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R105	ERHY0000282	RES,CHIP	1	120K ohm,1/16W,J,1005,R/TP	Yes	
5	R106	ERHY0000282	RES,CHIP	1	120K ohm,1/16W,J,1005,R/TP	Yes	
5	R107	ERHY0000512	RES,CHIP	1	10M ohm,1/16W,J,1608,R/TP	Yes	
5	R108	ERHY0000278	RES,CHIP	1	82K ohm,1/16W,J,1005,R/TP	Yes	
5	R110	ERHY0000106	RES,CHIP	1	100 ohm,1/16W,F,1005,R/TP	Yes	
5	R111	ERHY0000163	RES,CHIP	1	220K ohm,1/16W,F,1005,R/TP	Yes	
5	R112	ERHY0000163	RES,CHIP	1	220K ohm,1/16W,F,1005,R/TP	Yes	
5	R113	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R140	ERHY0000278	RES,CHIP	1	82K ohm,1/16W,J,1005,R/TP	Yes	
5	R145	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R146	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R147	ERHY0000247	RES,CHIP	1	2.2K ohm,1/16W,J,1005,R/TP	Yes	
5	R201	ERHY0000265	RES,CHIP	1	20K ohm,1/16W,J,1005,R/TP	Yes	
5	R202	ERHY0000265	RES,CHIP	1	20K ohm,1/16W,J,1005,R/TP	Yes	
5	R203	ERHY0000294	RES,CHIP	1	560K ohm,1/16W,J,1005,R/TP	Yes	
5	R204	ERHY0000294	RES,CHIP	1	560K ohm,1/16W,J,1005,R/TP	Yes	
5	R205	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R207	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R208	ERHY0000243	RES,CHIP	1	1.2K ohm,1/16W,J,1005,R/TP	Yes	
5	R209	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R210	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R211	ERHY0000243	RES,CHIP	1	1.2K ohm,1/16W,J,1005,R/TP	Yes	
5	R212	ERHY0000247	RES,CHIP	1	2.2K ohm,1/16W,J,1005,R/TP	Yes	
5	R213	ERHY0000296	RES,CHIP	1	1M ohm,1/16W,J,1005,R/TP	Yes	
5	R214	ERHY0000250	RES,CHIP	1	3.3K ohm,1/16W,J,1005,R/TP	Yes	
5	R215	ERHY0006602	RES,CHIP	1	620 Kohm,1/16W ,J ,1005 ,R/TP	Yes	
5	R216	ERHY0000202	RES,CHIP	1	4.7 ohm,1/16W,J,1005,R/TP	Yes	
5	R217	ERHY0000202	RES,CHIP	1	4.7 ohm,1/16W,J,1005,R/TP	Yes	
5	R218	ERHY0000296	RES,CHIP	1	1M ohm,1/16W,J,1005,R/TP	Yes	
5	R219	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R220	ERHY0000202	RES,CHIP	1	4.7 ohm,1/16W,J,1005,R/TP	Yes	
5	R221	ERHY0000202	RES,CHIP	1	4.7 ohm,1/16W,J,1005,R/TP	Yes	
5	R232	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R247	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R257	ERHY0000296	RES,CHIP	1	1M ohm,1/16W,J,1005,R/TP	Yes	
5	R258	ERHY0006602	RES,CHIP	1	620 Kohm,1/16W ,J ,1005 ,R/TP	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	R259	ERHY0000261	RES,CHIP	1	10K ohm,1/16W,J,1005,R/TP	Yes	
5	R260	ERHY0000249	RES,CHIP	1	2.7K ohm,1/16W,J,1005,R/TP	Yes	
5	R262	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R263	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R265	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R301	ERHY0001103	RES,CHIP	1	0.33 ohm,1/4W ,F ,2012 ,R/TP	Yes	
5	R304	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R306	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R315	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R316	ERHY0000261	RES,CHIP	1	10K ohm,1/16W,J,1005,R/TP	Yes	
5	R318	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R319	ERHY0000261	RES,CHIP	1	10K ohm,1/16W,J,1005,R/TP	Yes	
5	R320	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R323	ERHY0000261	RES,CHIP	1	10K ohm,1/16W,J,1005,R/TP	Yes	
5	R324	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R401	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R402	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R403	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R404	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R405	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R406	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R407	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R408	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R409	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R410	ERHY0004301	RES,CHIP	1	130 ohm,1/16W ,J ,1005 ,R/TP	Yes	
5	R411	ERHY0004301	RES,CHIP	1	130 ohm,1/16W ,J ,1005 ,R/TP	Yes	
5	R412	ERHY0000296	RES,CHIP	1	1M ohm,1/16W,J,1005,R/TP	Yes	
5	R413	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R414	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R415	ERHY0000263	RES,CHIP	1	15K ohm,1/16W,J,1005,R/TP	Yes	
5	R416	ERHY0006603	RES,CHIP	1	36 ohm,1/16W ,J ,1005 ,R/TP	Yes	
5	R417	ERHY0000223	RES,CHIP	1	150 ohm,1/16W,J,1005,R/TP	Yes	
5	R418	ERHY0000223	RES,CHIP	1	150 ohm,1/16W,J,1005,R/TP	Yes	
5	R419	ERHY0000263	RES,CHIP	1	15K ohm,1/16W,J,1005,R/TP	Yes	
5	R420	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R421	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R422	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R423	ERHY0000289	RES,CHIP	1	270K ohm,1/16W,J,1005,R/TP	Yes	
5	R424	SETY0001201	THERMISTOR	1	NTC ,22 Kohm,SMD ,1.0*0.5 / NSM4 SERIES	Yes	
5	R425	ERHY0000237	RES,CHIP	1	680 ohm,1/16W,J,1005,R/TP	Yes	
5	R426	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R427	ERHY0000254	RES,CHIP	1	4.7K ohm,1/16W,J,1005,R/TP	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	R428	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R501	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R502	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R503	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R504	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R505	ERHY0000205	RES,CHIP	1	15 ohm,1/16W,J,1005,R/TP	Yes	
5	R506	ERHY0000274	RES,CHIP	1	51K ohm,1/16W,J,1005,R/TP	Yes	
5	R507	ERHY0000244	RES,CHIP	1	1.5K ohm,1/16W,J,1005,R/TP	Yes	
5	R508	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R512	ERHY0000244	RES,CHIP	1	1.5K ohm,1/16W,J,1005,R/TP	Yes	
5	R513	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R519	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R520	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R521	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R522	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R523	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R524	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R525	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R526	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R527	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R528	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R529	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R530	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R531	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R532	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R533	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R534	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R535	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R536	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R537	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R538	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R539	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R540	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R541	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R543	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R544	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R545	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R546	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R547	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R548	ERHY0000241	RES,CHIP	1	1K ohm,1/16W,J,1005,R/TP	Yes	
5	R551	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R552	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R553	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	R554	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R555	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R556	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R557	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R558	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R559	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R560	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R561	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R562	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R563	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R564	ERHY0000207	RES,CHIP	1	20 ohm,1/16W,J,1005,R/TP	Yes	
5	R601	ERHY0000265	RES,CHIP	1	20K ohm,1/16W,J,1005,R/TP	Yes	
5	R602	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R603	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R604	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R605	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R606	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R607	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R608	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	R612	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R613	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R614	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R618	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R619	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R620	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R621	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R622	ERHY0000202	RES,CHIP	1	4.7 ohm,1/16W,J,1005,R/TP	Yes	
5	R623	ERHY0000202	RES,CHIP	1	4.7 ohm,1/16W,J,1005,R/TP	Yes	
5	R624	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R625	ERHY0000213	RES,CHIP	1	47 ohm,1/16W,J,1005,R/TP	Yes	
5	R626	ERHY0000220	RES,CHIP	1	100 ohm,1/16W,J,1005,R/TP	Yes	
5	R629	ERHY0000211	RES,CHIP	1	33 ohm,1/16W,J,1005,R/TP	Yes	
5	R630	ERHY0000201	RES,CHIP	1	0 ohm,1/16W,J,1005,R/TP	Yes	
5	R631	ERHY0000280	RES,CHIP	1	100K ohm,1/16W,J,1005,R/TP	Yes	
5	SPFY00	SPFY0039101	PCB,MAIN	1	FR-4 ,9 mm,MULTI-8 ,V1.3	Yes	
5	SW401	ENWY0000101	CONN,RF SWITCH	1	ANGLE ,SMD ,0.5 dB,	Yes	
5	U101	EUSY0157001	IC	1	LFBGA ,160 PIN,R/TP ,DIGITAL BASEBAND PROCESSOR	No	
5	U102	EUSY0100701	IC	1	64 BALL LFBGA / MINI-BGA ,64 PIN,R/TP ,DUAL-MODE VOICEBAND BASEBAND CODEC / AD20MSP430	No	
5	U103	EUSY0147002	IC	1	US8 ,8 PIN,R/TP ,DUAL 2-INPUT OR GATE	Yes	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
5	U201	EUSY0148902	IC	1	QFN ,48 PIN,R/TP ,16 TONES 32 POLY / GM by PCM method	Yes	
5	U203	EUSY0119001	IC	1	10 uMAX ,10 PIN,R/TP ,DUAL SPDT ANALOG SWITCHES	Yes	
5	U204	EUSY0119001	IC	1	10 uMAX ,10 PIN,R/TP ,DUAL SPDT ANALOG SWITCHES	Yes	
5	U205	EUSY0077301	IC	1	SC70-6/SOT23-6 ,6 PIN,R/TP ,	Yes	
5	U206	EUSY0077701	IC	1	SC70-5 ,5 PIN,R/TP ,	Yes	
5	U207	EUSY0149701	IC	1	LLP ,10 PIN,R/TP ,1 Watt Audio Power Amplifier / Leadless Type	Yes	
5	U208	EUSY0077301	IC	1	SC70-6/SOT23-6 ,6 PIN,R/TP ,	Yes	
5	U209	EUSY0077701	IC	1	SC70-5 ,5 PIN,R/TP ,	Yes	
5	U301	EUSY0145401	IC	1	P-FBGA73 ,73 PIN,R/TP ,128M FLASH 32M PSRAM / BOTTOM BOOT / CE 2 PCS	No	
5	U302	EUSY0145101	IC	1	LFCSF-32 (5mmX5mm) ,32 PIN,R/TP ,2.8V LDO for Memory / GSM POWER MANAGEMENT SYSTEM	Yes	
5	U401	EUSY0144804	IC	1	5*5 MLP32 ,32 PIN,R/TP ,	Yes	
5	U402	EUSY0144801	IC	1	5*5 ,32 PIN,R/TP ,	Yes	
5	U403	EUSY0144802	IC	1	5*5 MLP28 ,28 PIN,R/TP ,	Yes	
5	U404	SMPY0004001	PAM	1	35 dBm,55 % ,2 A,-50 dBc,25 dB,10.0 * 7.0 * 1.4 ,SMD ,	Yes	
5	U405	EUSY0076701	IC	1	SOT-23-6 ,6 PIN,R/TP ,	Yes	
5	U406	EUSY0077201	IC	1	SOT(DCK) ,5 PIN,R/TP ,	Yes	
5	U501	EUSY0129501	IC	1	SC-74A FIT ,3 PIN,R/TP ,HALL EFFECT SWITCH	Yes	
5	U601	EUSY0122301	IC	1	SURFACE MOUNT ,7 PIN,R/TP ,IRDA DATA 1.3 LOW POWER TRANSCEIVER / 115.2kb/s	Yes	
5	VA201	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	VA202	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	VA203	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	VA204	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	VA501	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	VA502	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	VA503	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	VA504	SEVY0000702	VARISTOR	1	14 V,10% ,SMD ,	Yes	
5	X101	EXXY0004601	X-TAL	1	0.32768 MHz,20 PPM,12.5 pF,65000 ohm,SMD ,6.9*1.4*1.3 ,	Yes	
5	X401	EXSK0003501	VCTCXO	1	13 MHz,2.5 PPM,10 pF,SMD ,5.0*3.2*1.5	Yes	
3	SAKY00	SAKY0002001	PCB ASSY,SIDEKEY	1	G5400	Yes	
3	SBCL00	SBCL0001302	BATTERY,CELL,LITHIUM	1	2 V,1 mAh,COIN ,W3000 Back Up Battery	Yes	
2	MBAD00	MBAD0002901	BAG,VINYL(PE)	1	LOWDENSITY POLYETHYLENE(t=0.05mm)	Yes	
2	MBEE00	MBEE0034601	BOX,MASTER	0	480*400*315H(G5400#20sets)	No	

13. EXPLODED VIEW & REPLACEMENT PART LIST

Level	Location No.	Part Number	Description	Qty	Specification	Service	Remark
2	MBEF00	MBEF0034601	BOX,UNIT	1	G5400(Standard)	Yes	
2	MLAC00	MLAC0000801	LABEL,BARCODE	0	84 x 203.5	No	DARK GRAY
2	MLAQ00	MLAQ0001601	LABEL,UNIT BOX	1		Yes	
2	MLAZ00	MLAZ0033401	LABEL	0	210x297(ORANGE#FOR PALLET)	No	
2	MMBB00	MMBB0084001	MANUAL,OPERATION	1	5400 User manual for Europe_English Only	Yes	GRAY
2	MPAD00	MPAD0002601	PACKING,SHELL	1	225*253*75H(G5200)	Yes	GRAY
2	MPCY00	MPCY0004401	PALLET	0	1295*1025(LG-G510)	No	DARK GRAY
2	SBPL00	SBPL0065835	BATTERY PACK,LI-ION	1	3.7 V,720 mAh,1 CELL,PRISMATIC ,G5400 BATTERY (SV)	Yes	
2	SGEY00	SGEY0002901	EAR PHONE/EAR MIKE SET	1	G7000,G5200 Common use, 3P EAR MIC	Yes	
2	SSAD00	SSAD0007801	ADAPTOR,AC-DC	1	100-240V ,60 Hz,5.2 V,850 mA,CE ,85VAC~264VAC / 50HZ~60HZ	Yes	
2	WSYY00	WSYY0021101	SOFTWARE	1	G5400 EUA V.PT T0	Yes	